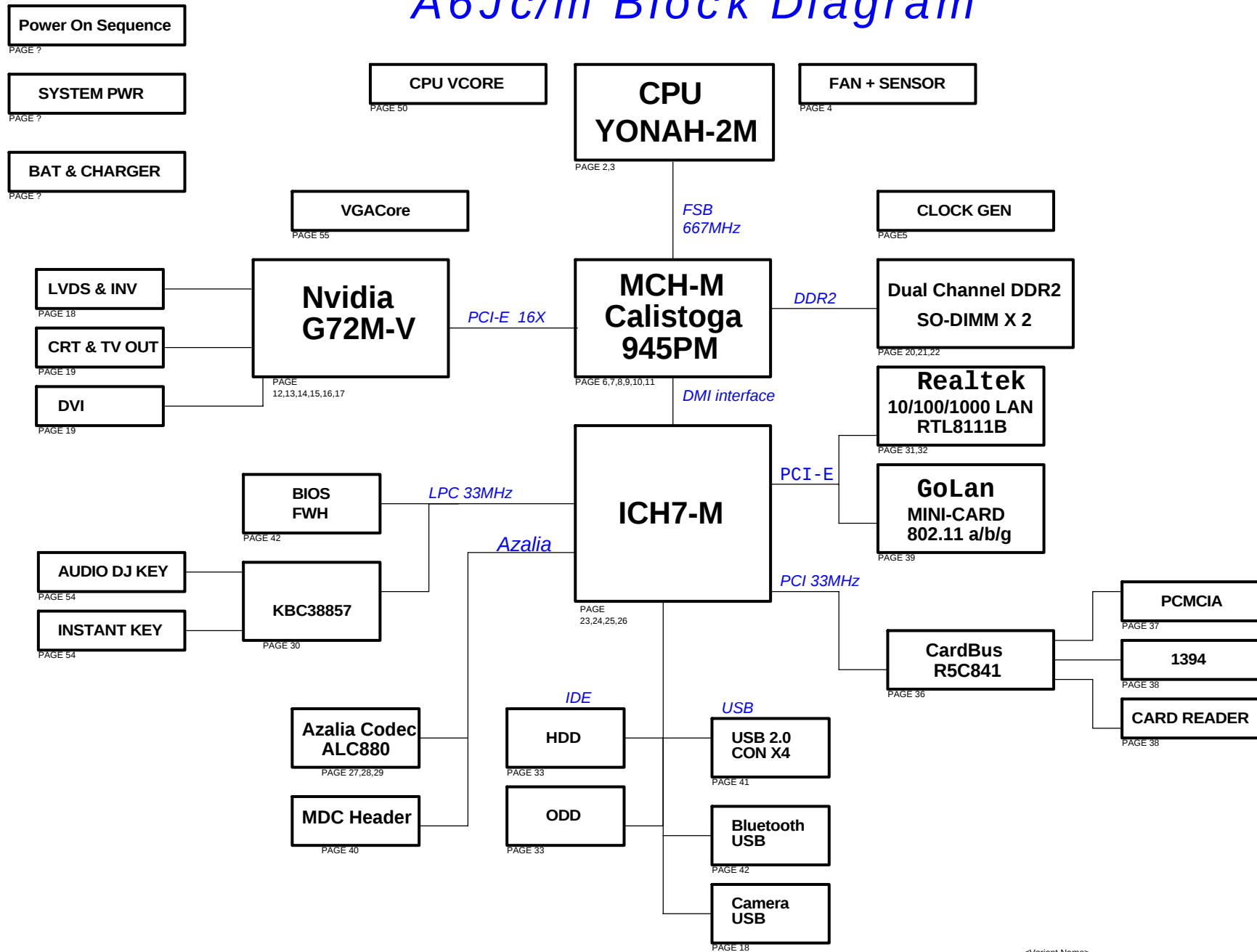
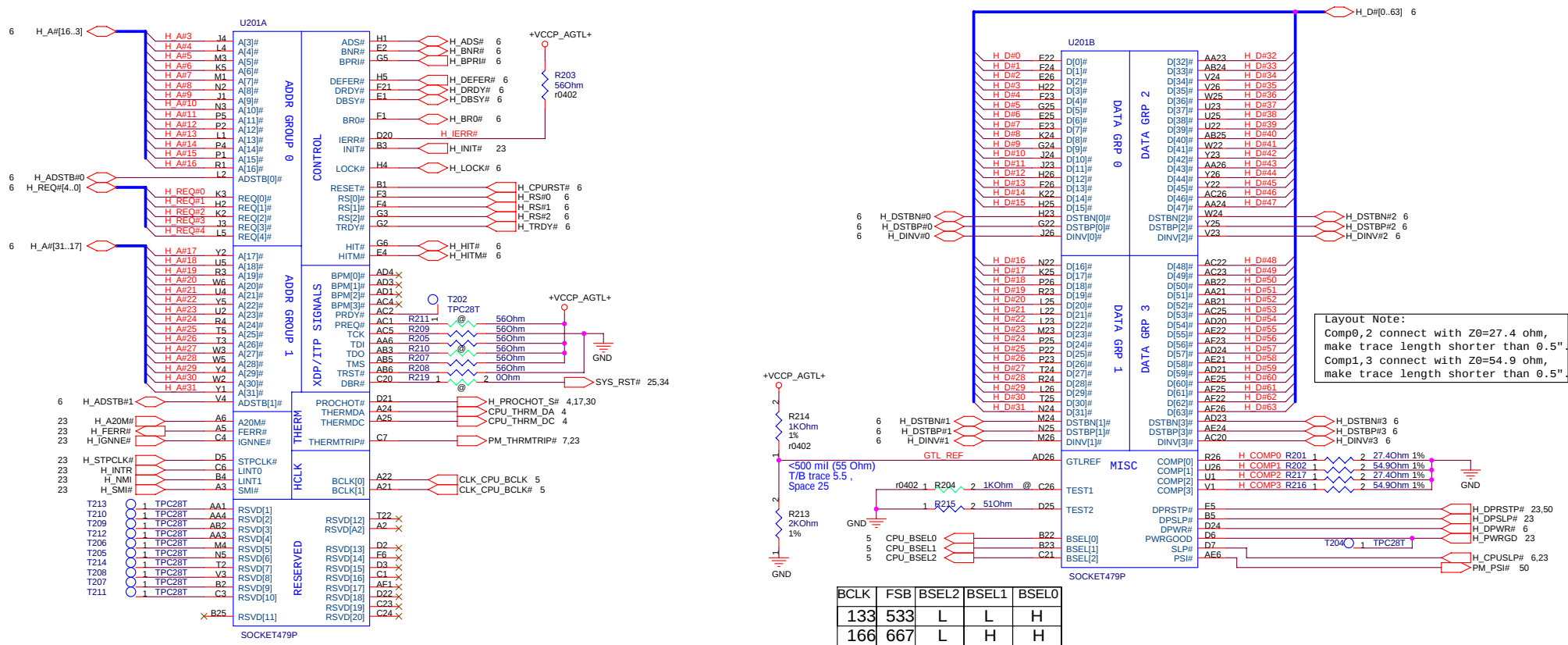


A6Jc/m Block Diagram

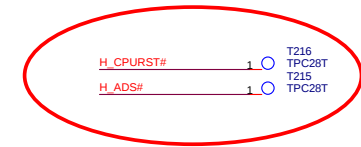
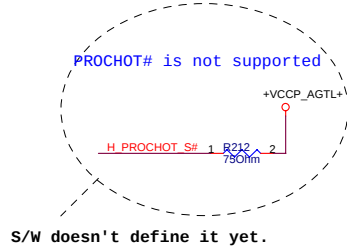


<Variant Name>

ASUS		Title : BLOCK DIAGRAM	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	1	of 63



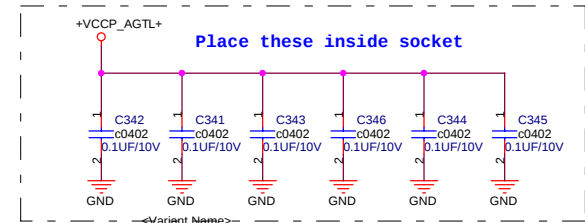
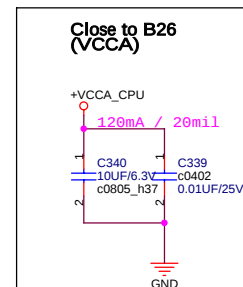
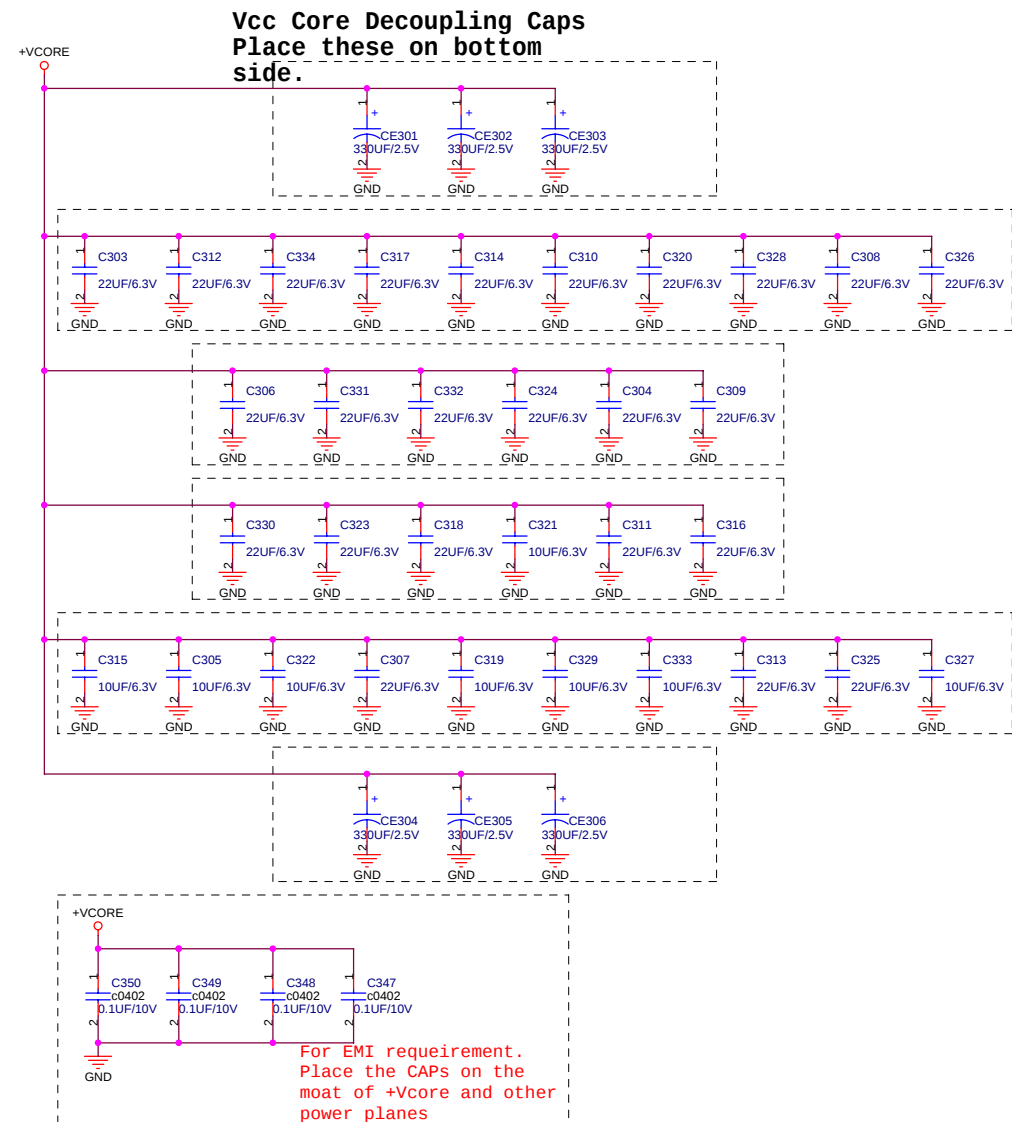
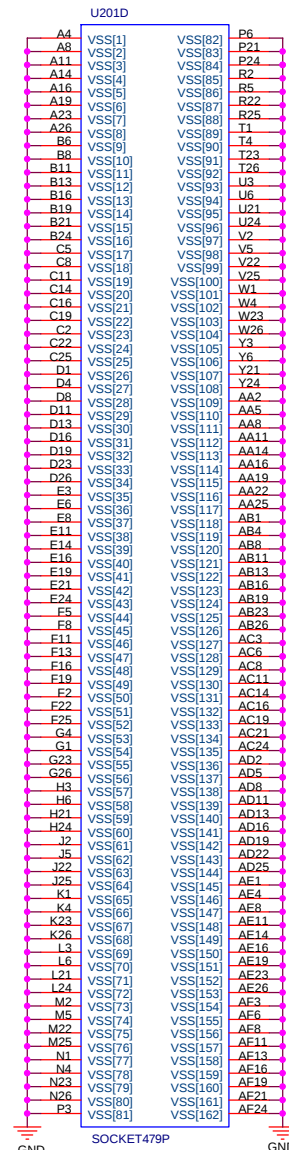
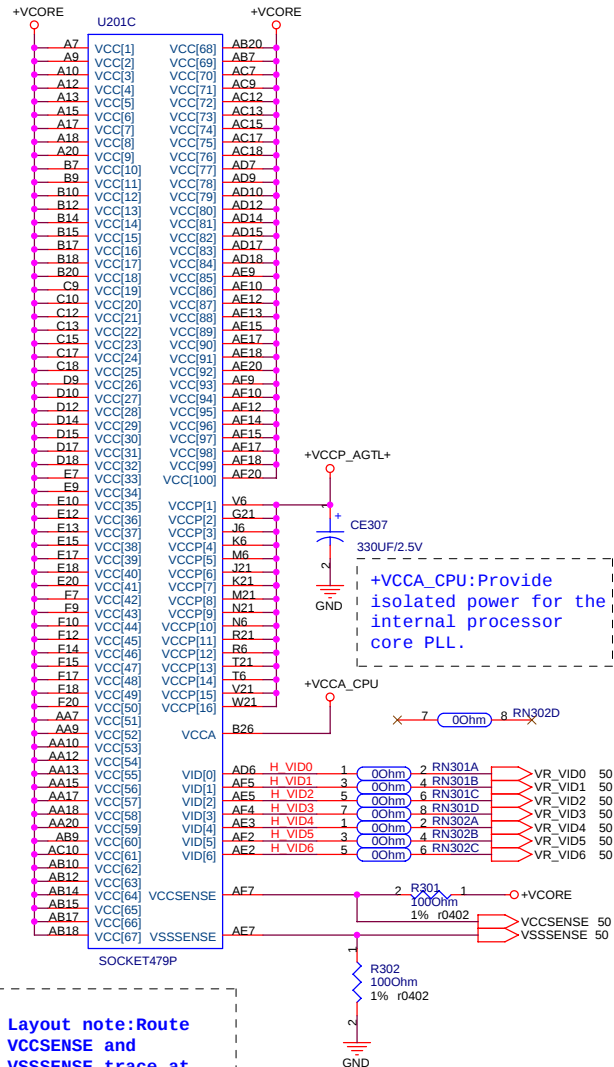
BCLK	FSB	BSEL2	BSEL1	BSEL0
133	533	L	L	H
166	667	L	H	H



<Variant Name>

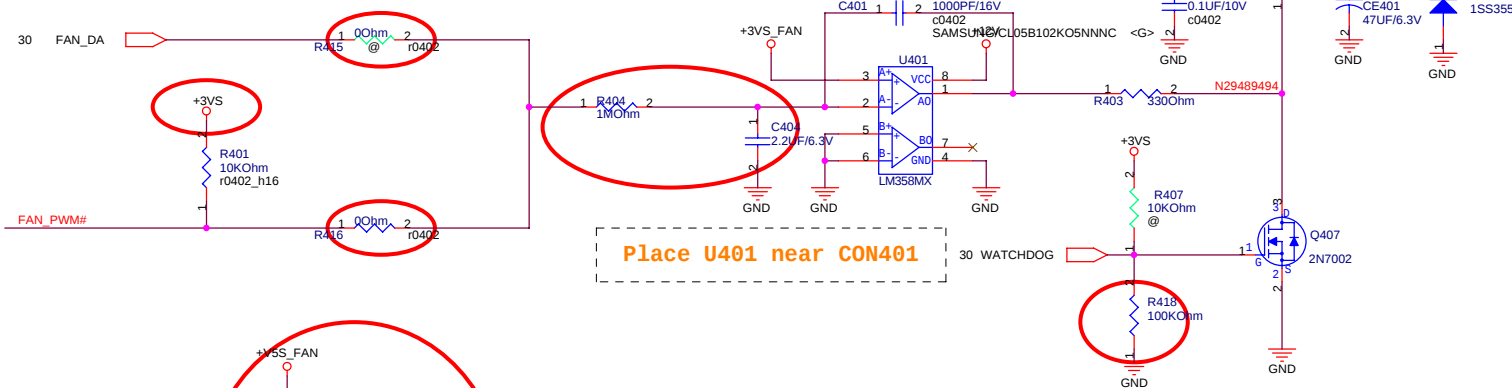
YUNAH	FSB667	LFM	TYP	HFM
VCC	1.14V	1.2V	1.356V	
C4		C3	C0	
ICC	0.9A	7.59A	27A	

YUNAH	FSB667	Min	Typ	Max
VCCP	0.997V	1.05V	1.102V	
Min		Typ	Max	
ICCP				2.5A

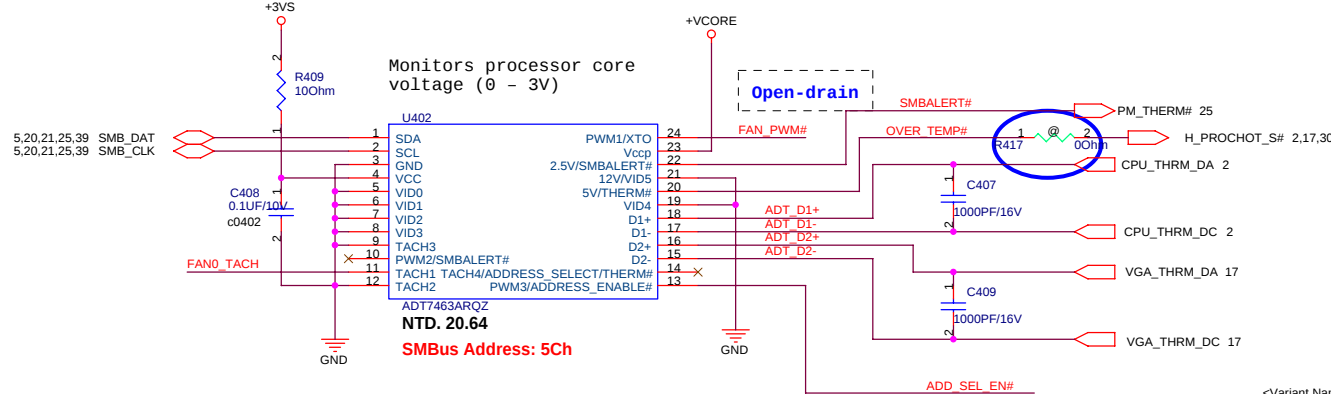
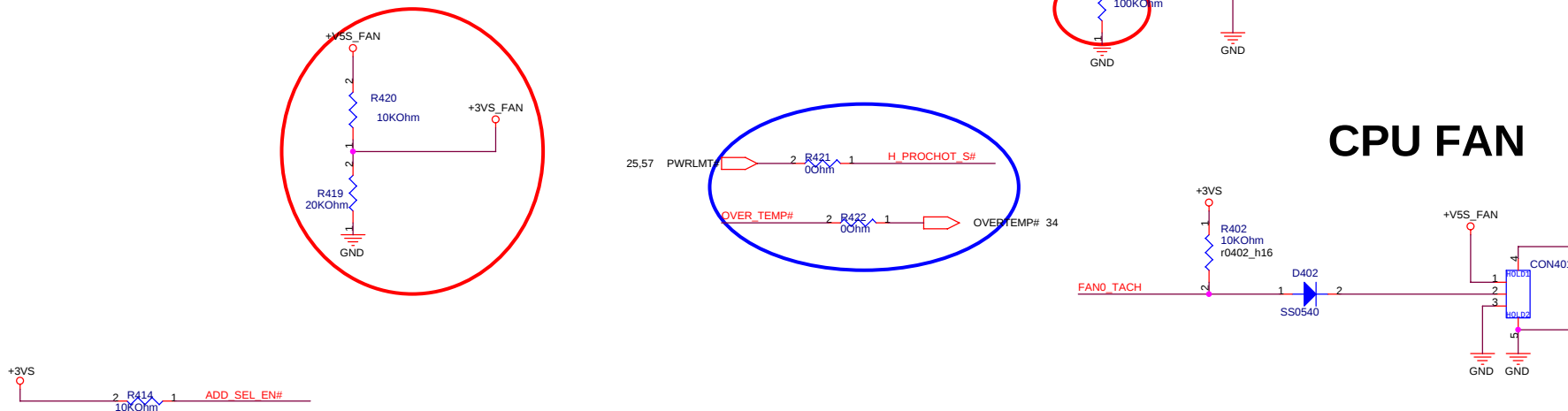


Fan Speed Control

Using a OP AMP and fine-tuning the level, we can improve the fan speed accuracy.



CPU FAN

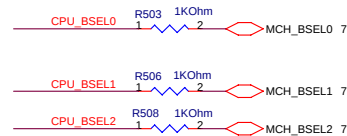


Pin 10 & Pin 24 set inverting PWM Mode
Set INV=1 to invert PWM output

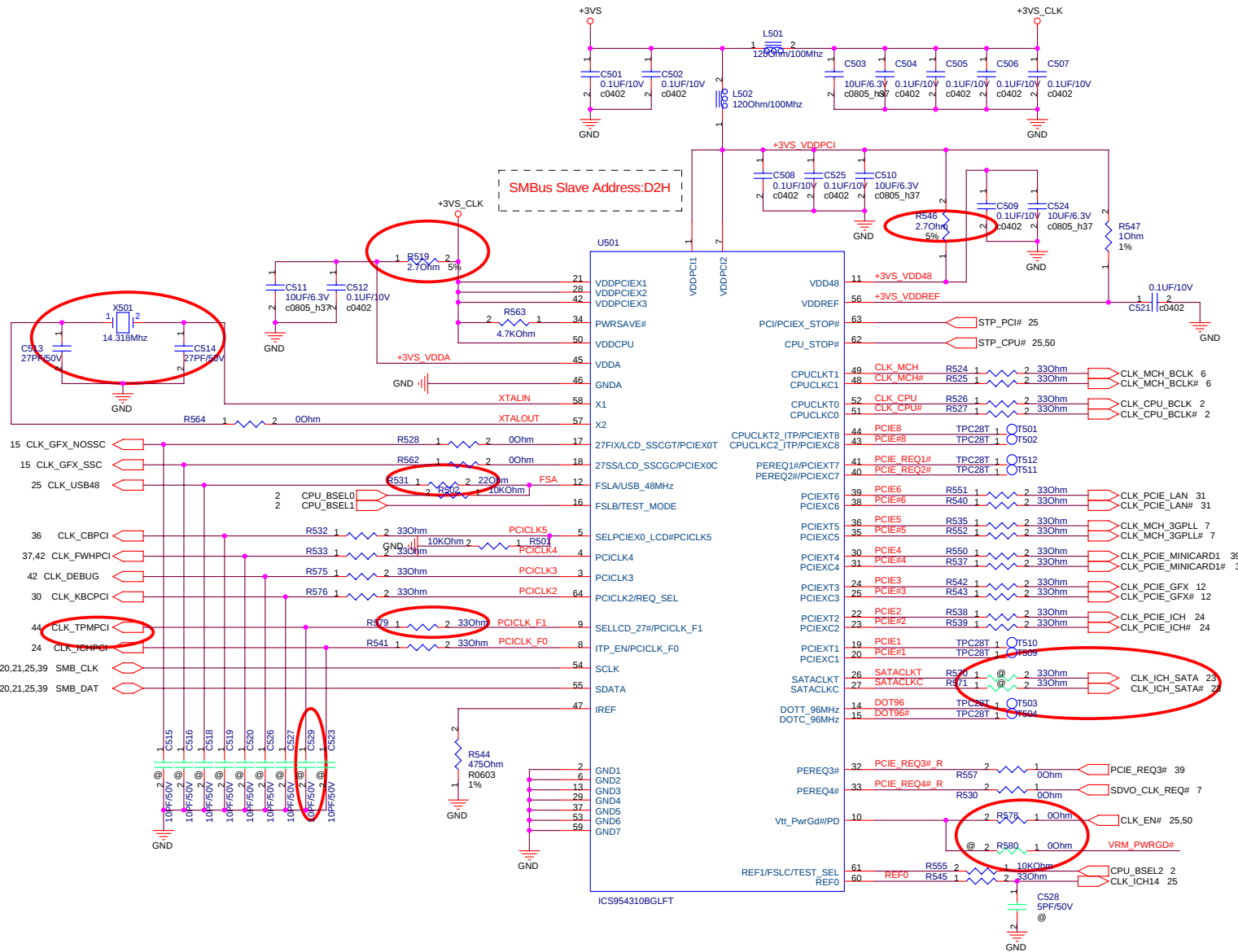
Route H_THERMDA and H_THERMDC on the same layer

-----OTHER SIGNALS
12 mils
=====GND
10 mils
=====H_THERMDA(10 mils)
10 mils
=====H_THERMDC(10 mils)
10 mils
=====GND
12 mils
-----OTHER SIGNALS

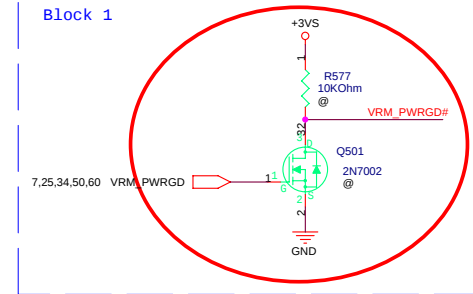
Avoid BPSB,Power



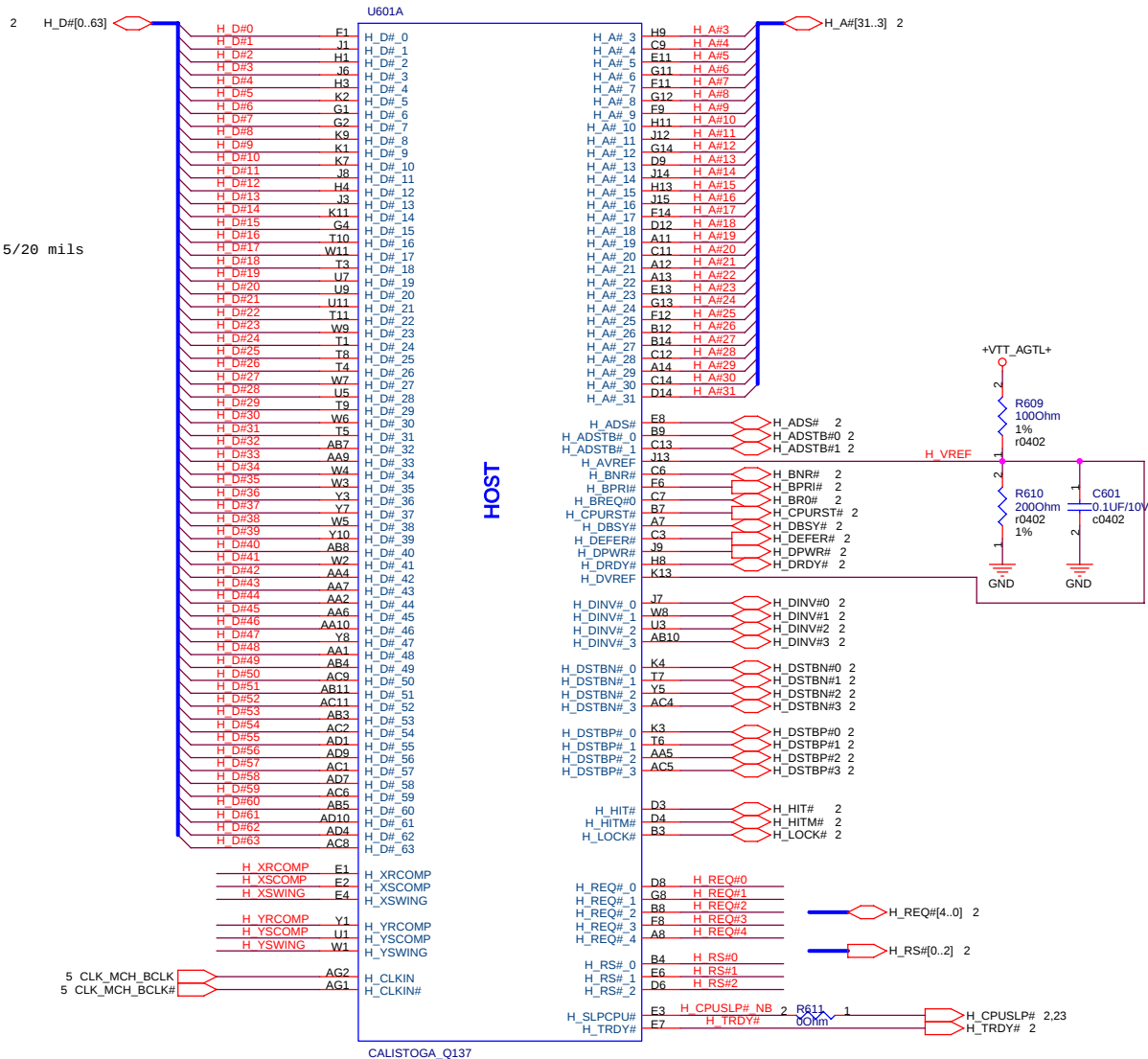
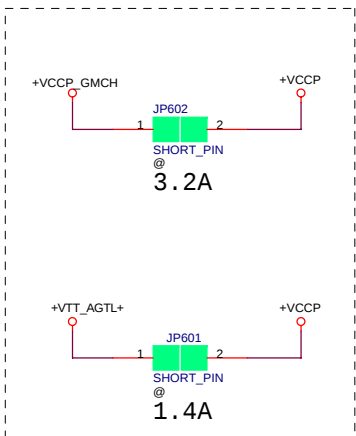
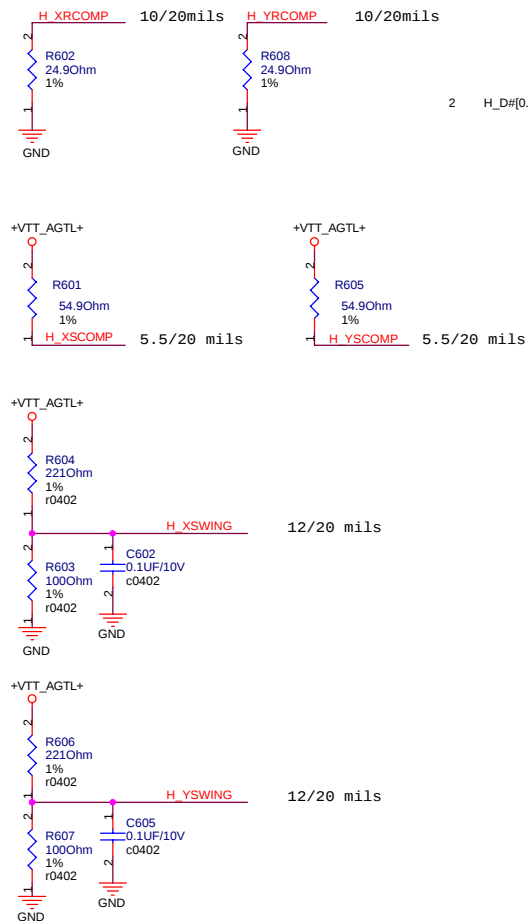
Bclk	FSB	FSLC	FSLB	FSLA
133	533	L	L	H
166	667	L	H	H



Place termination closed to source IC

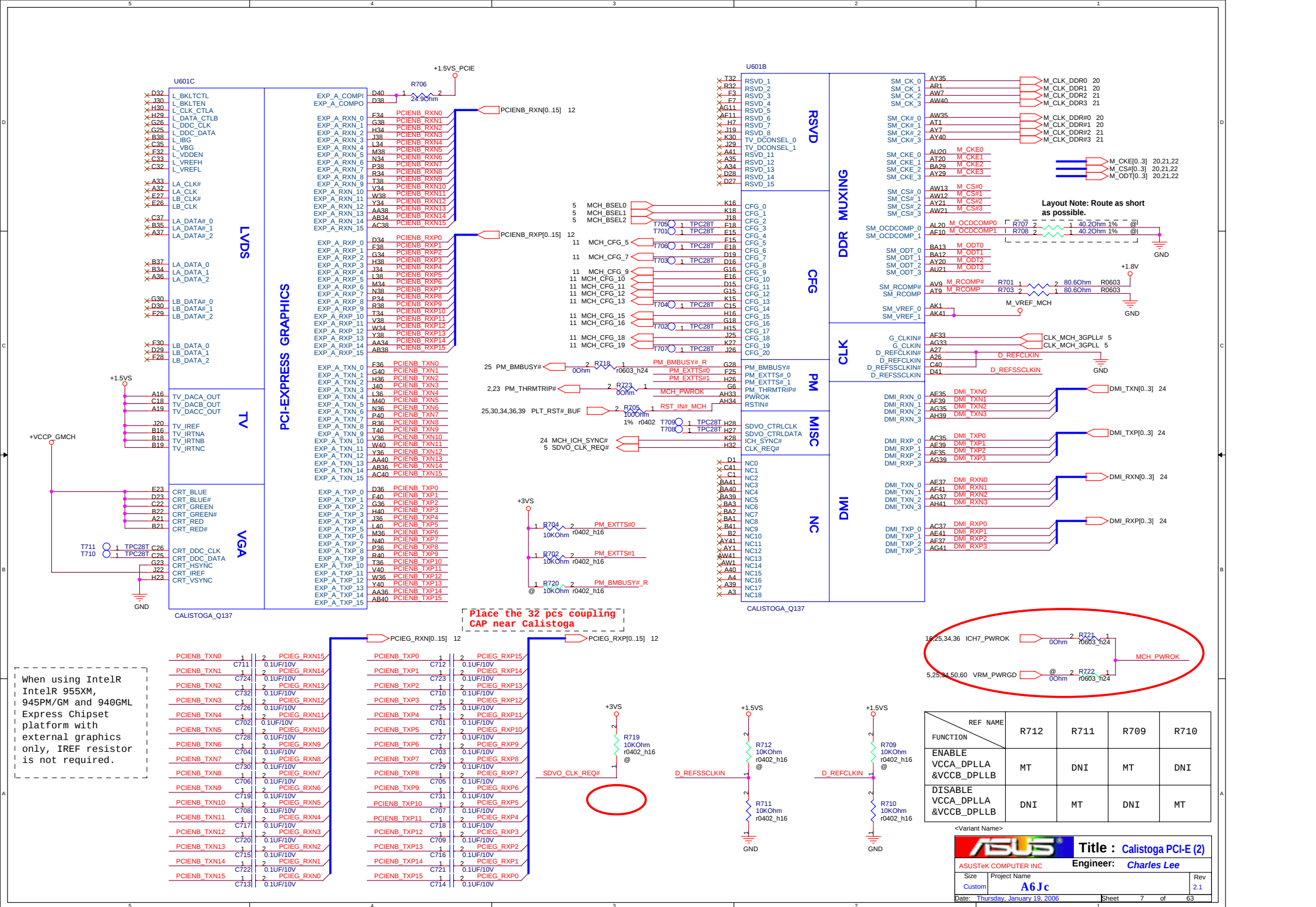


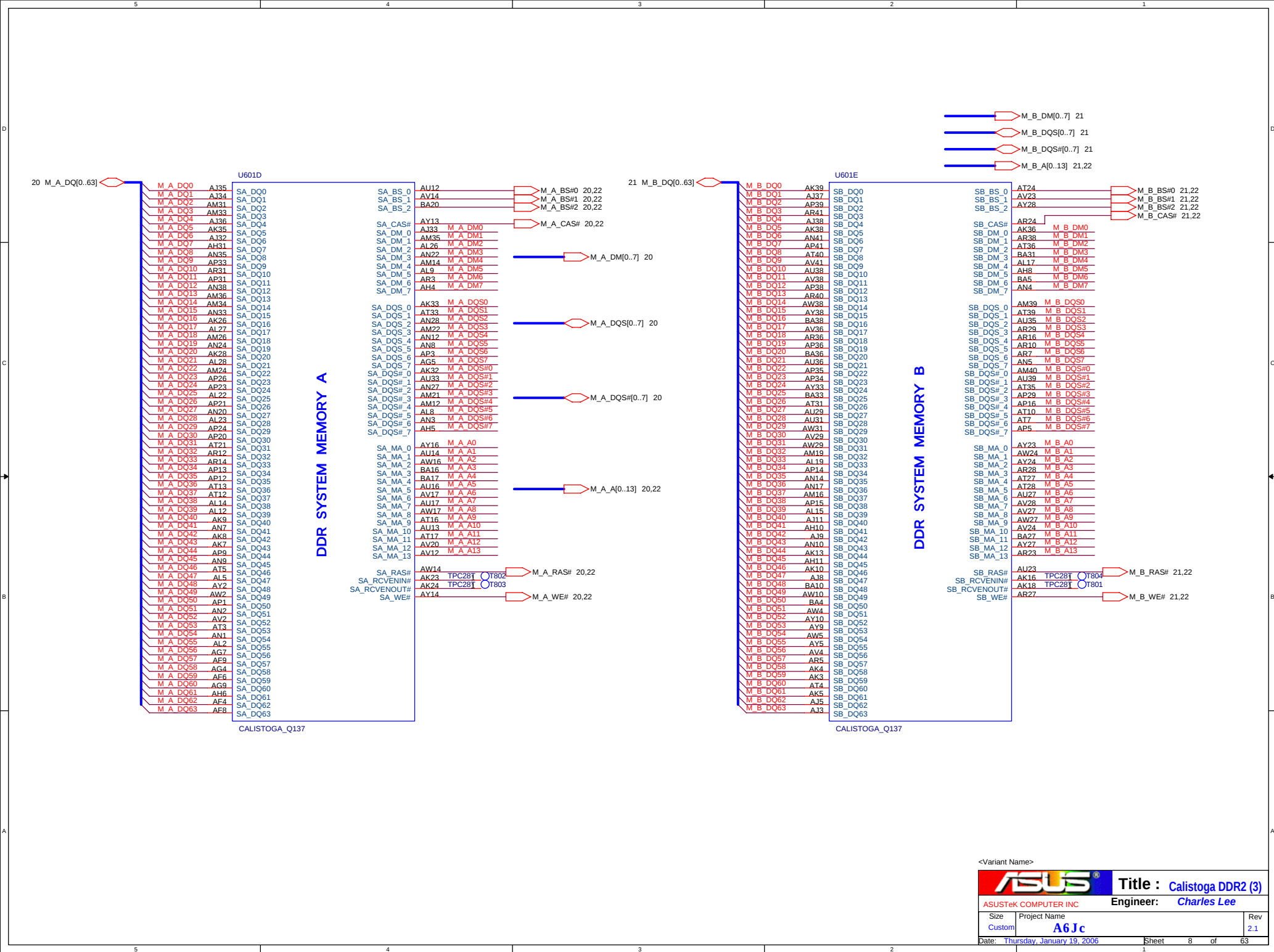
Request	Control net	Net name
PCIE_REQ1#	PCIE0(#), PCIE6(#)	None
PCIE_REQ2#	PCIE1(#), PCIE8(#)	None
PCIE_REQ3#	PCIE2(#), PCIE4(#)	CLK_PCIE_MINICARD1(#)
PCIE_REQ4#	PCIE3(#), PCIE5(#)	CLK_MCH_3GPLL(#)



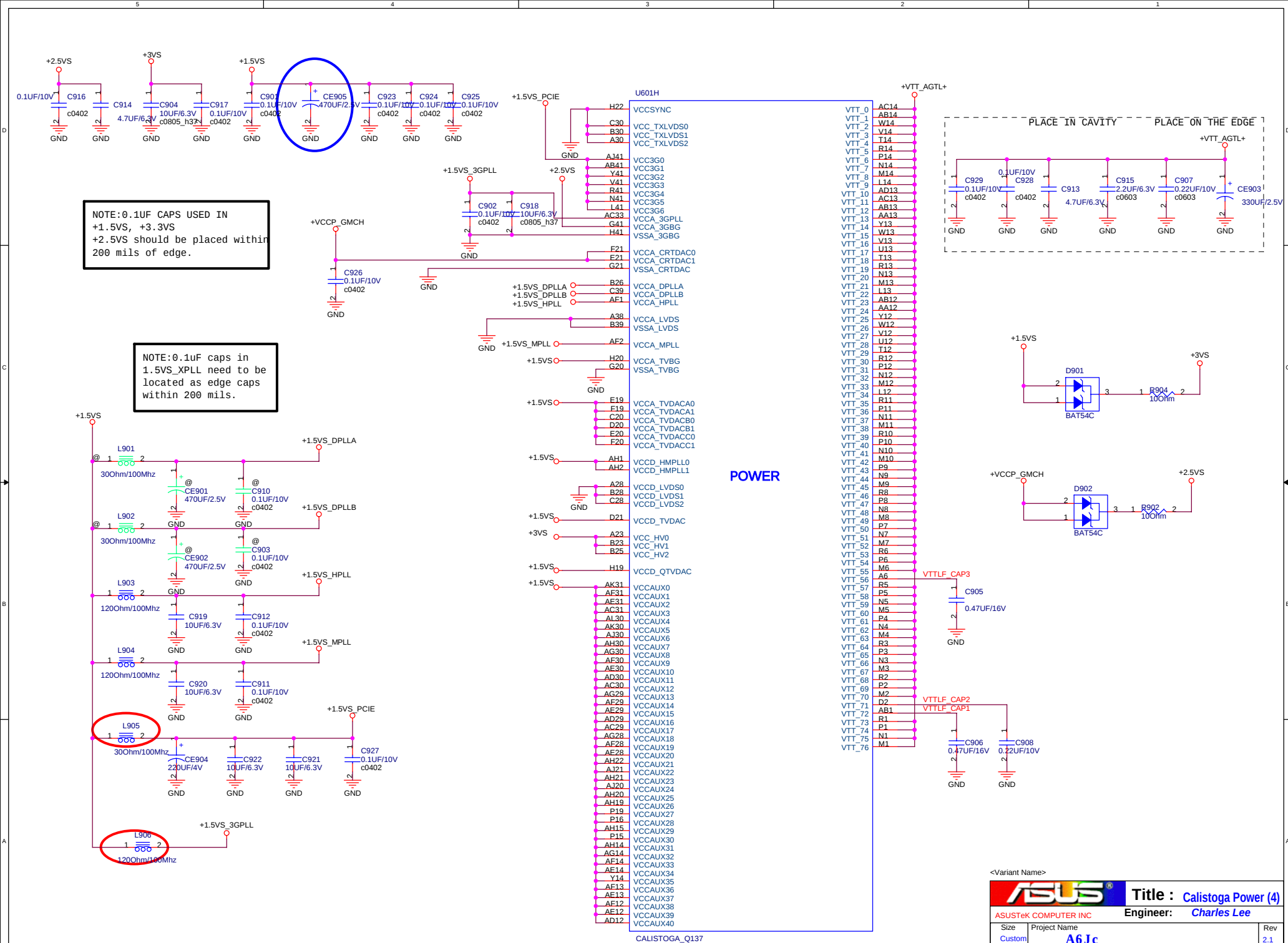
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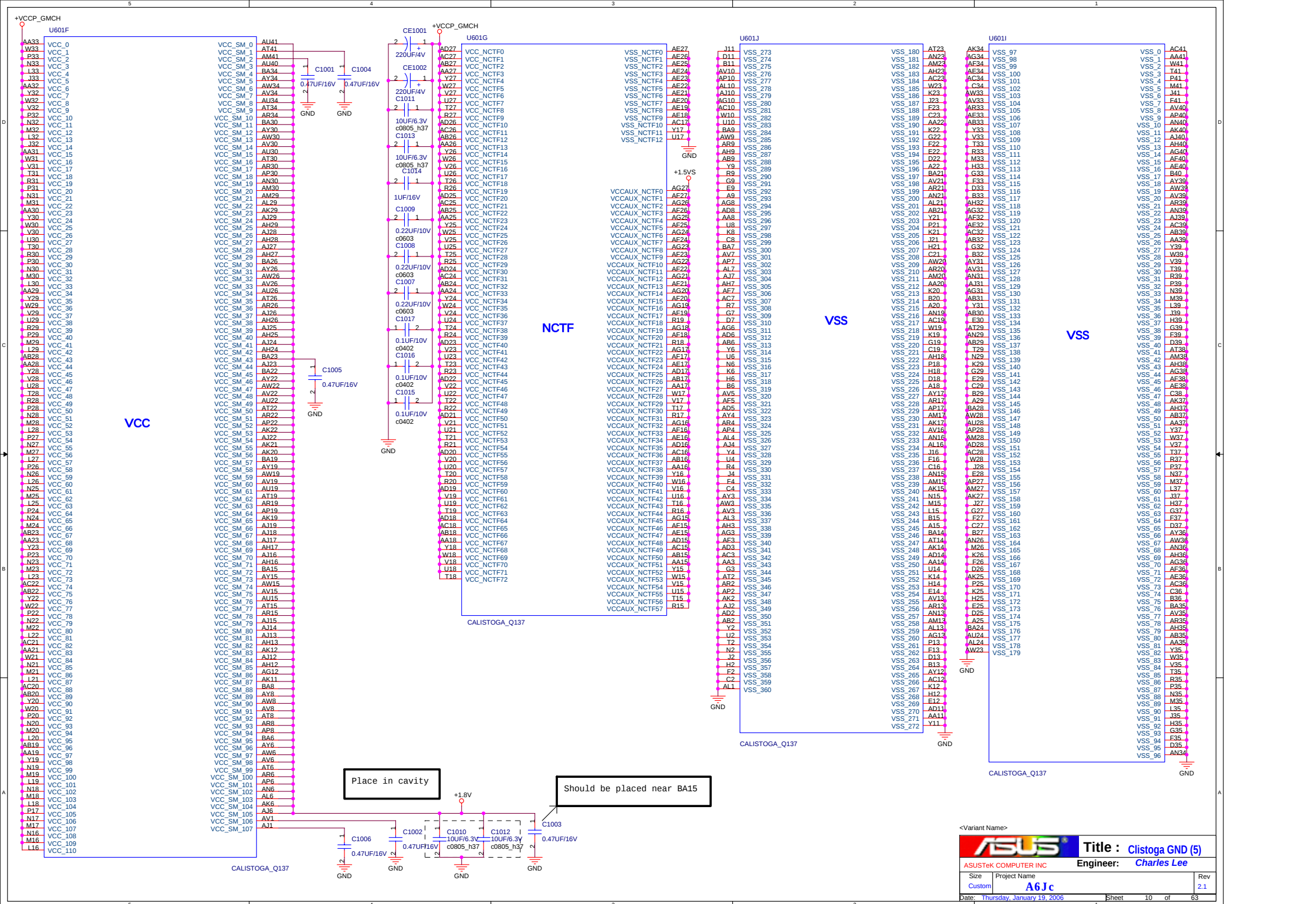
ASUS		Title : Calistoga MCH (1)	
ASUSTek COMPUTER INC		Engineer: Charles Lee	
Size	Project Name		Rev
Custom	A6Jc		2.1
Date: Thursday, January 19, 2006	Sheet	6	of 63

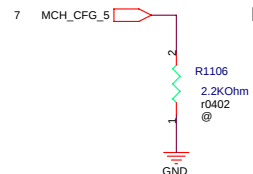




<Variant Name>

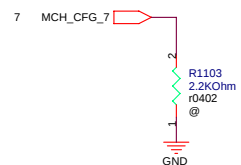






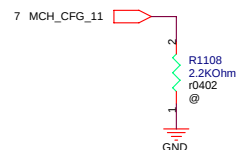
CFG5 : DMI STRAP

LOW = DMI X 2
HIGH = DMI X 4 (Default)



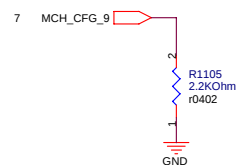
CFG7 : CPU STRAP

LOW = Mobile Prescott
HIGH = Dothan CPU (Default)



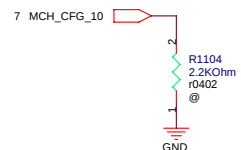
CFG11 : PSB 4X CLK ENABLE

LOW = REVERSAL
HIGH = Calistoga(Default)



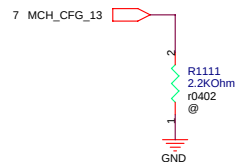
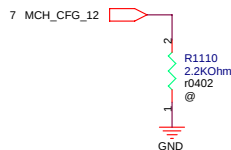
CFG9 : PCIE GRAPHIC LANE

LOW = REVERSE LANE (Default)
 HIGH = NORMAL OPERATION



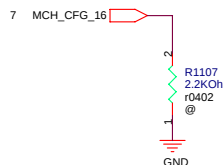
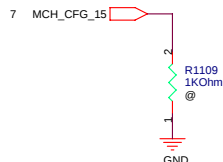
CFG10: HOST PLL VCO SELECT

LOW = RESERVED
HIGH = MOBILITY



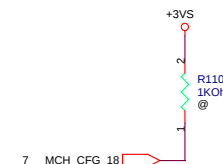
CFG15 :ICH RESET DISABLE

LOW = ICH RESET DISABLE
HIGH = NORMAL OPERATION



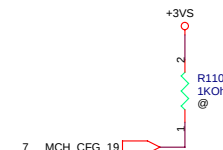
CFG16 : FSB DYNAMIC ODT

LOW = Dynamic ODT Disabled
HIGH = Dynamic ODT Enabled (Default)



CFG18 : GMCH Core Voltage Level

LOW = 1.05V (Default)
 HIGH = 1.5V



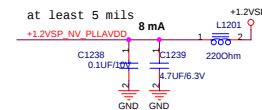
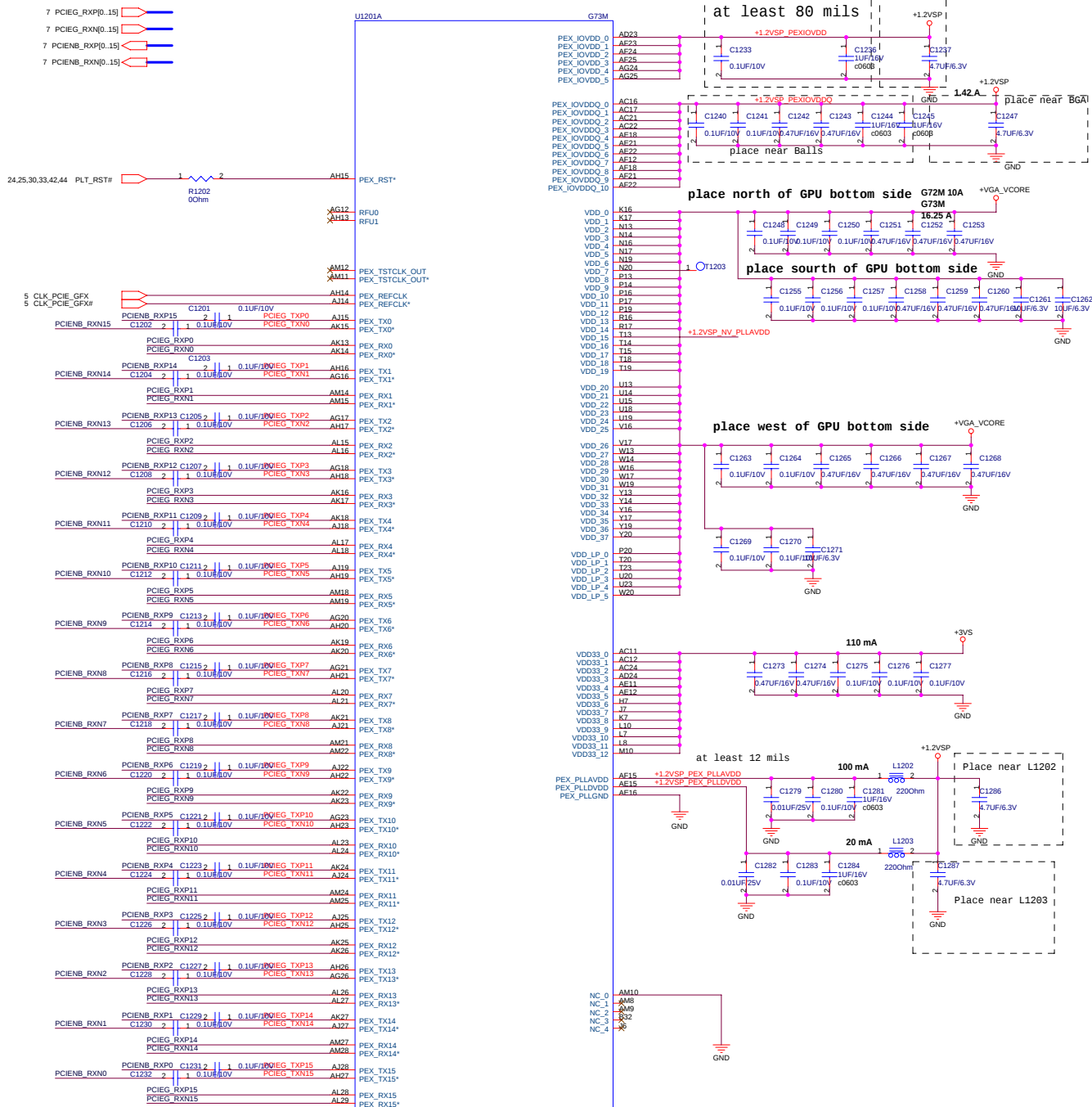
CFG19 : DMI LANE REVERSAL

LOW = NORMAL
 HIGH = LANES REVERSED

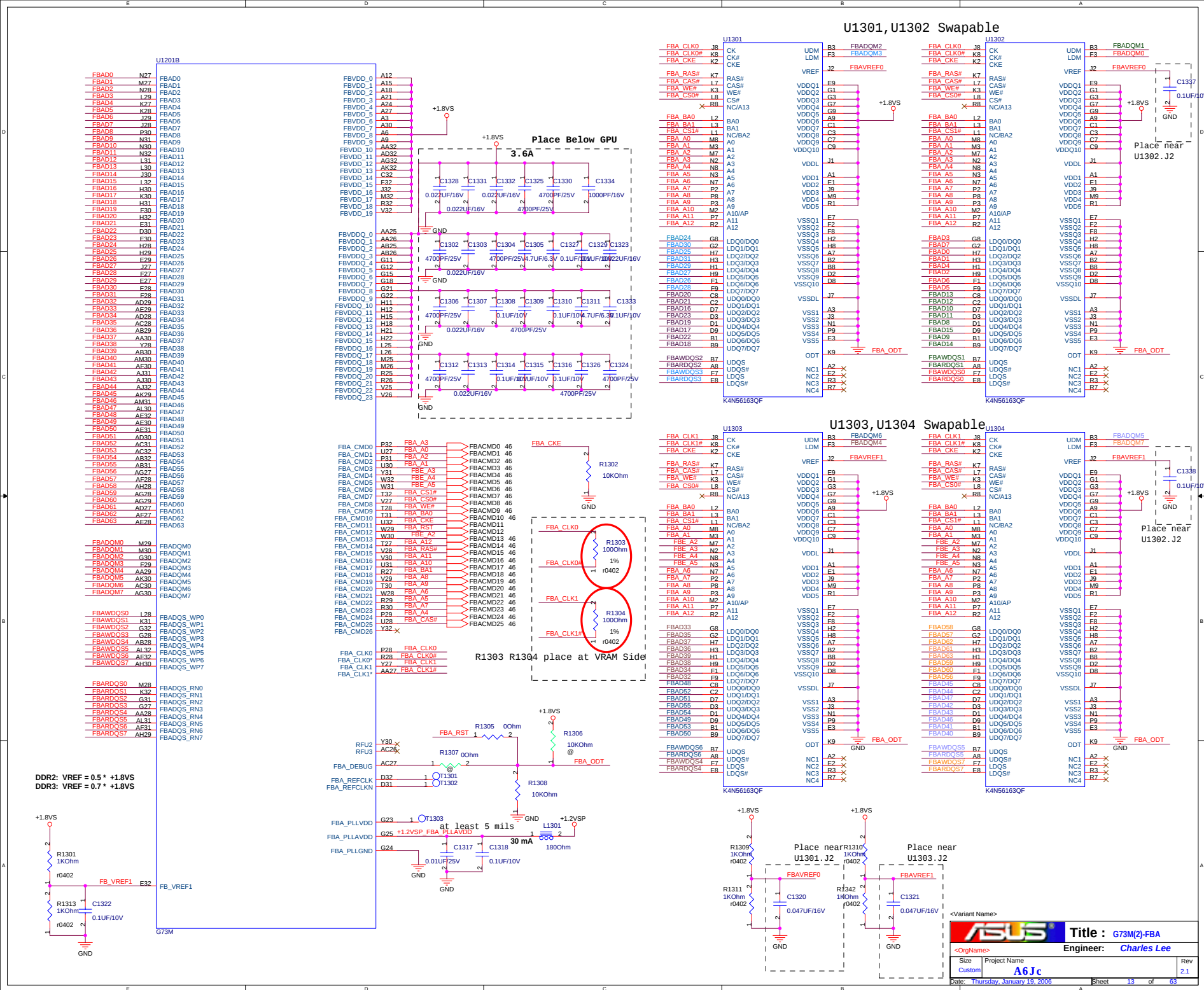
CFG[17..3] have internal pullup resistors.
 CFG[20..18] have internal pulldown resistors.
 SDVOCRTL_DATA has internal pulldown resistors.

<Variant Name>

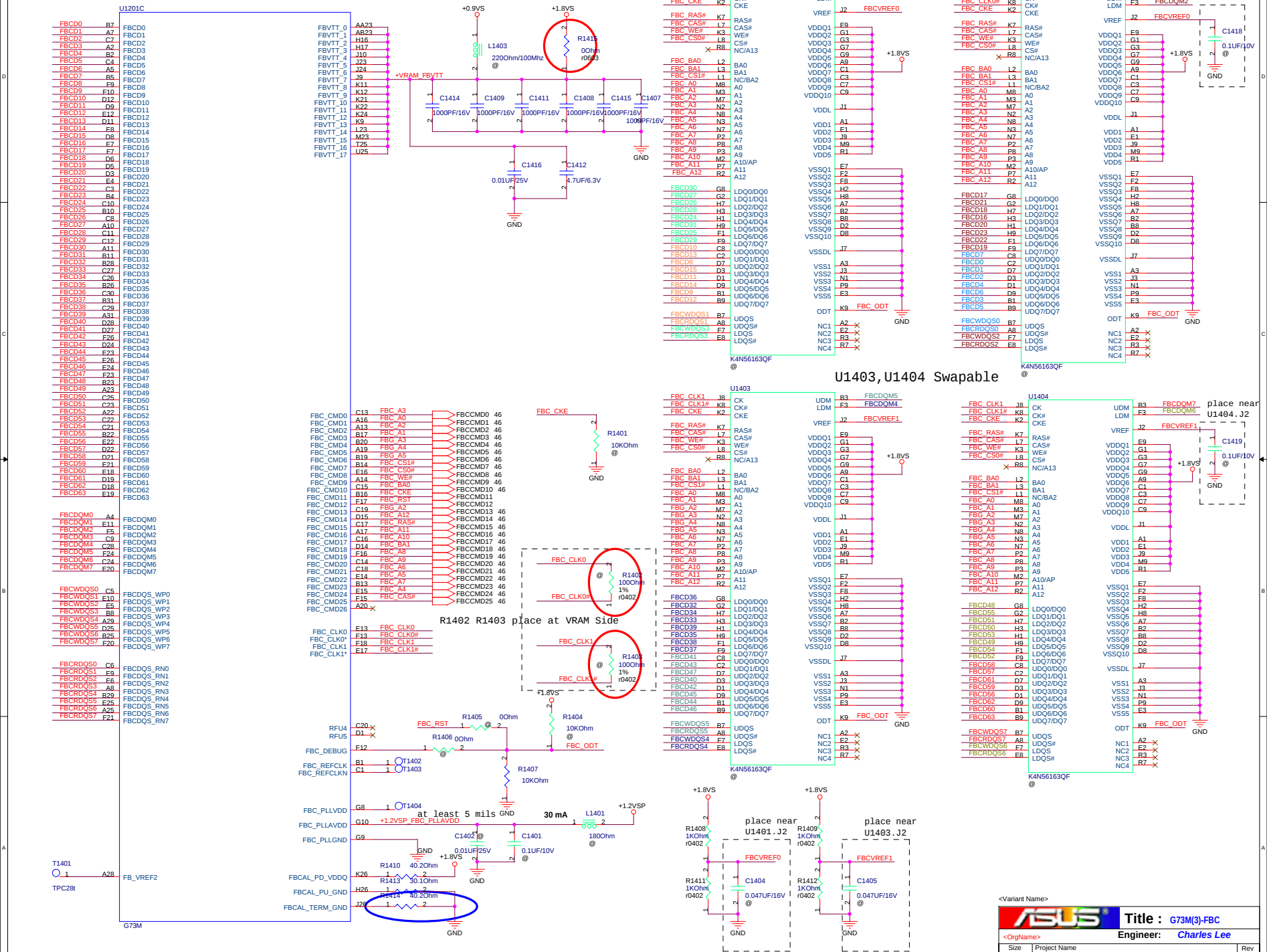
		Title : Calistoga Strapping	
ASUSTek COMPUTER INC		Engineer: Charles Lee	
Size Custom	Project Name A6Jc	Rev 2.1	
Date: Thursday, January 19, 2006		Sheet 11 of 63	

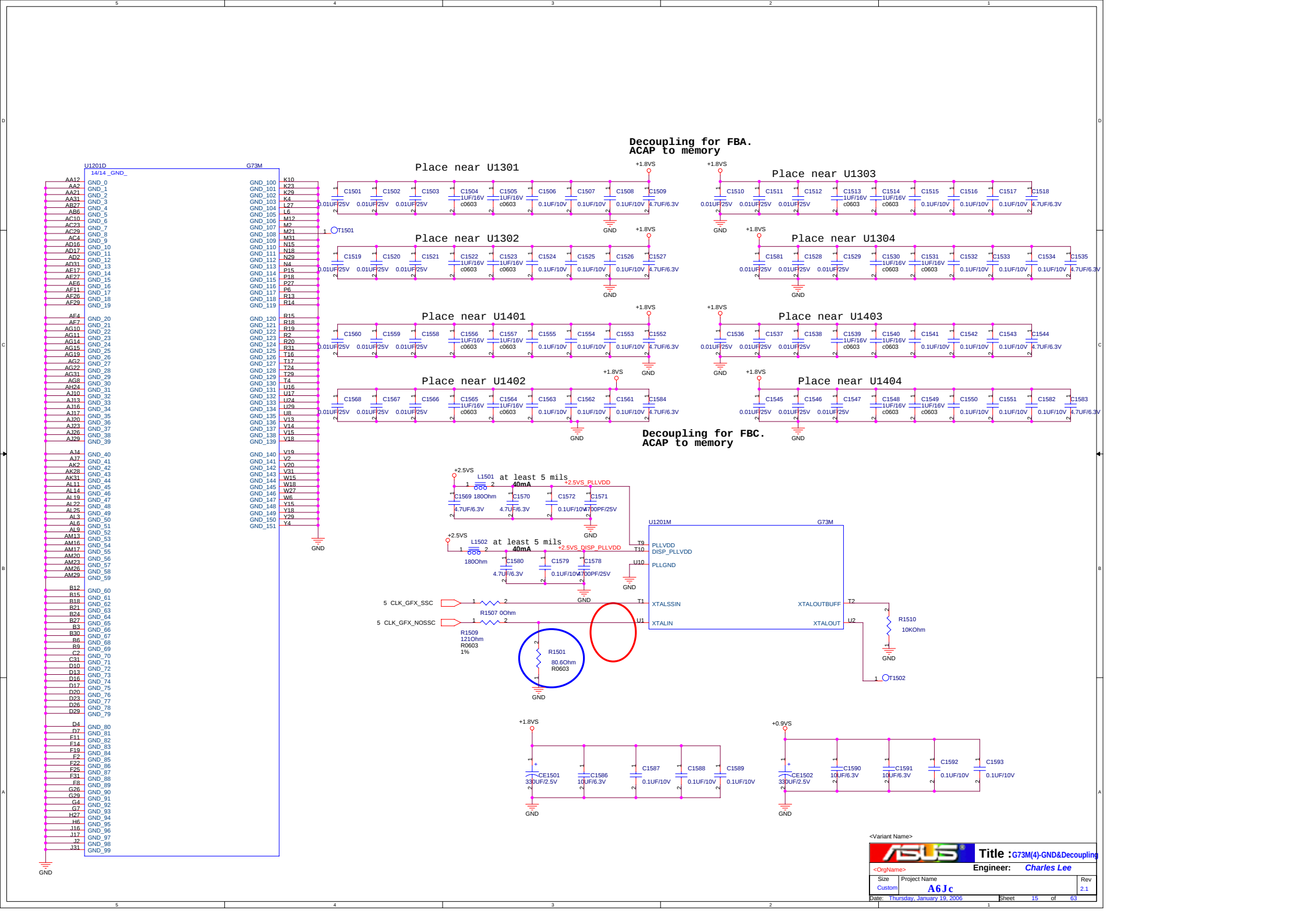


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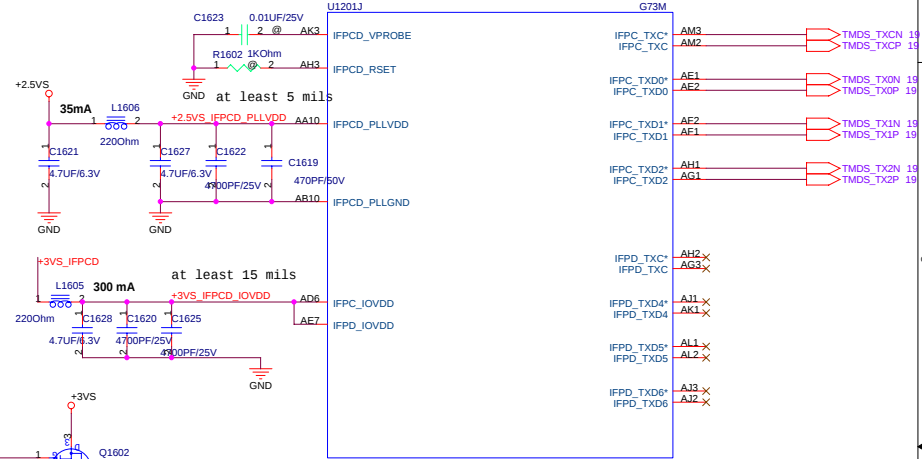
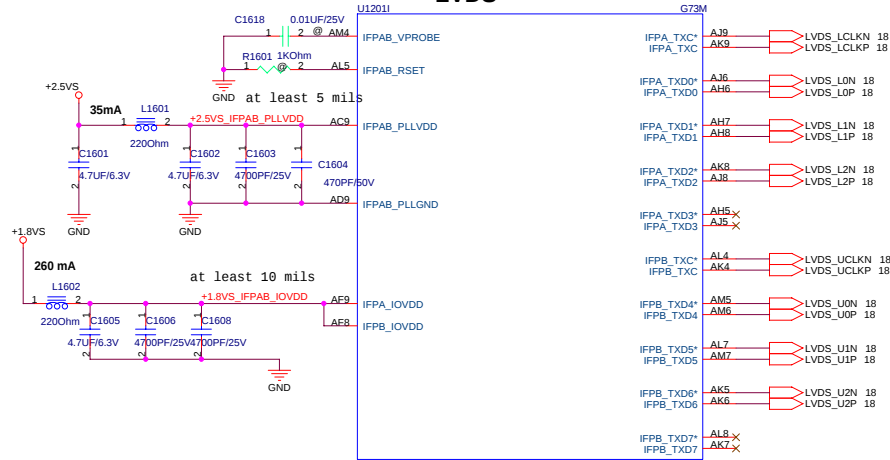


DDR2 Terminated FBVTT=0.5* +1.8VS
Unterminated FBVTT=+1.8VS

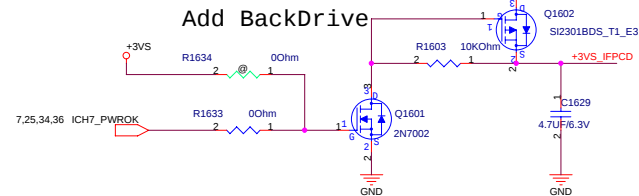




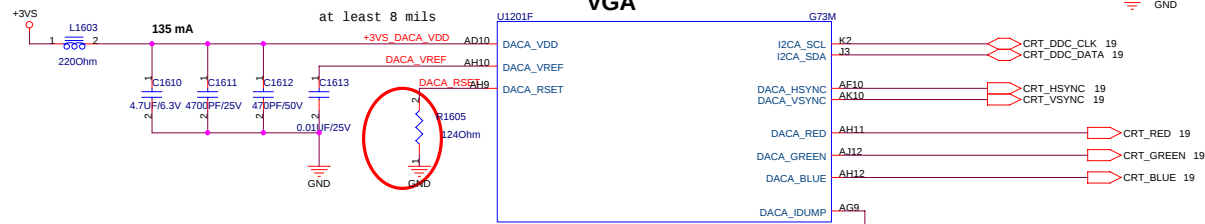
LVDS



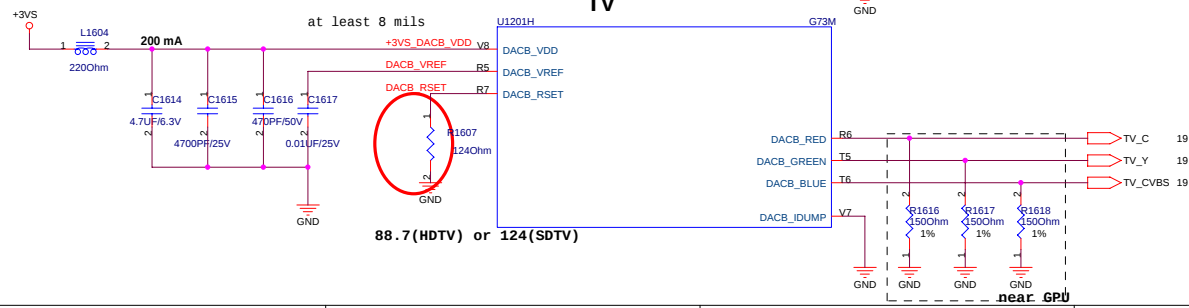
Add BackDrive



VGA

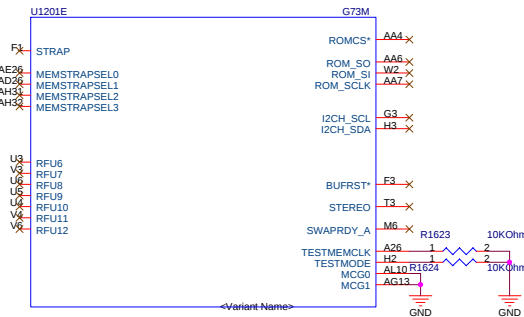
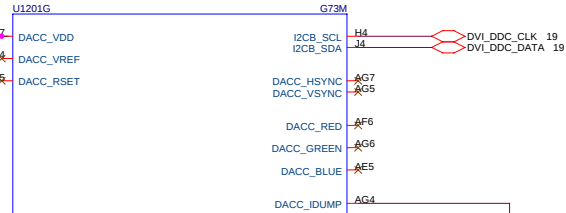


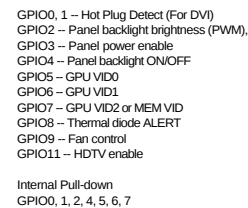
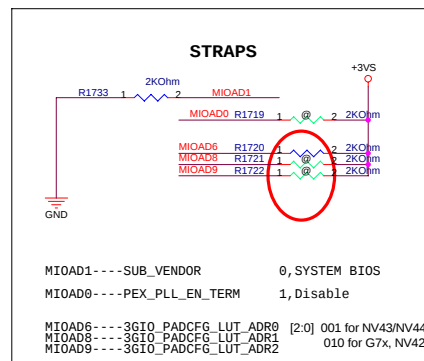
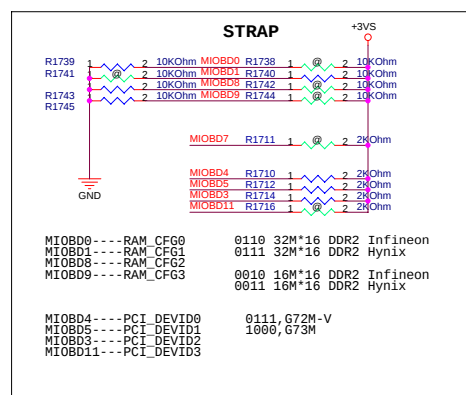
TV



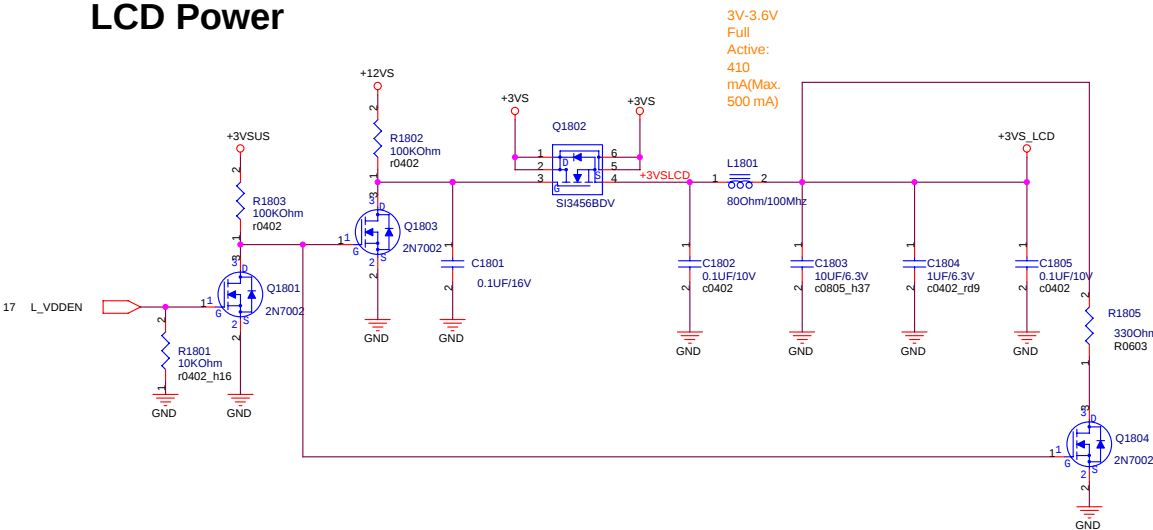
88.7(HDTV) or 124(SDTV)

near GPU

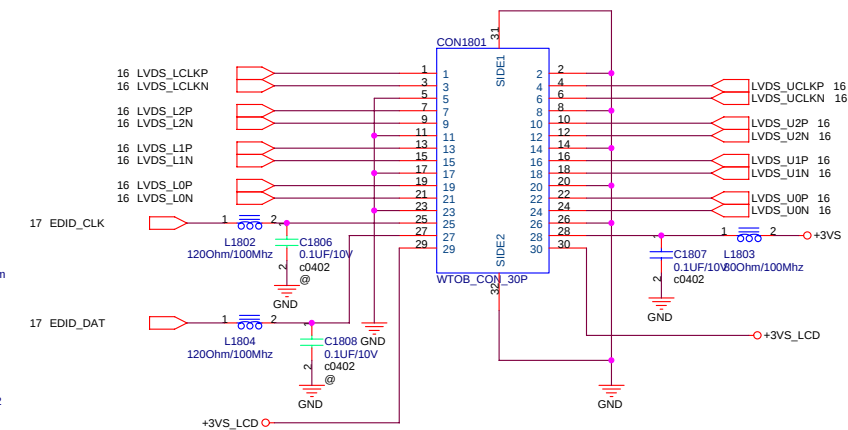




LCD Power



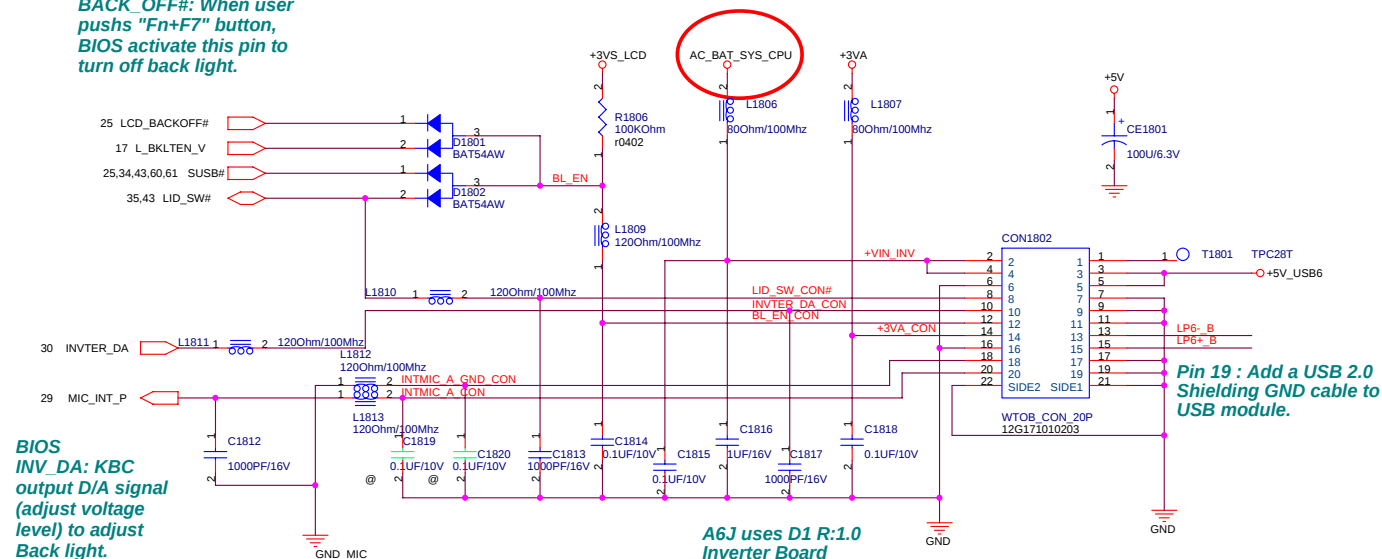
LCD LVDS Interface



Cable Requirement:
Impedence: 100 ohm +/- 10%
Length Mismatch <= 10 mils
Twisted Pair(Not Ribbon)
Maximum Length <= 16"

INVERTER Interface

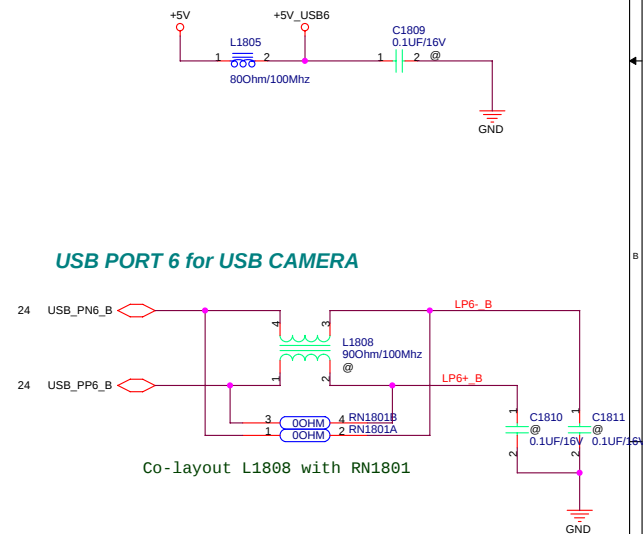
BIOS
BACK_OFF#: When user
pushs "Fn+F7" button,
BIOS activate this pin to
turn off back light.



For EMI



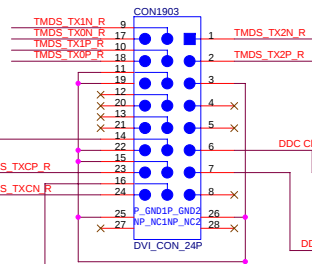
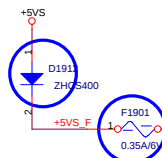
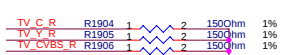
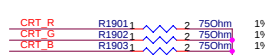
USB PORT 6 for USB CAMERA



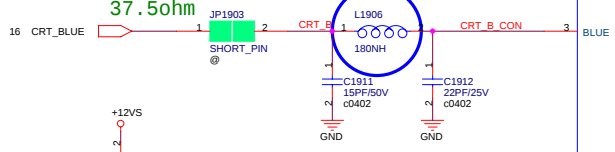
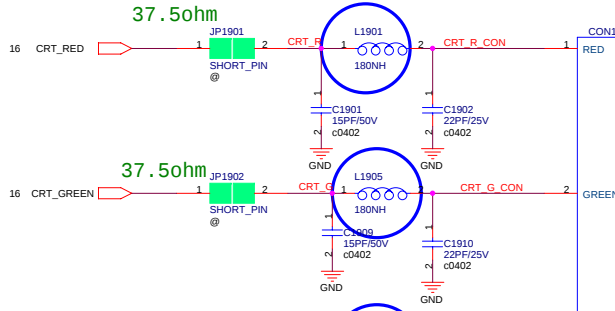
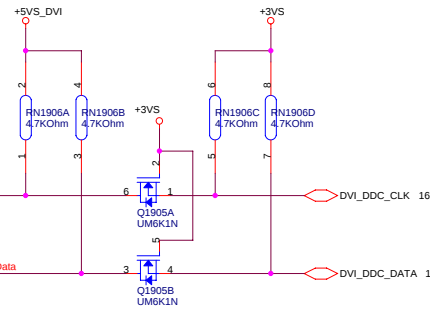
A6J doesn't support USB
WLAN function!

<Variant Name>

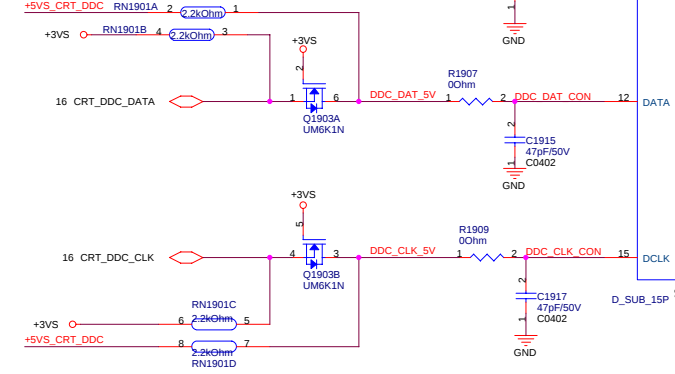
ASUS		Title : LVDS & INVERTER	
<OrgName>		Engineer: Charles Lee	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	18	of 63



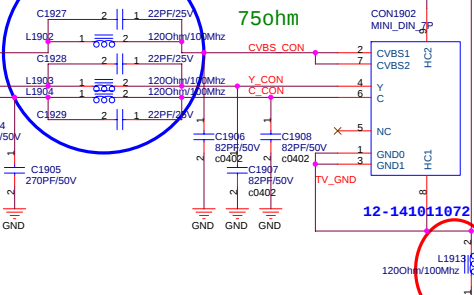
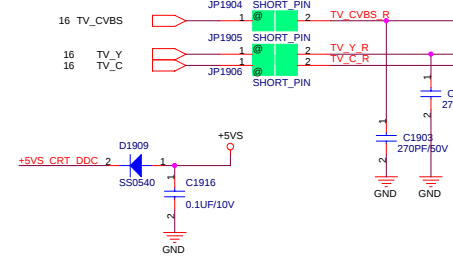
RN1906 Swapable



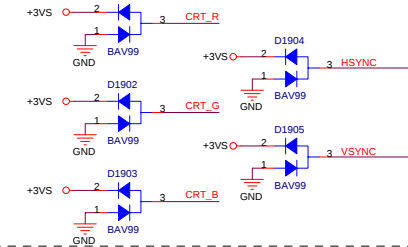
RN1901 Swapable



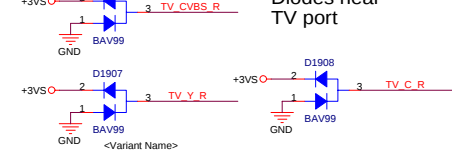
500ohm

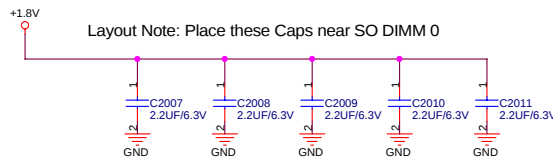
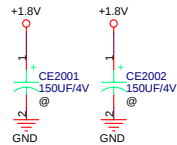
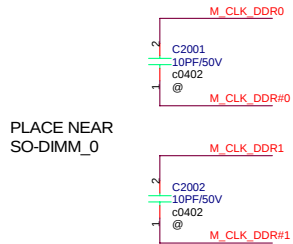
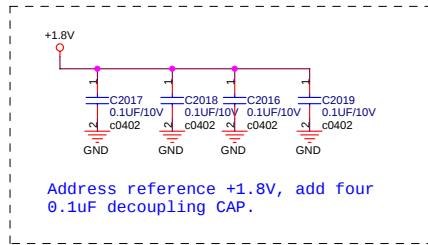


PLACE ESD Diodes near VGA port



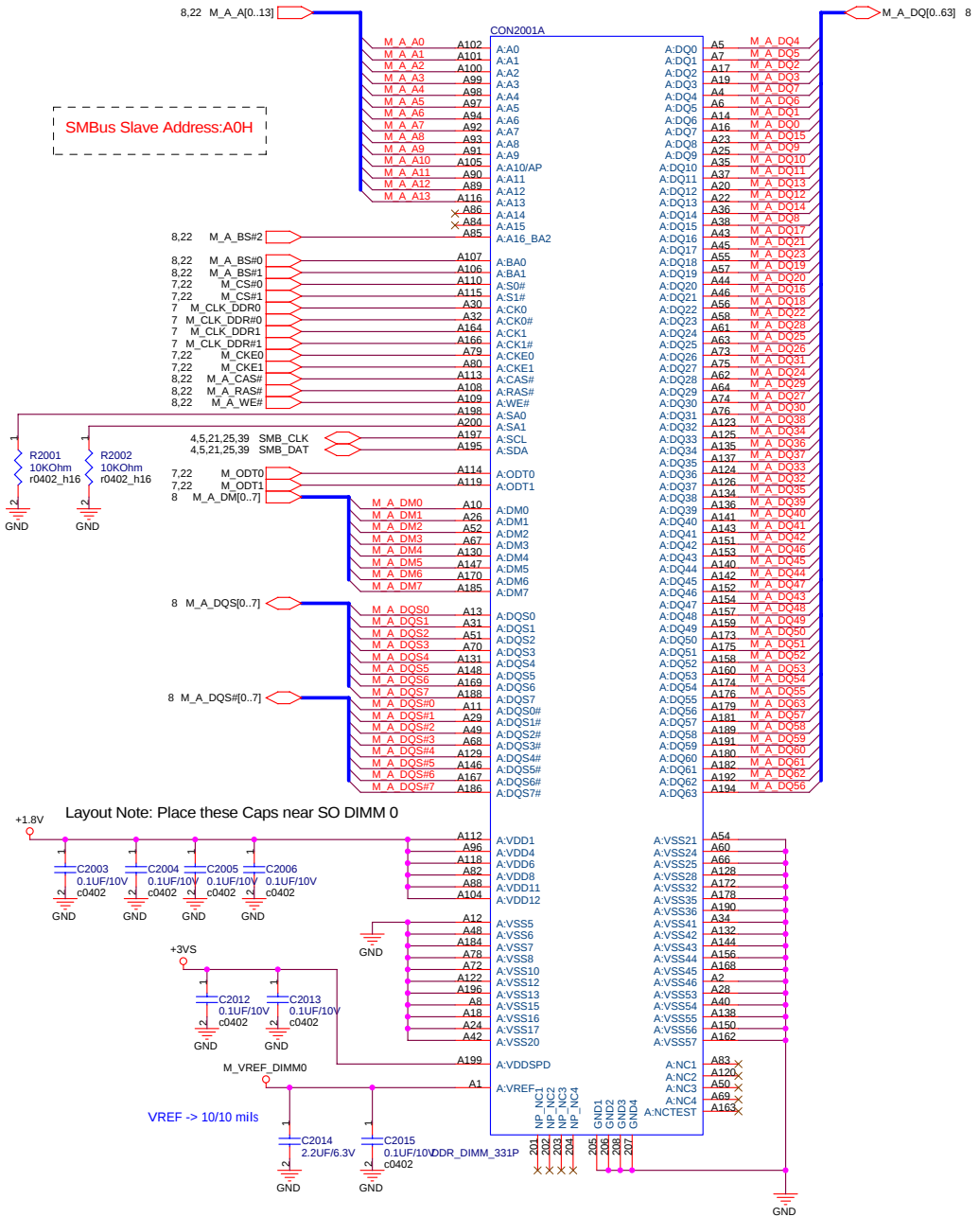
PLACE ESD Diodes near TV port

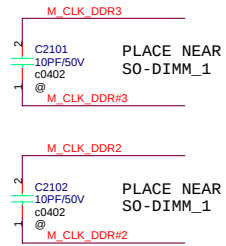
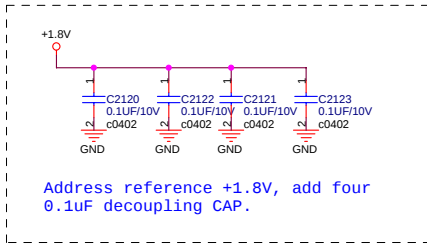




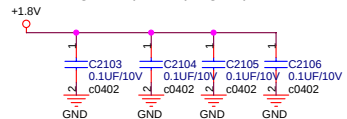
SO-DIMM 0 is placed farther from the GMCH than SO-DIMM 1

SMBus Slave Address: A0H

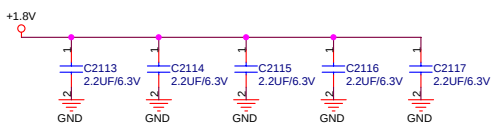




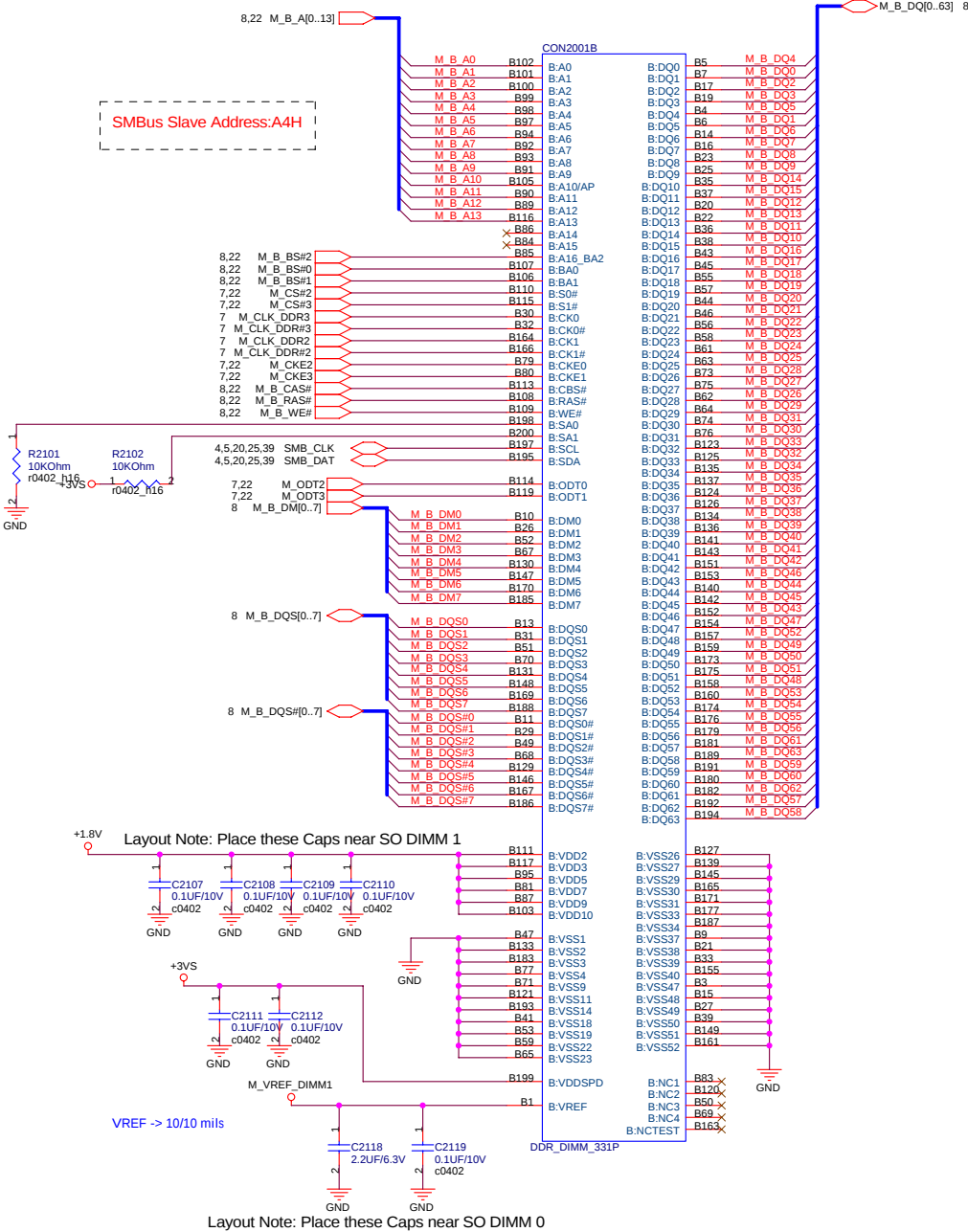
Layout Note: Place these High-Freq decoupling Caps near the GMCH

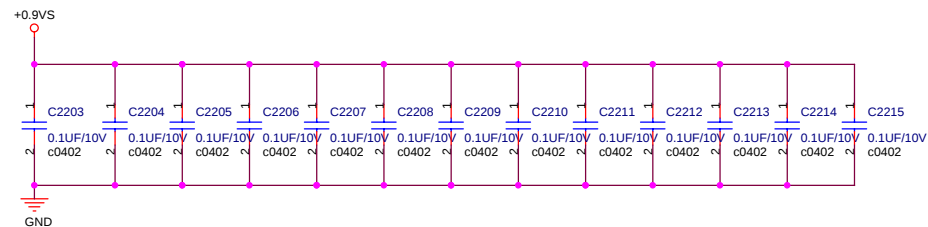
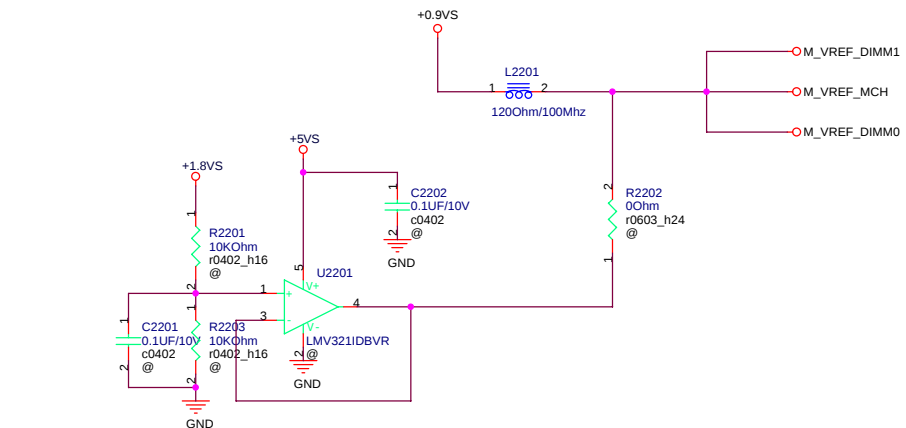


Layout Note: Place these CAPs near the GMCH

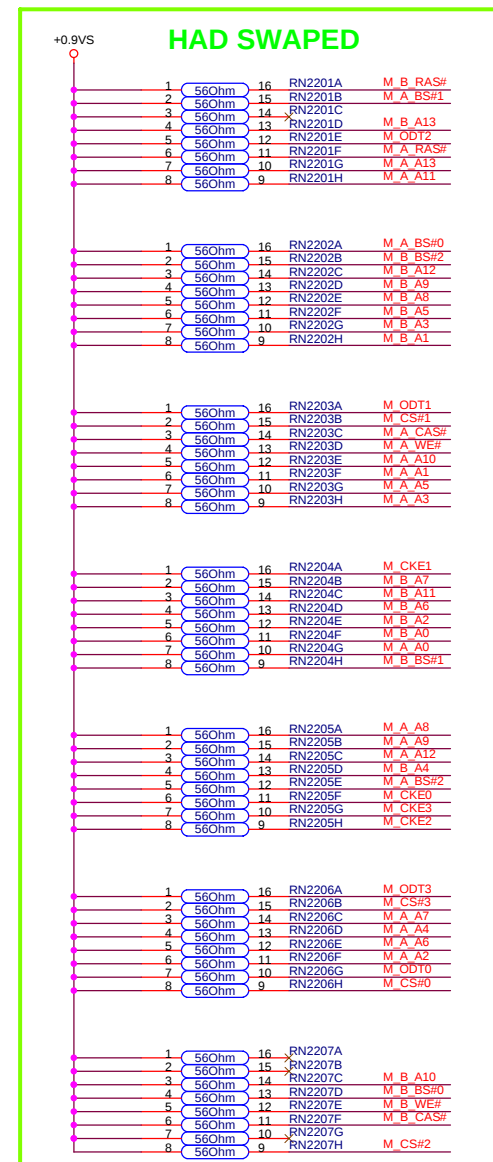
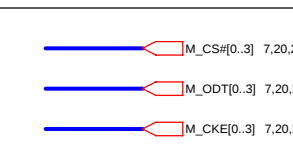
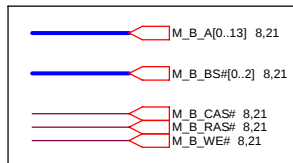
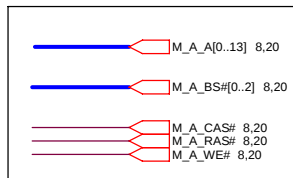
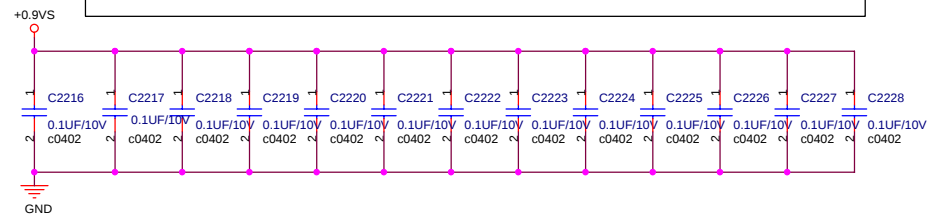


SMBus Slave Address:A4H

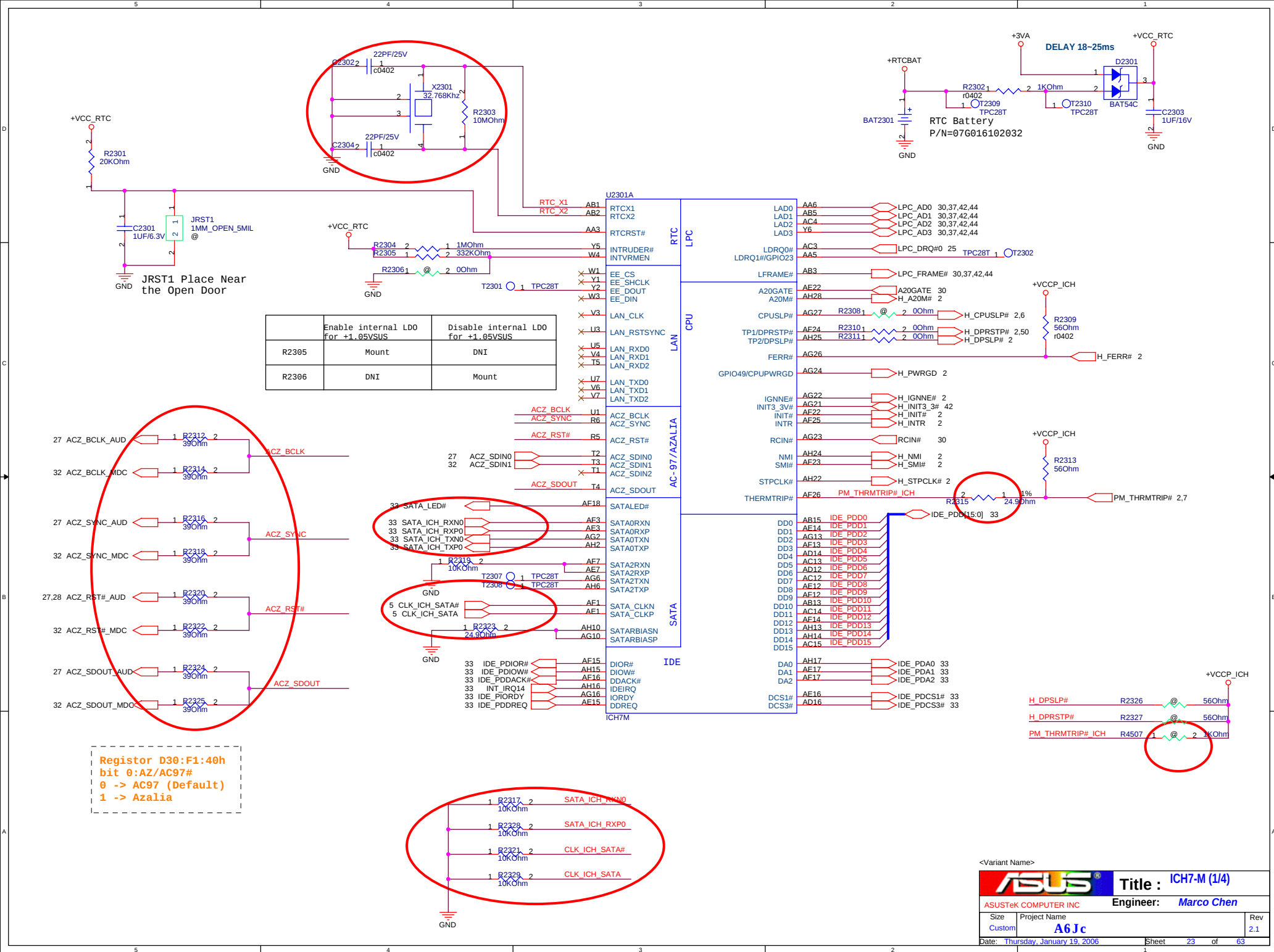


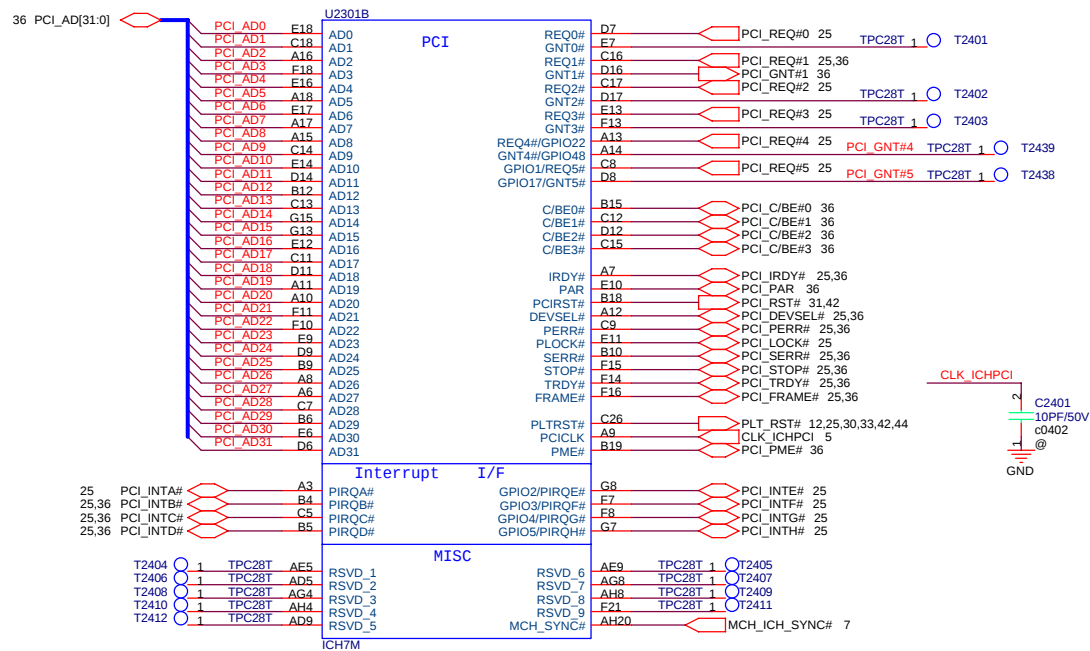


Layout note: Place one cap close to every 2 pullup resistors terminated to +0.9VS



<Variant Name>

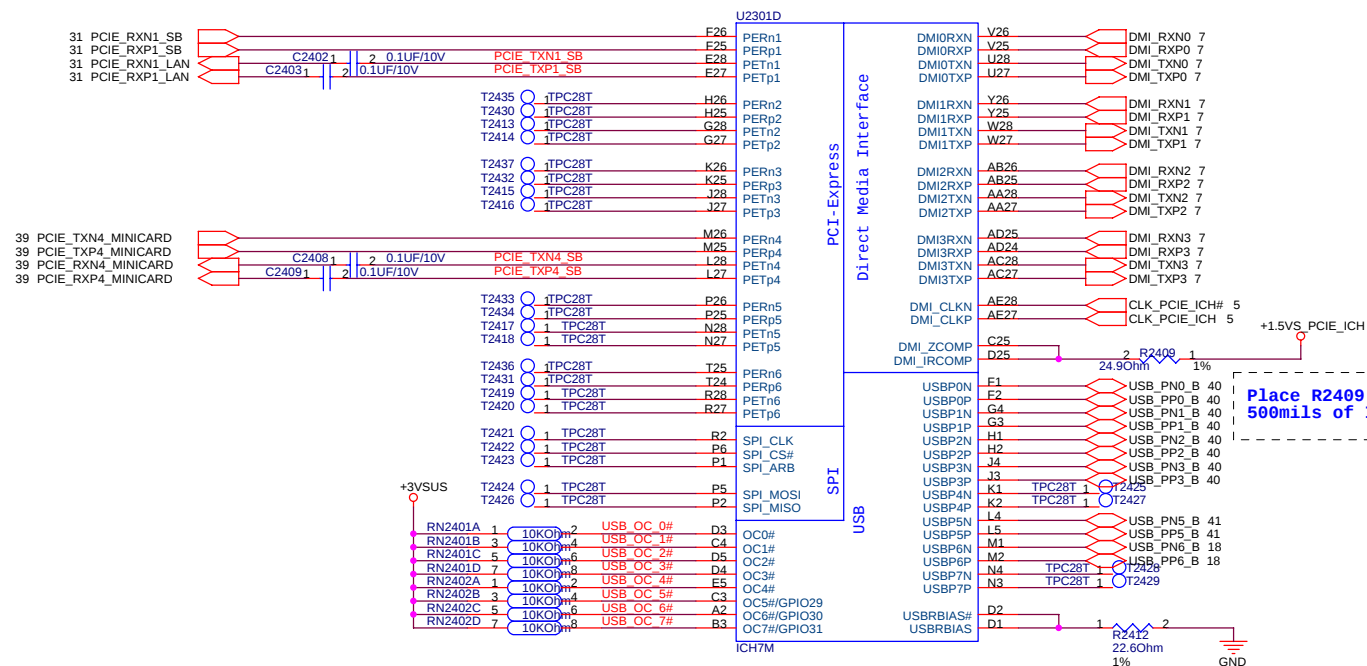




ICH-7 BOOT BIOS select

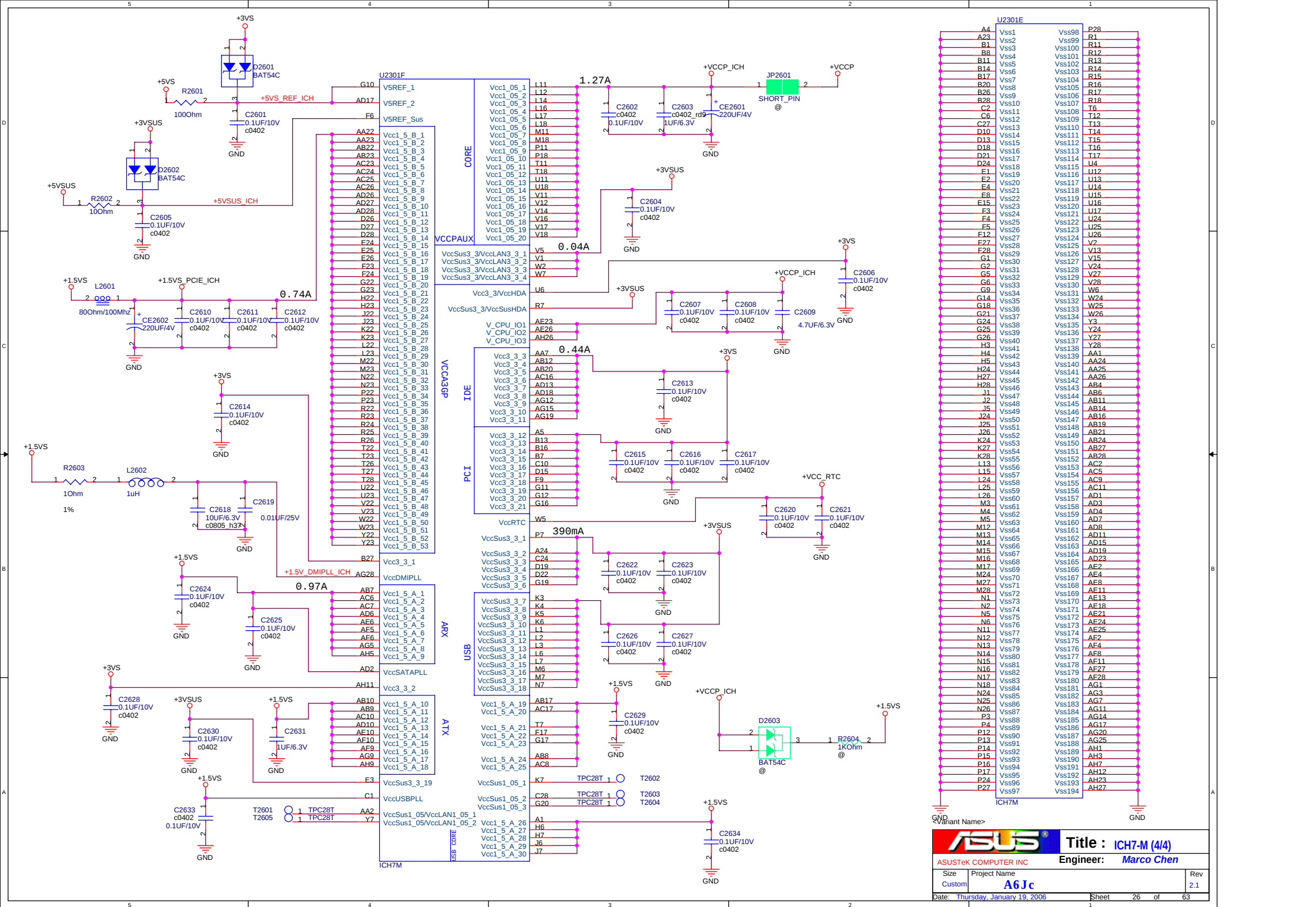
	GNT#5	GNT#4
LPC	11	1
PCI	10	0
SPI	01	0

(default)

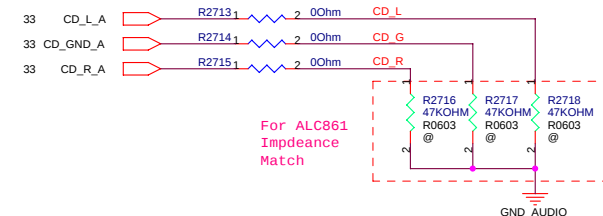
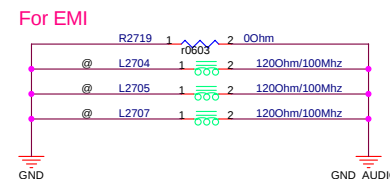
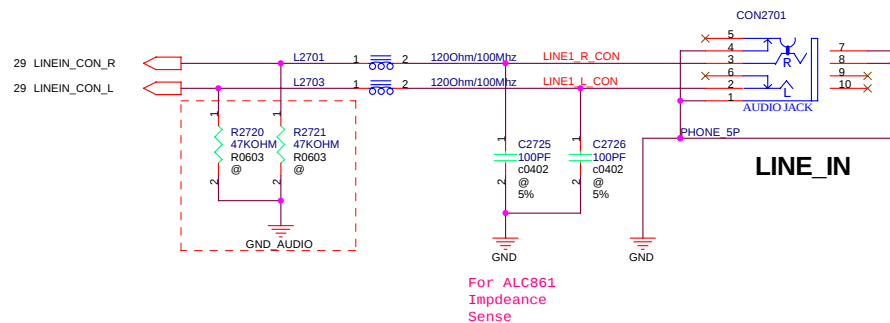
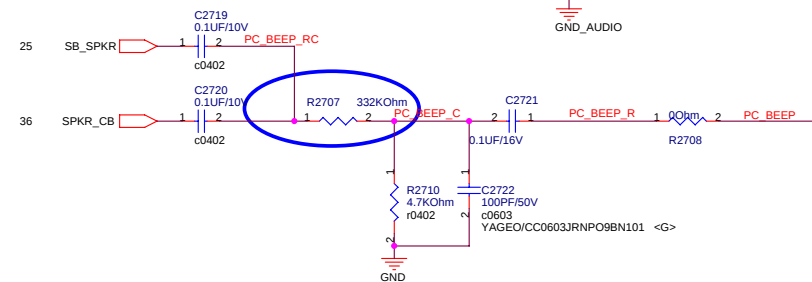
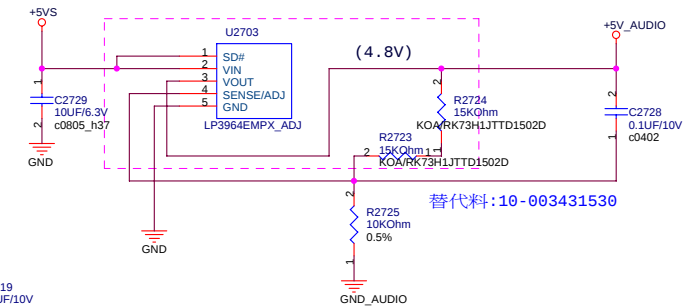
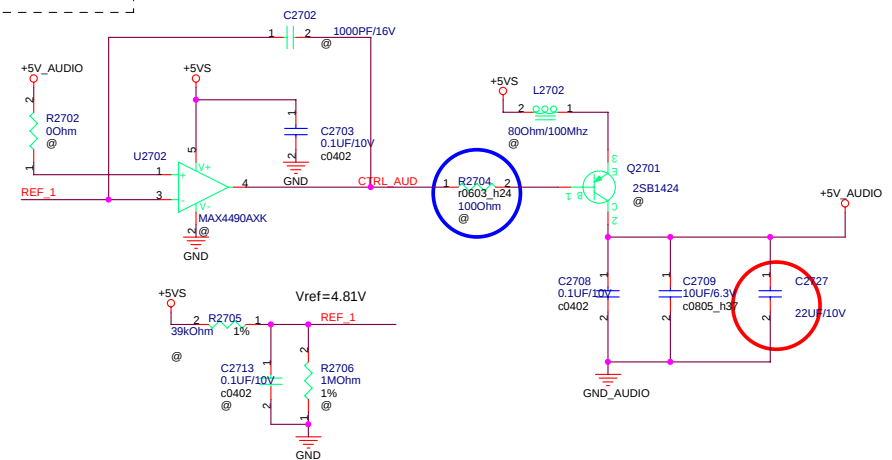
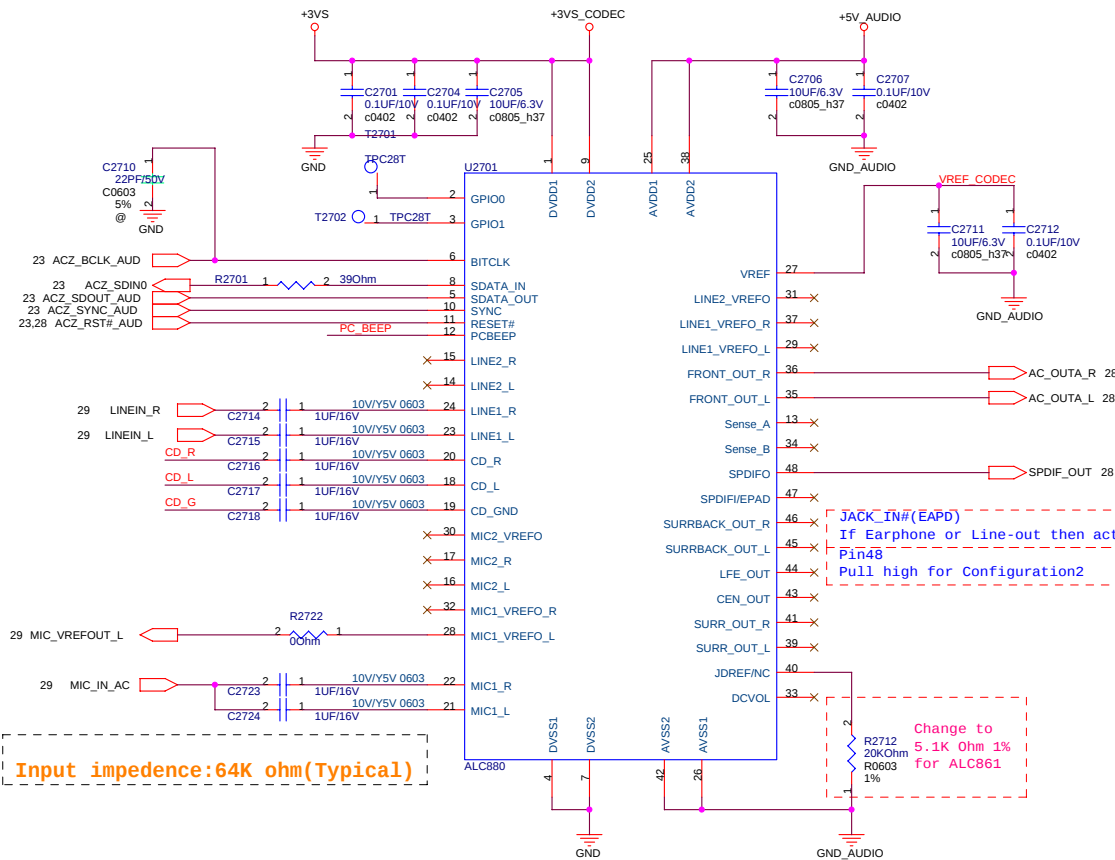


<Variant Name>

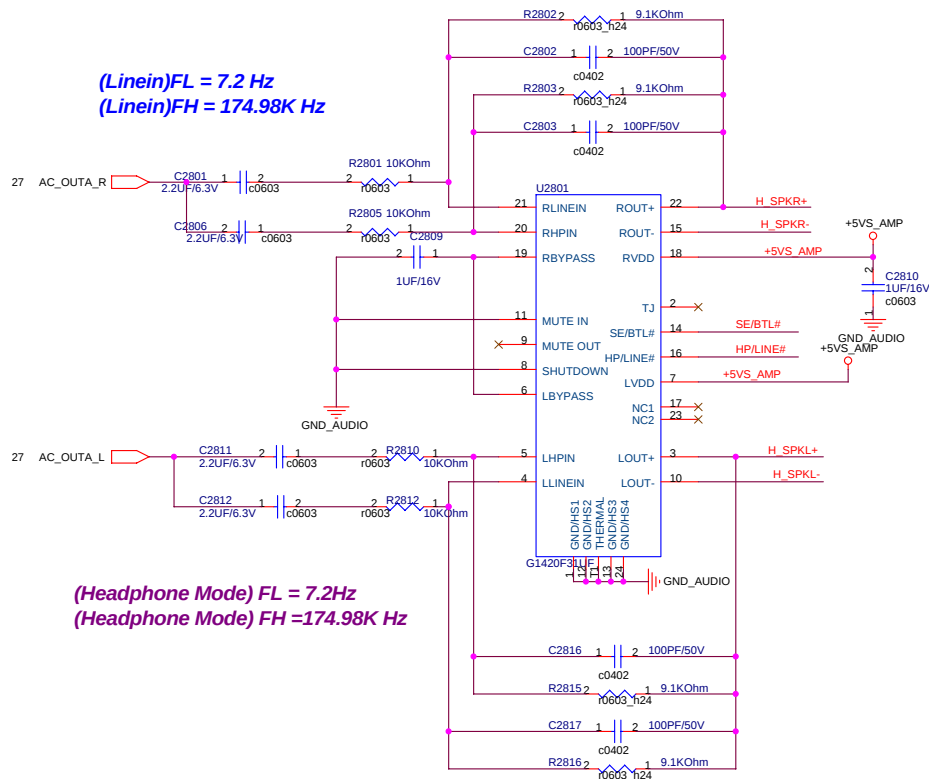
ASUS		Title : ICH7-M (2/4)	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	24	of 63



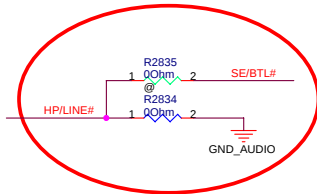
Place U2802near U2801



(Linein)FL = 7.2 Hz
(Linein)FH = 174.98K Hz

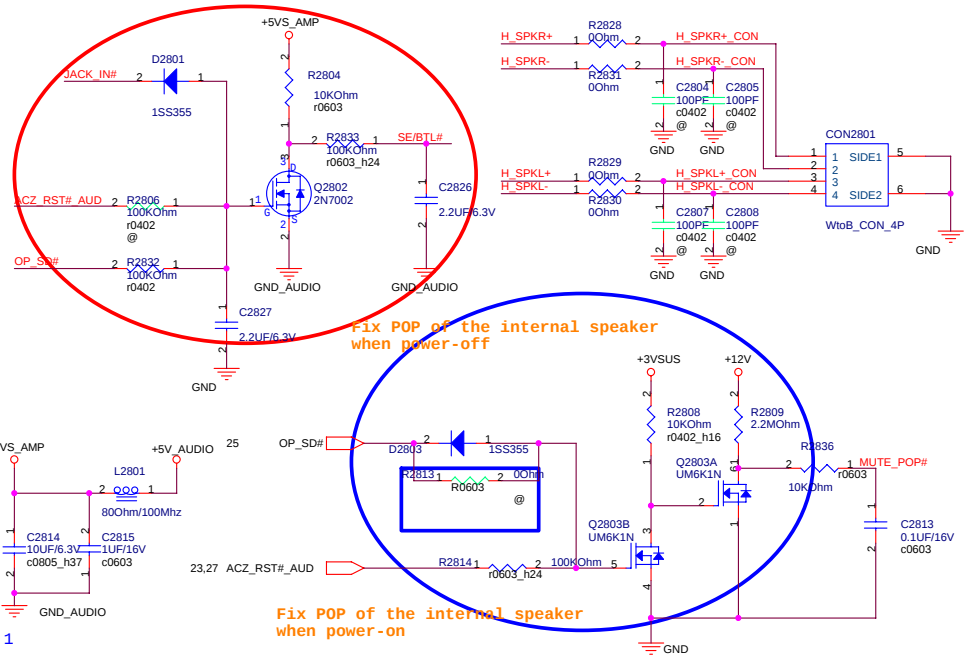


(Headphone Mode) FL = 7.2Hz
(Headphone Mode) FH = 174.98K Hz

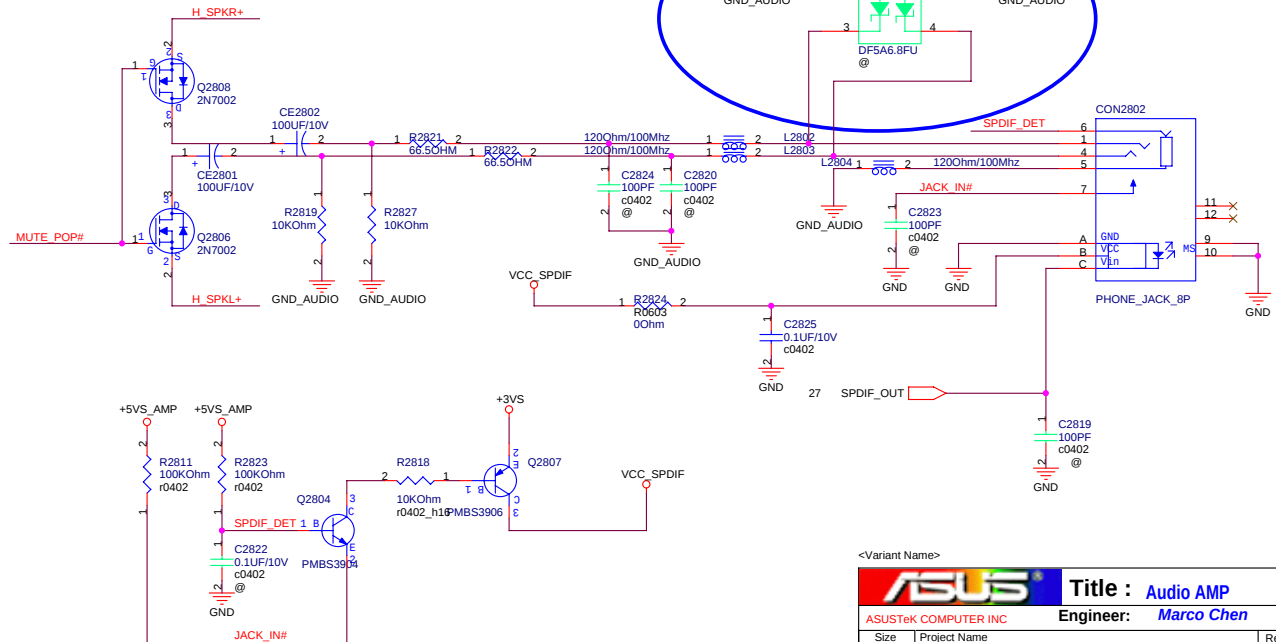


	SE/BTL#	SPDIF_IN
SPDIF Mode	H	Hi-Z
HP Mode	H	L
SPK Mode	L	X

PR BLOCK 1

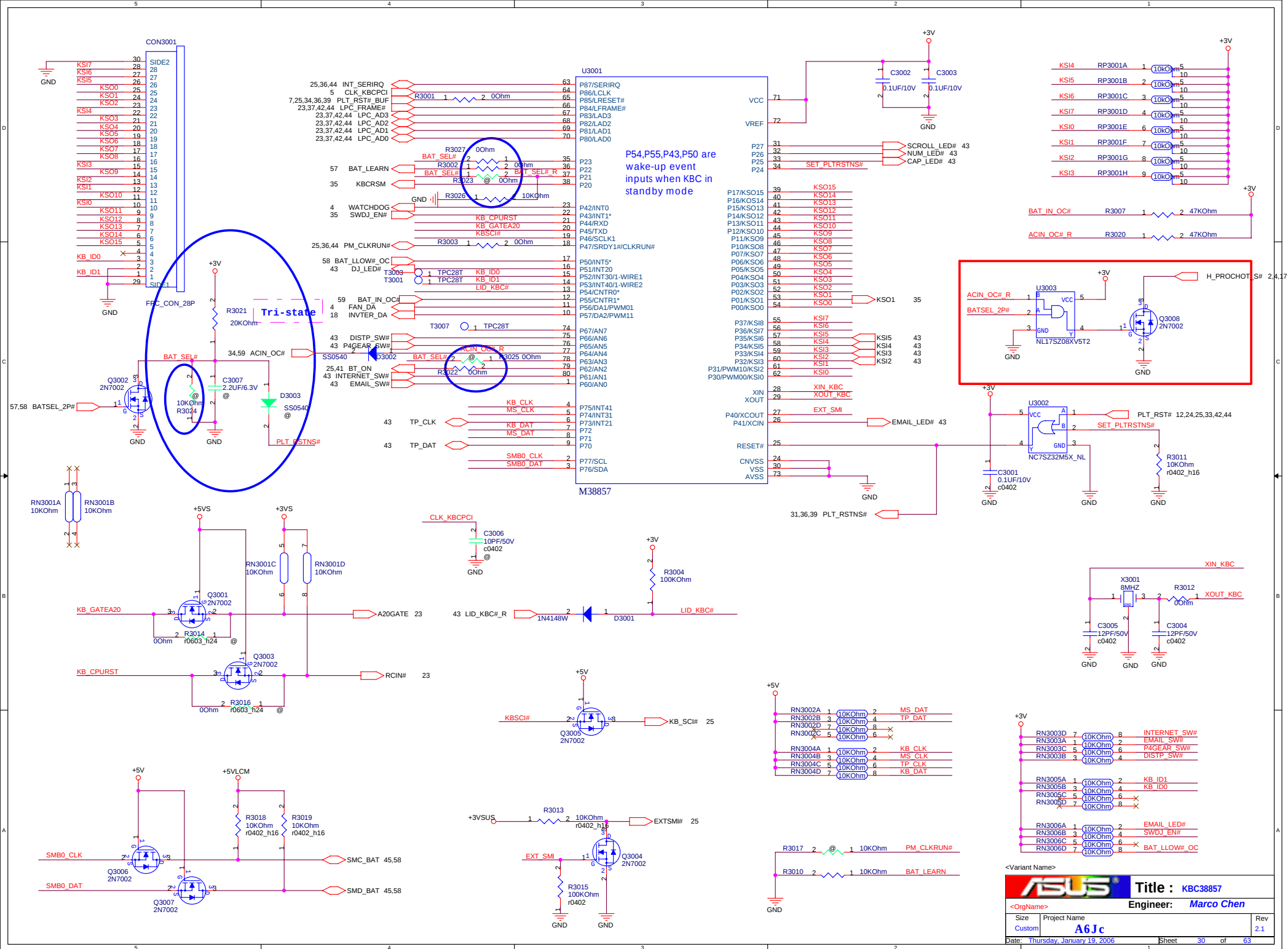


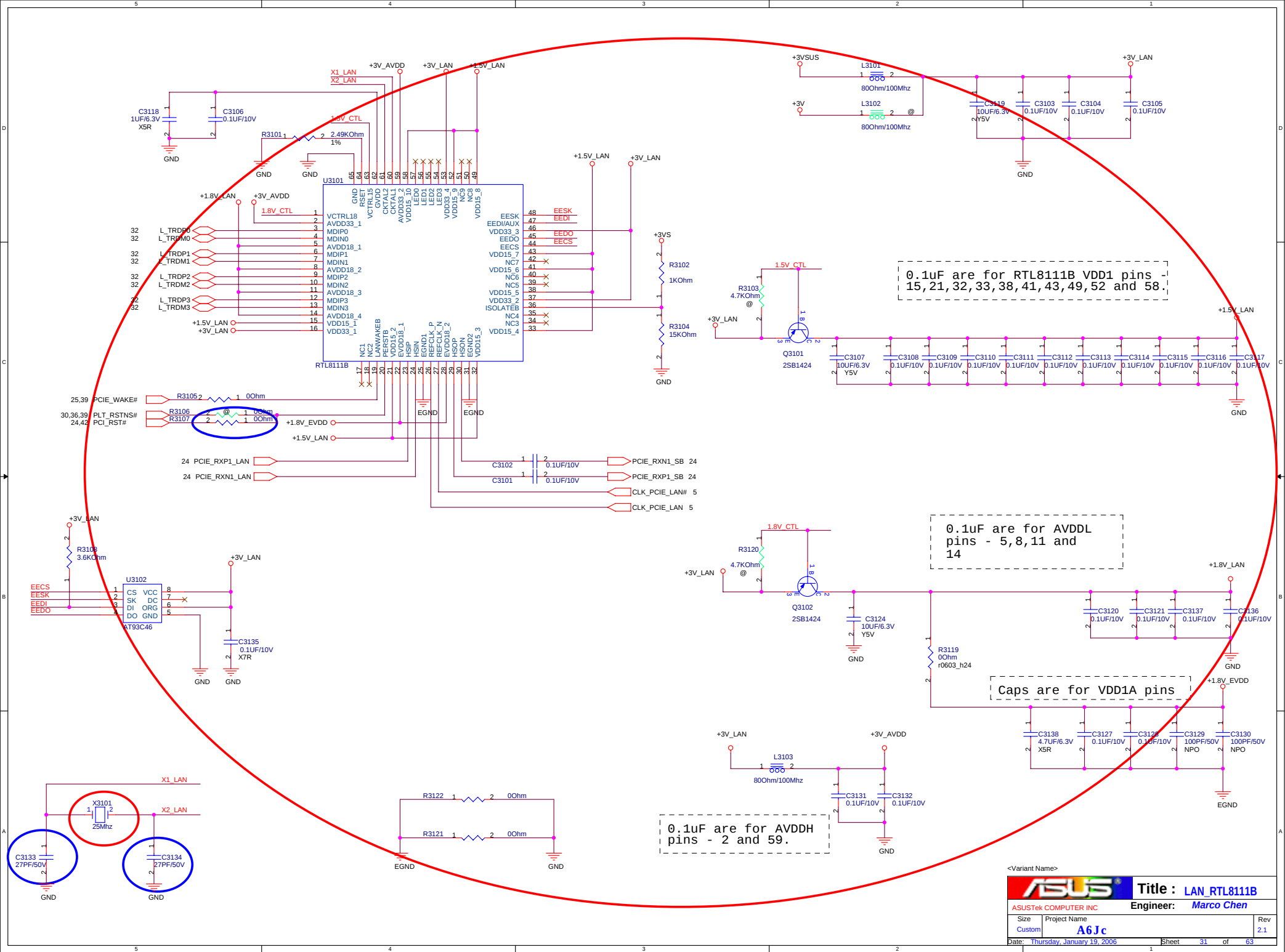
Headphone & SPDIF JACK



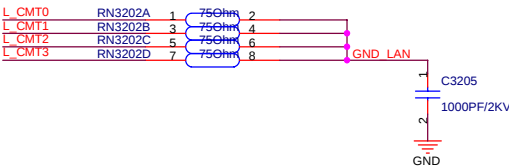
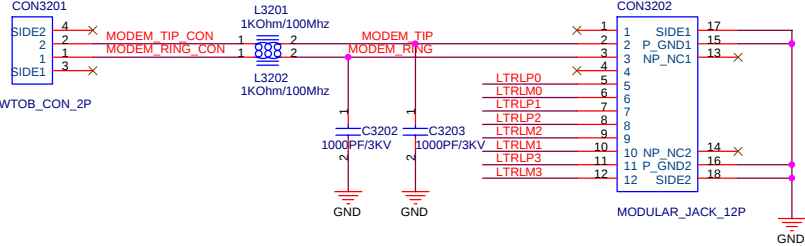
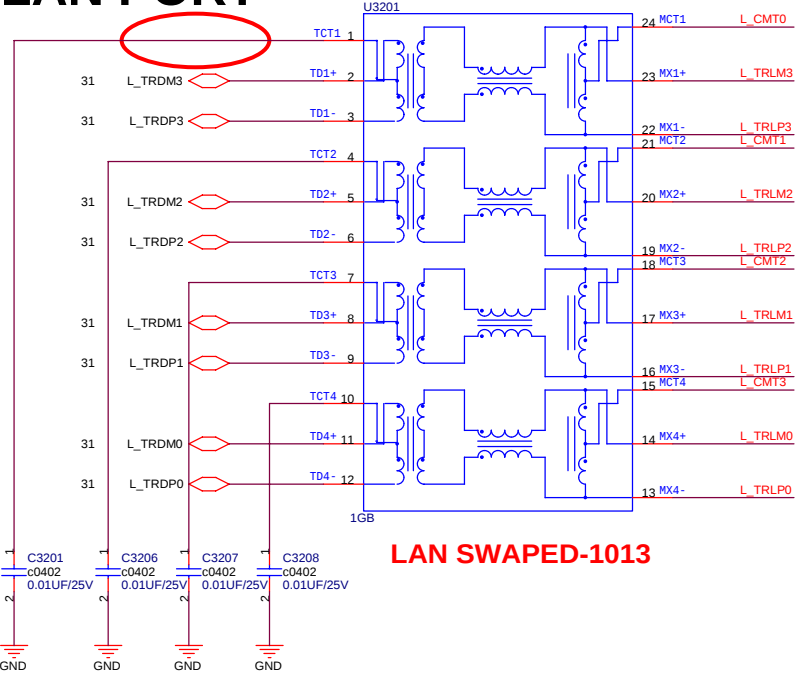
<Variant Name>

ASUS		Title : Audio AMP	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size Custom	Project Name A6Jc	Rev 2.1	
Date: Thursday, January 19, 2006		Sheet 28 of 63	





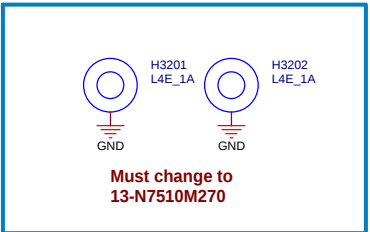
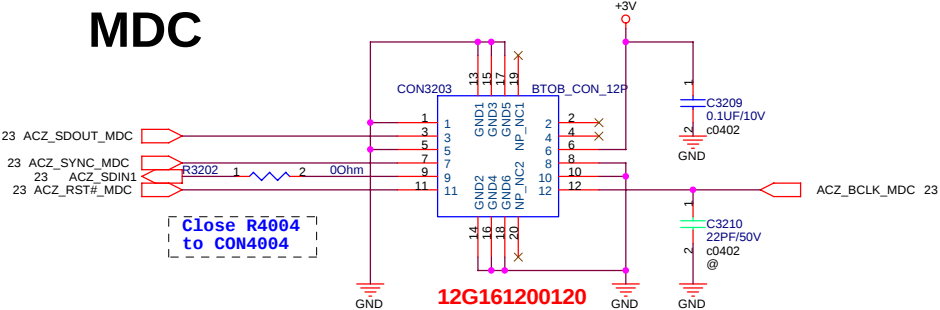
LAN PORT



FOR EMI

L_TRLM2	1	00hm	2	RN3201A	LTRLM2
L_TRLP2	3	00hm	4	RN3201B	LTRLP2
L_TRLM0	5	00hm	6	RN3201C	LTRLM0
L_TRLP0	7	00hm	8	RN3201D	LTRLP0
L_TRLP1	1	00hm	2	RN3203A	LTRLP1
L_TRLM1	3	00hm	4	RN3203B	LTRLM1
L_TRLM3	5	00hm	6	RN3203C	LTRLM3
L_TRLP3	7	00hm	8	RN3203D	LTRLP3

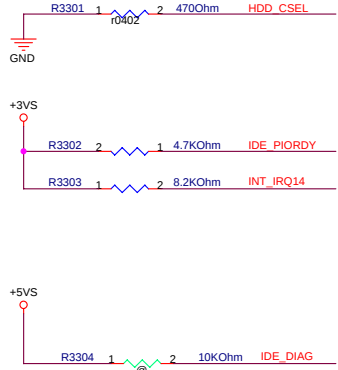
MDC



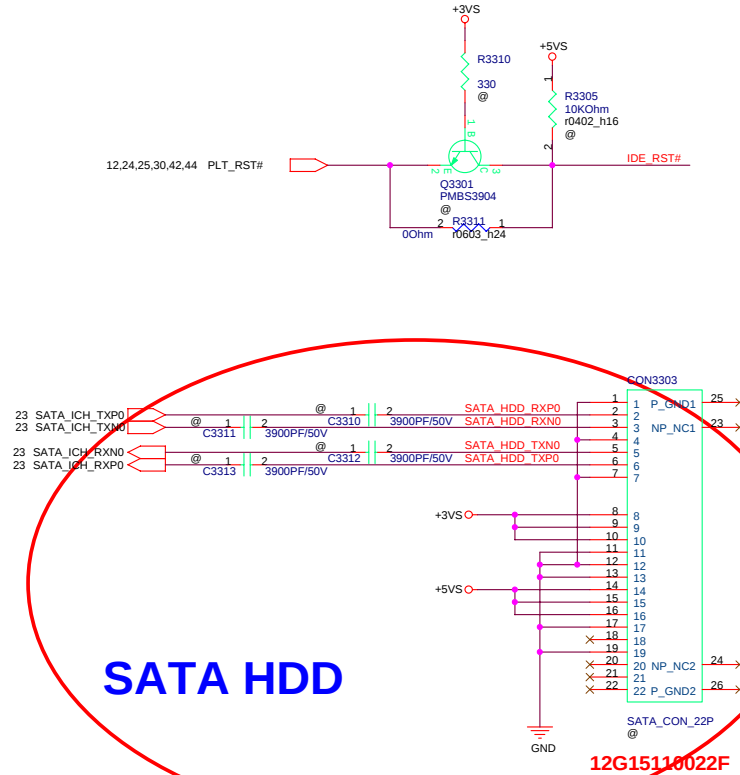
<Variant Name>

ASUS®		Title : RJ11+45,MDC	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	32	of 63

HDD_CSEL : Pull-Down HDD as Master

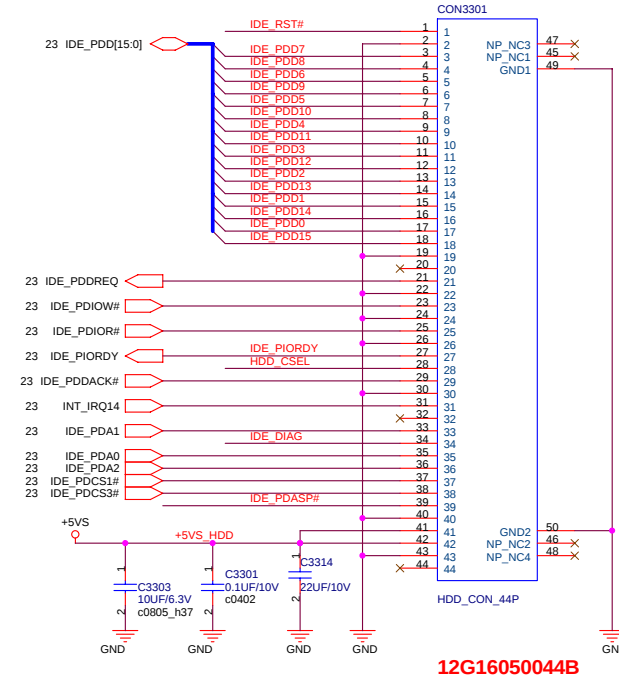


12,24,25,30,42,44 PLT_RST#



SATA HDD

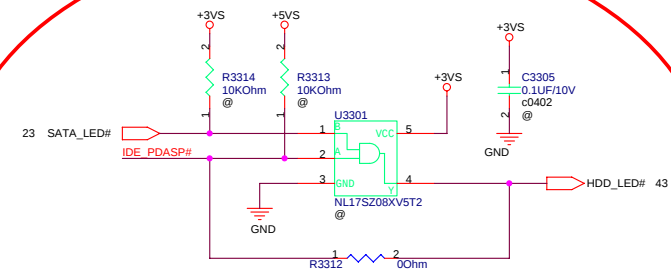
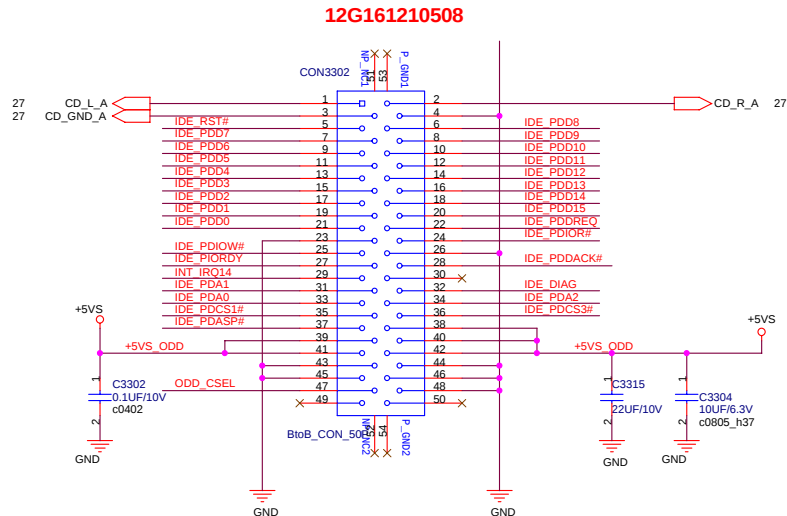
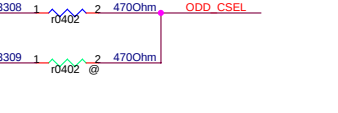
12G15110022F



PATA HDD

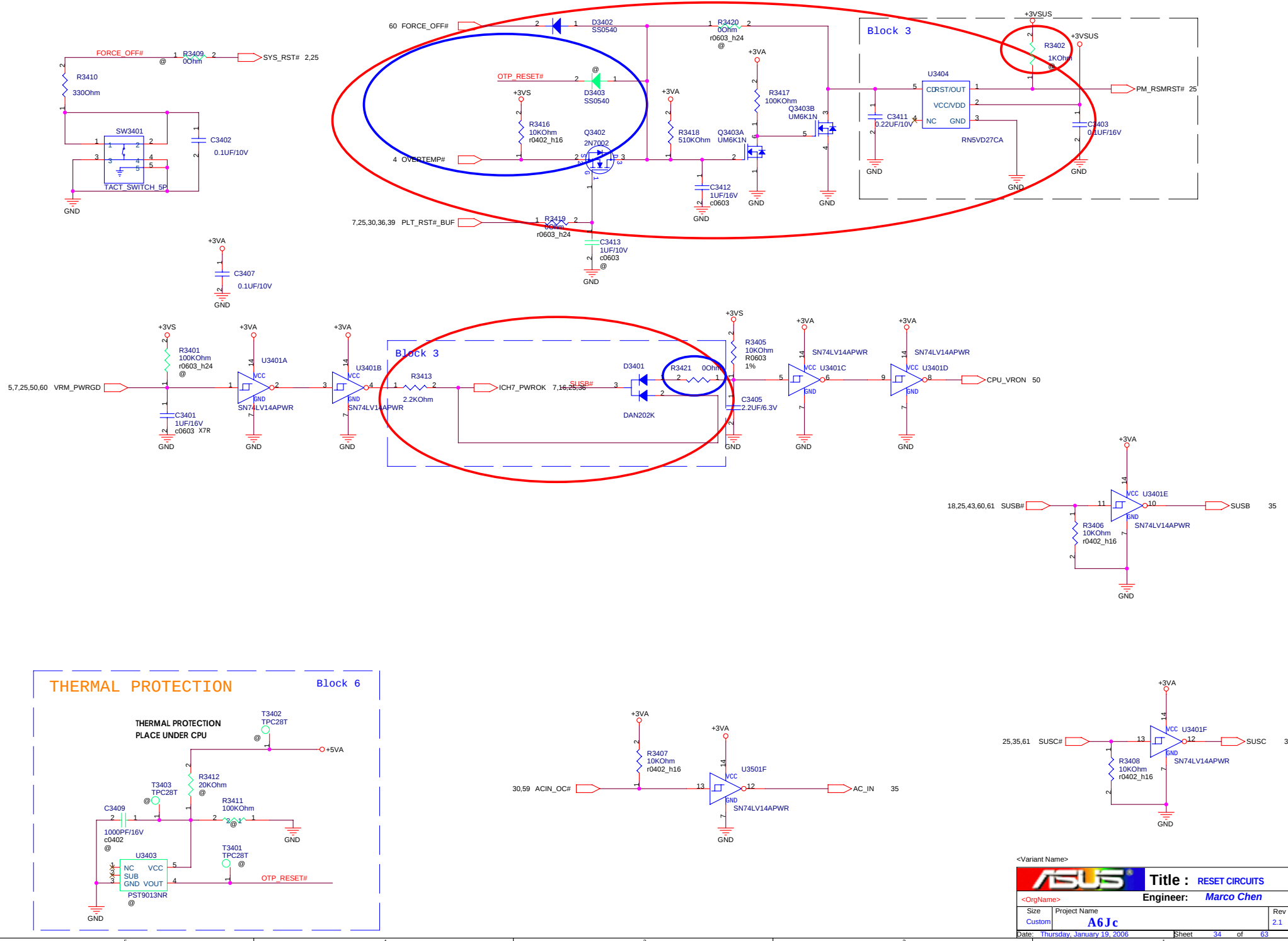
CD-ROM

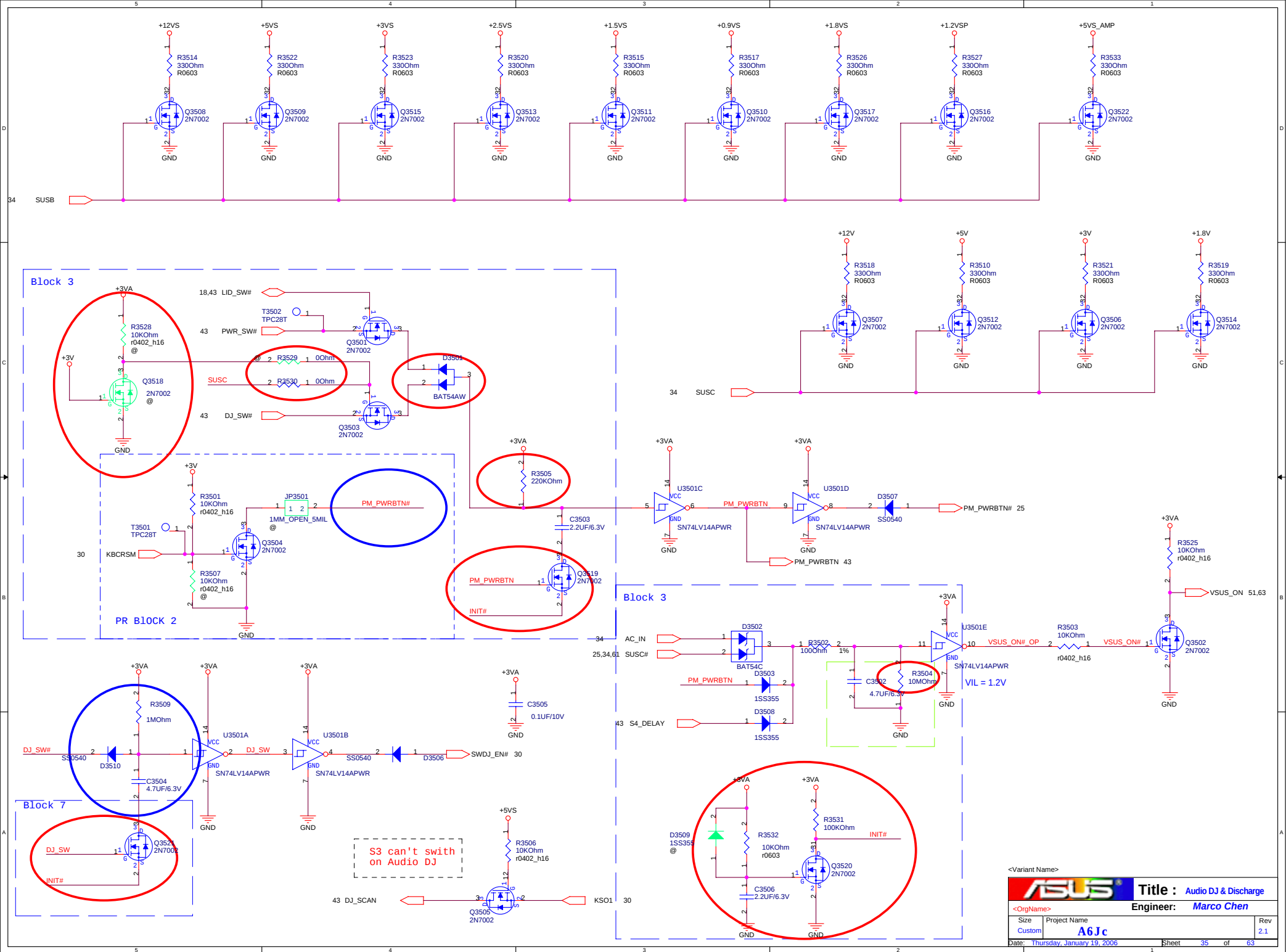
ODD_CSEL : Pull-Up, CDROM as Slave, Pull-Down, CDROM as Master

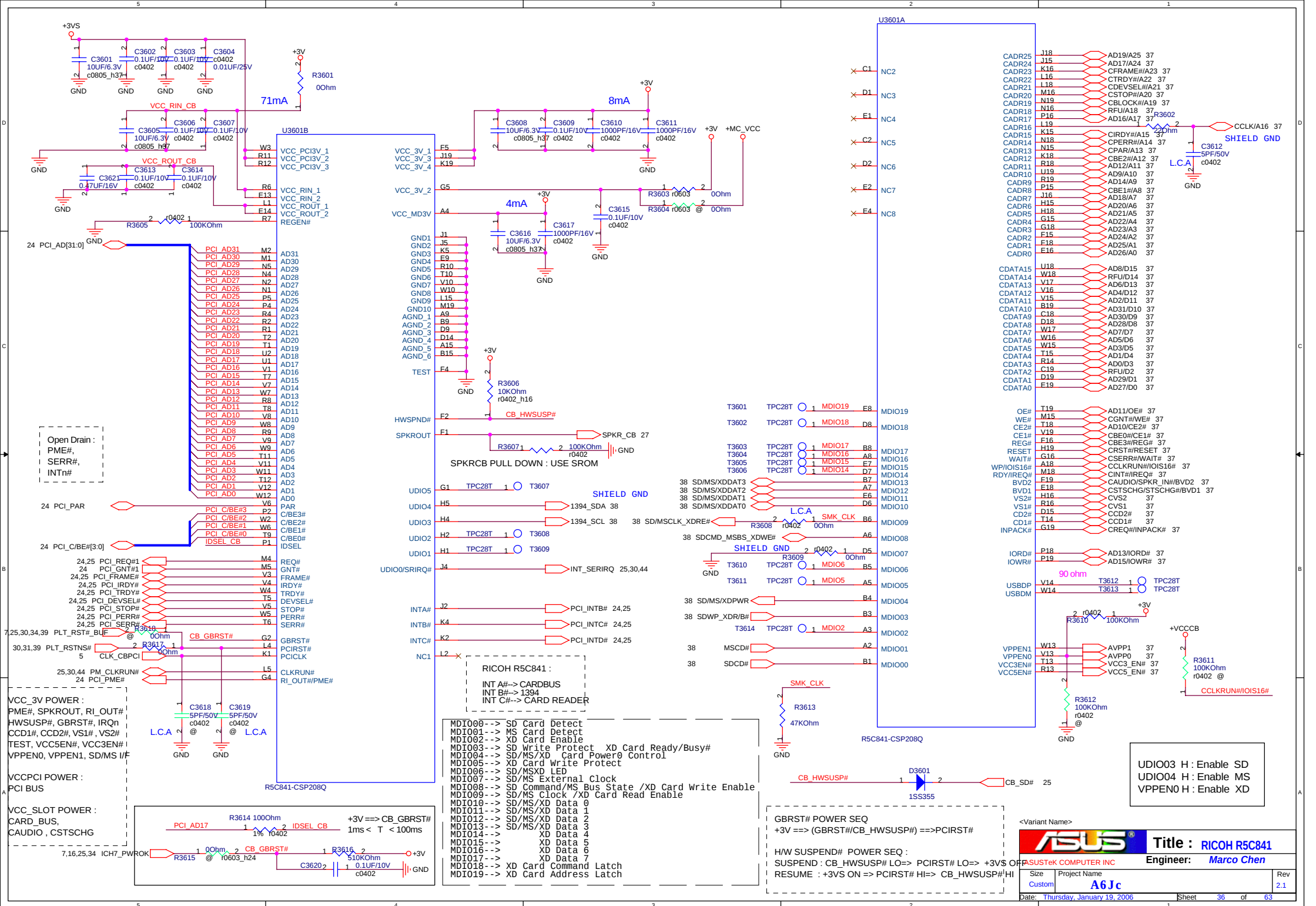


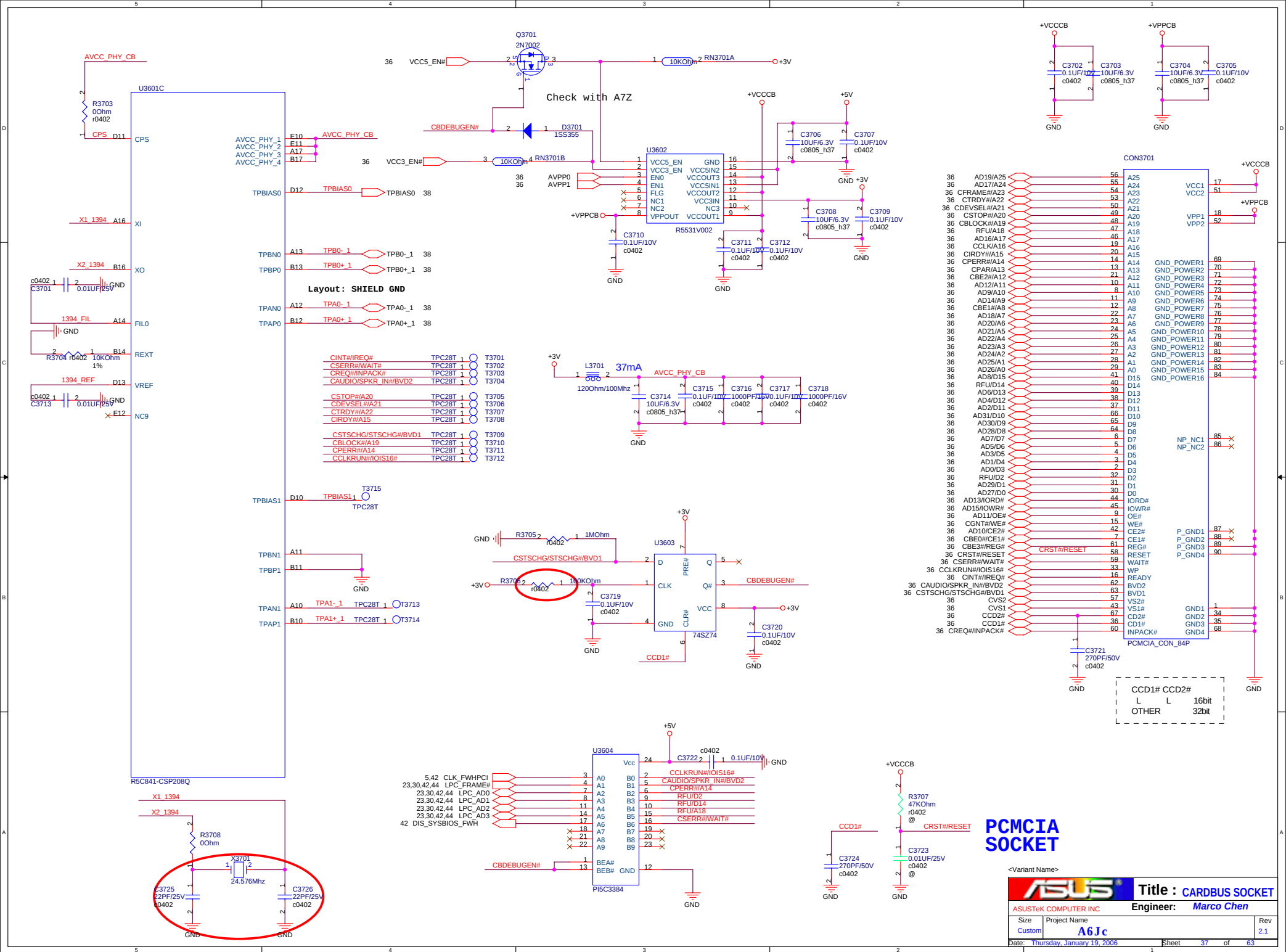
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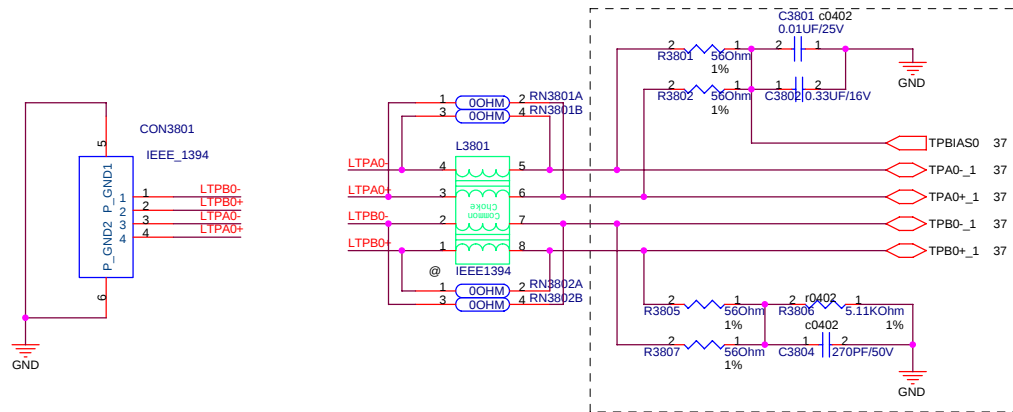
		Title : HDD & CDROM	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size Custom	Project Name A6Jc		Rev 2.1
Date: Thursday, January 19, 2006		Sheet 33	of 63



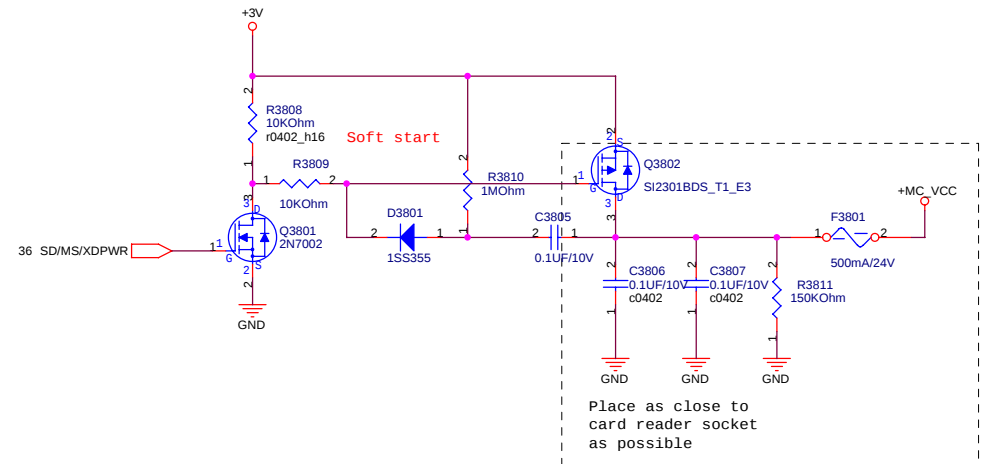
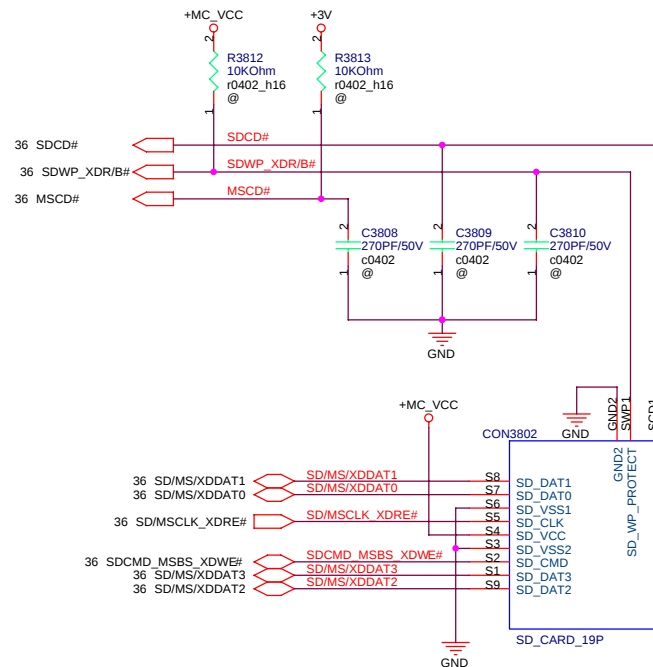
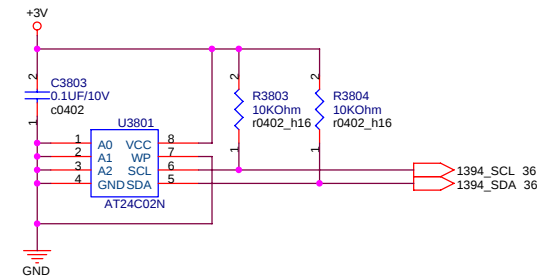








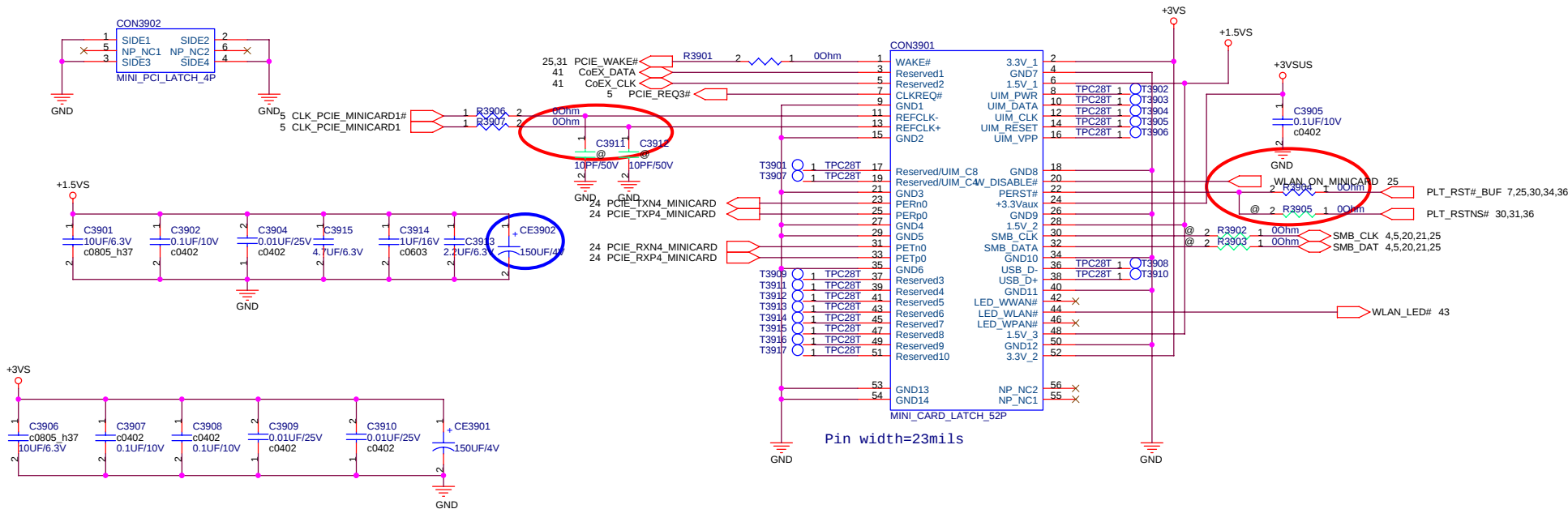
1. CLOSE TO R5C841
2. The area is as compact as possible, length < 10 mm
3. TPA Pair and TPB pair mismatch < 2.5mm
4. No via recommend, maximum is one.
5. Total length < 50 mm
6. Differential impedance is 110+/- 6 ohm
7. TPA Pair trace or TPB pair trace mismatch < 1.25mm



Layout: SHIELD GND

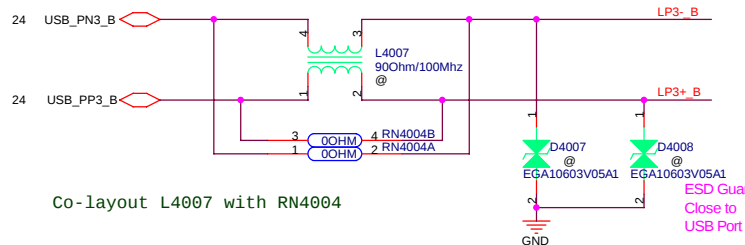
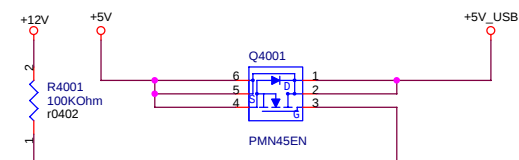
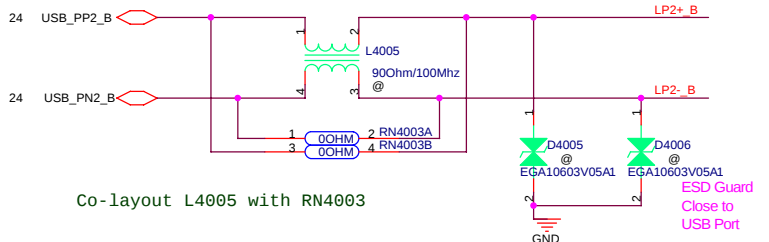
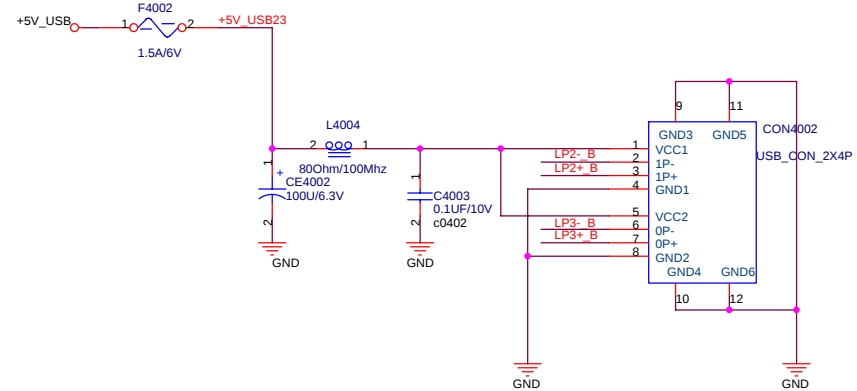
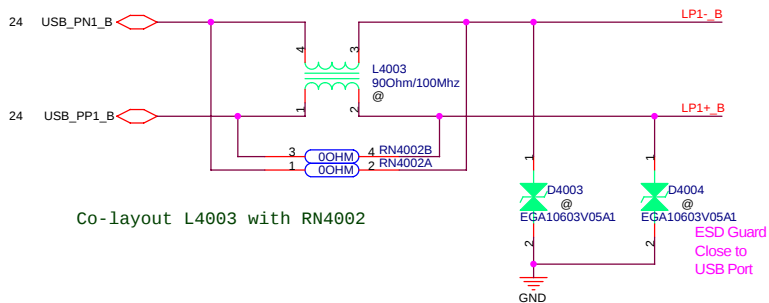
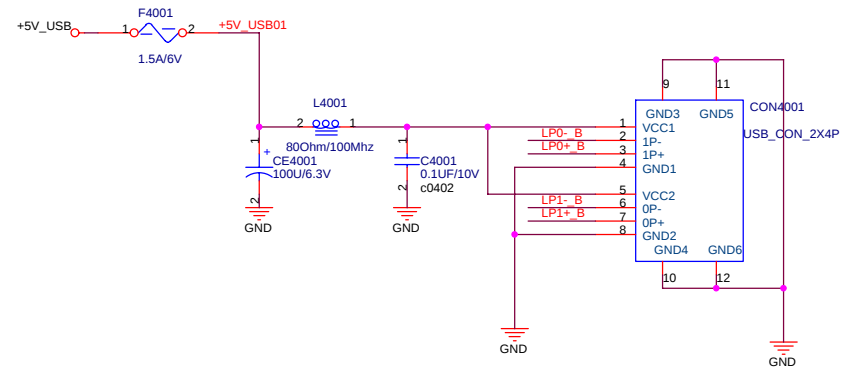
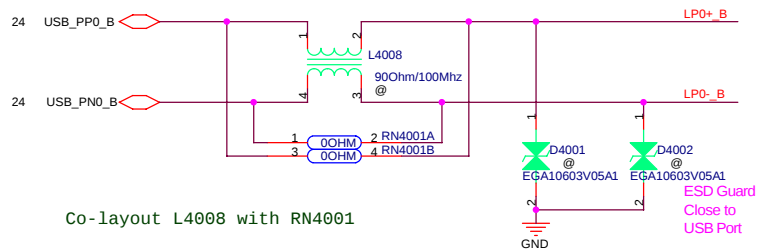
<Variant Name>

ASUS		Title : 1394 & 3 IN 1 CON	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006		Sheet	38 of 63



<Variant Name>

ASUS		Title : MINICARD (Golan)	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	39	of 63

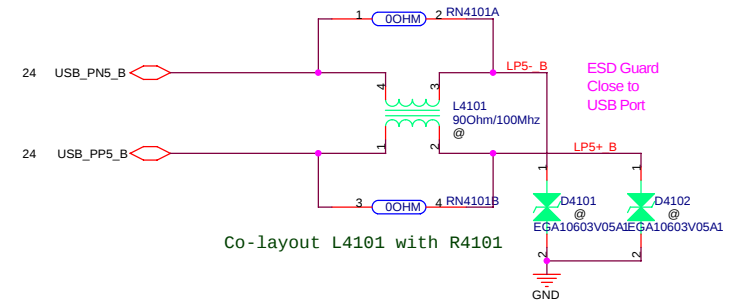
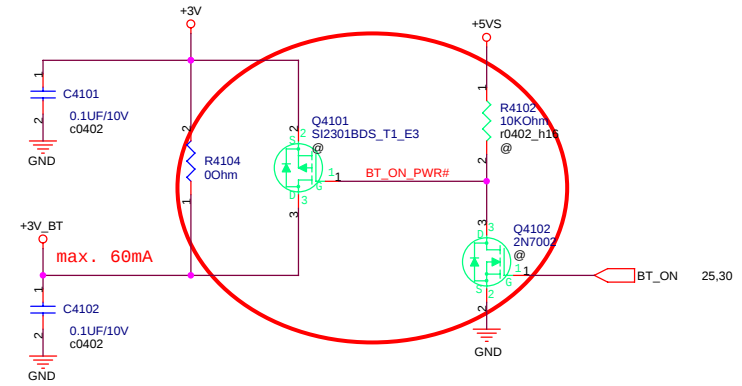


4P2R array resister
co-layout with comman choke

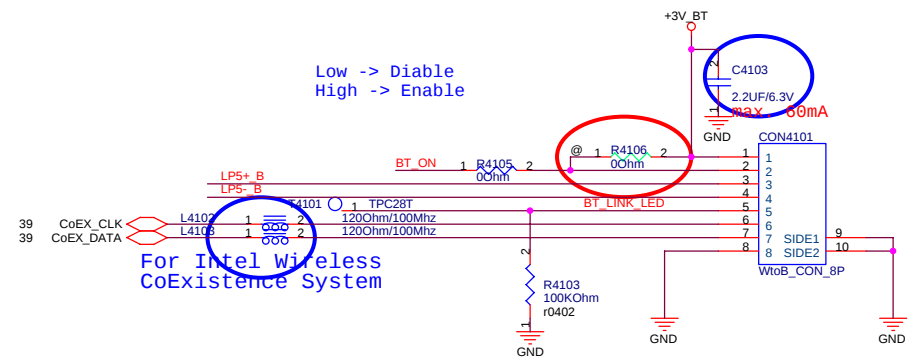
<Variant Name>

ASUS		Title : USB CONN X 4	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	40	of 63

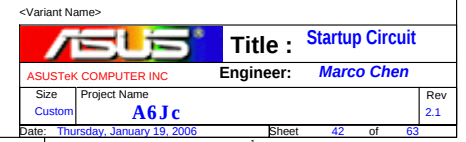
BT ON/OFF Control

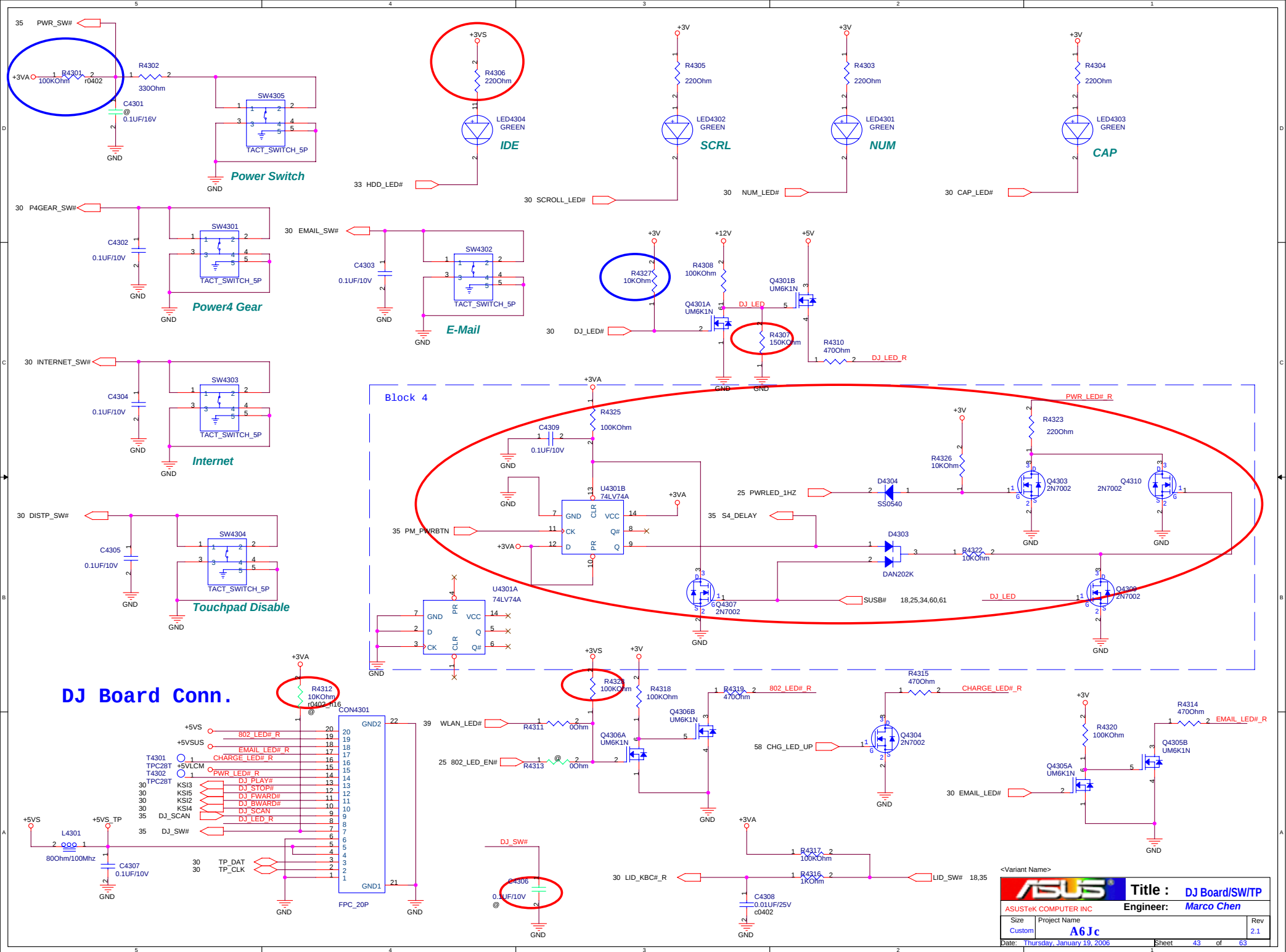


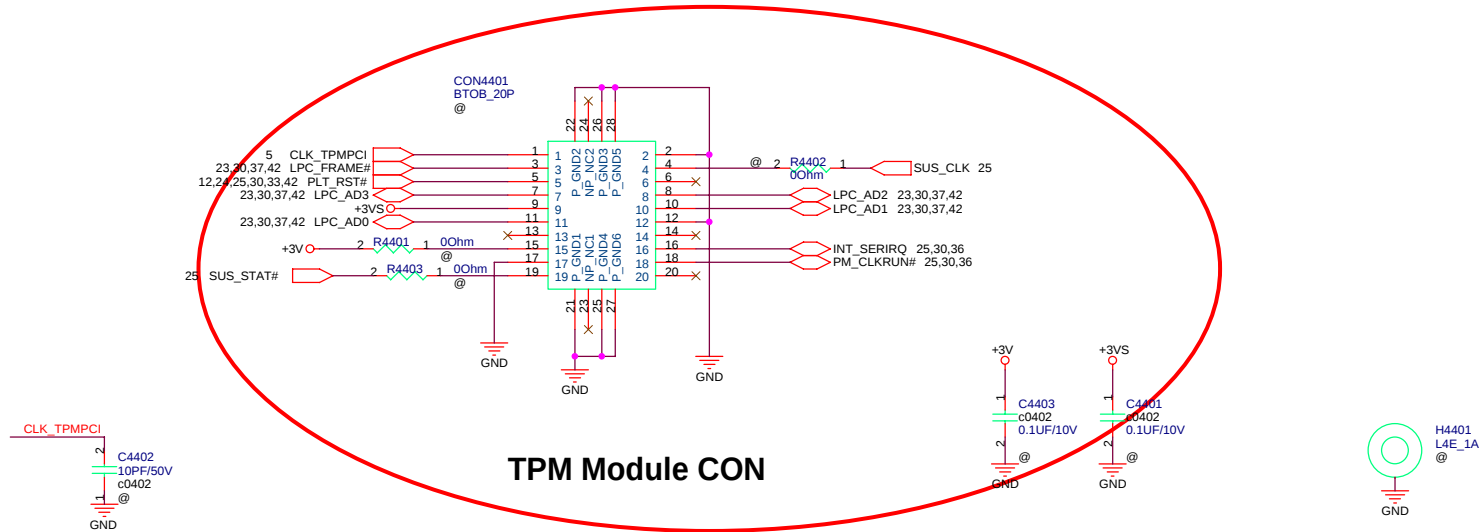
Bluetooth Module



ASUS		Title : Blue Tooth	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	41	of 63



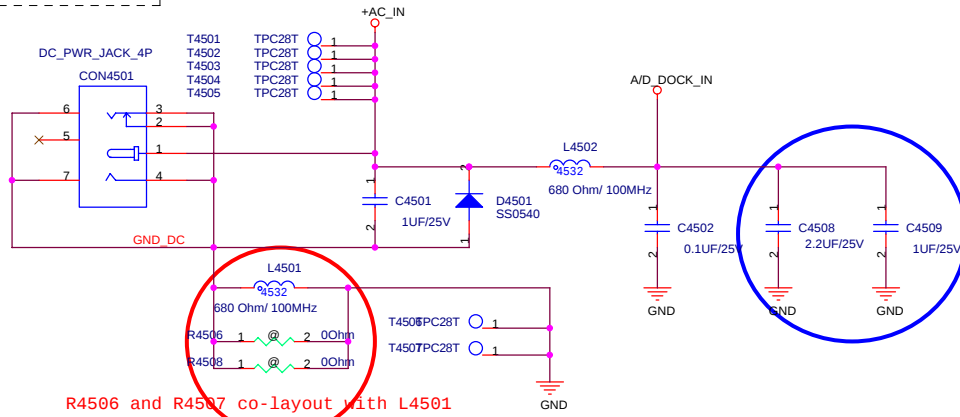




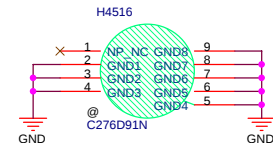
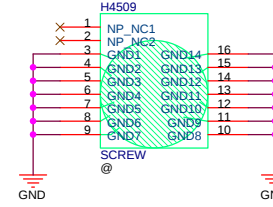
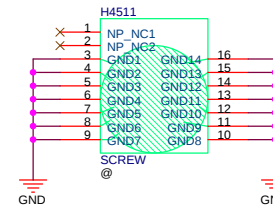
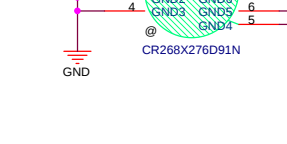
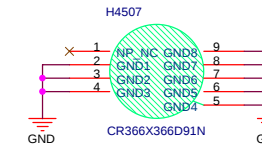
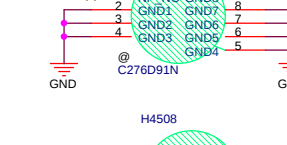
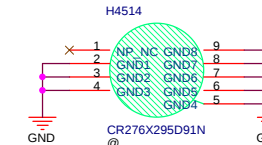
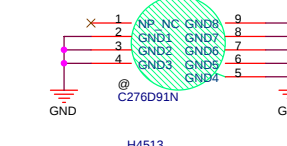
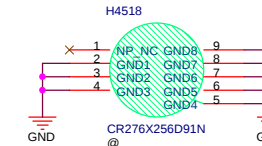
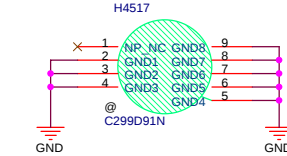
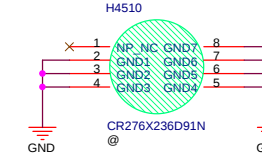
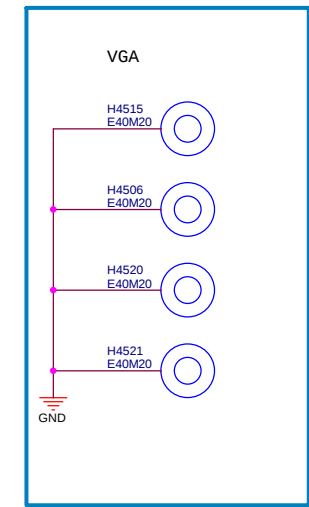
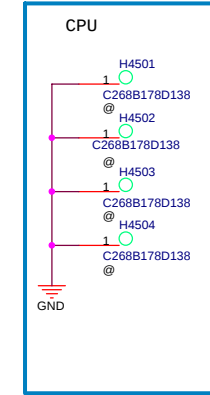
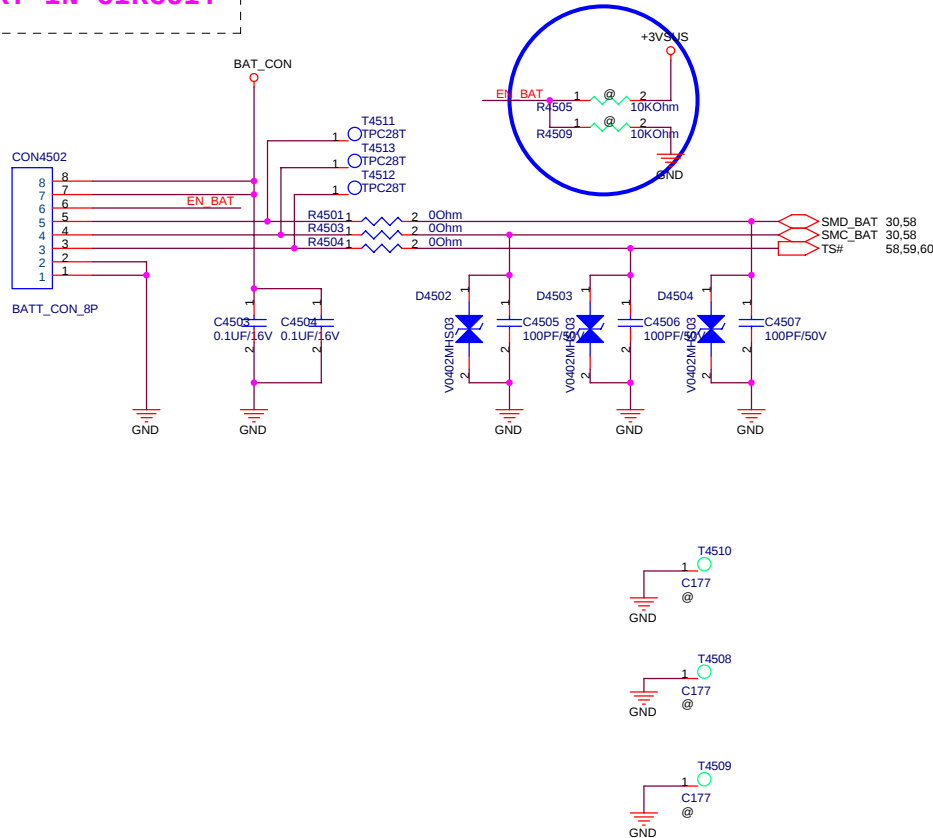
<Variant Name>

ASUS®		Title : TPM	
ASUSTeK COMPUTER INC		Engineer: Marco Chen	
Size	Project Name		Rev
Custom	A6Jc		2.1
Date: Thursday, January 19, 2006	Sheet 44 of 63		

Adaptor IN Circuit



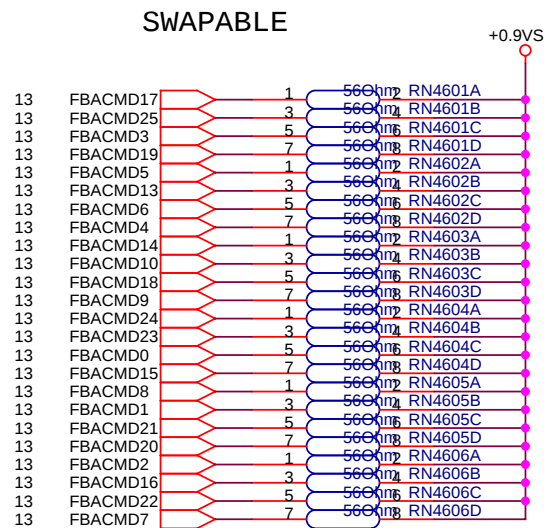
BATTERY IN CIRCUIT



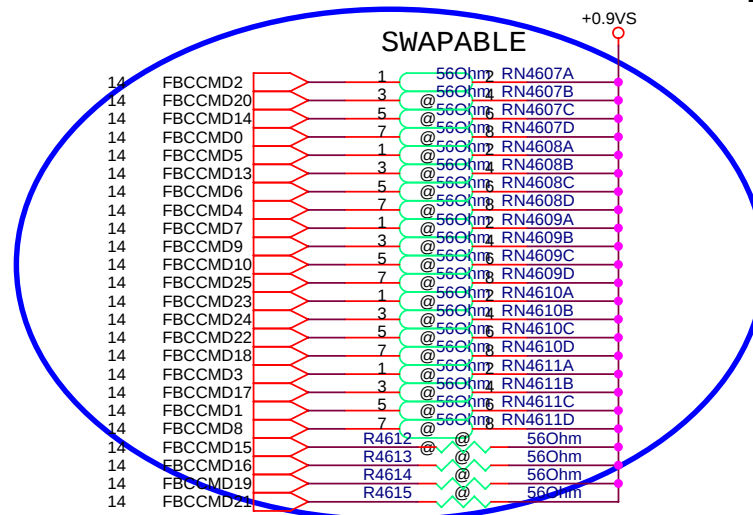
<Variant Name>

ASUS		Title : Power Connector	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
Size	Project Name	Rev	
Custom	A6Jc	2.1	
Date: Thursday, January 19, 2006	Sheet	45	of 63

FBA CMD/ADDR Termination



FBC CMD/ADDR Termination



<Variant Name>

		Title : G73M-Termination	
<OrgName>		Engineer: Charles Lee	
Size	Project Name		Rev
Custom	A6Jc		2.1
Date: Thursday, January 19, 2006		Sheet	46 of 63

Host	SM-Bus Device	SM-Bus Address	Device
ICH7-M	Clock Generator	1101001x (D2)	ICS954310
ICH7-M	SO-DIMM 0	1010000x (A0)	DDR SOCKET1
ICH7-M	SO-DIMM 1	1010001x (A4)	DDR SOCKET2
ICH7-M	Thermal Sensor	0101110x (5C)	ADT7463 (Optinal)

PCI Device	IDSEL#	REQ/GNT#	Interrupts
CARD READER	AD17	1	B
CARDBUS	AD17	1	C
1394	AD17	1	D

R1.0 -> R1.1

1. Page2: Add test points T215 and T216 for H_ADS# and H_CPURST#
2. Page4: Modify FAN solution from DA to PWM and change R-C delay timing.
 - A. Mount R416 and DNI R415
 - B. Change C404 to 1uF
3. Page4: Connect +3VS_FAN(R419*3.3K ohm and R420*2.2K ohm 分壓 from +V5S_FAN) to U401.3 because FAN_DA level is 3V and FAN_PWM# is open-drain, change pull-up to +3VS and U401.3 level shift from 5V to 3V
4. Page4: Add pull-down resistor R418*10M ohm to protect noise when power-on
5. Page5: Add (R579*33 ohm and C529*10pF) for TPM PCI 33MHz clock
6. Page5: Change R531 from 10 ohm to 22ohm to eliminate swing.
7. Page5: DNI R510 to disable ITP enable.
8. Page7: Delete R715 because it duplicate with R529.
9. Page9: Change L905 to P/N:09G012030000 and L905 to P/N:09G013120409 because +1.5VS_PCIE consume about 1.3A and +1.5VS_3GPLL consume 200mA only.
10. Page13: VGA_GPI05 add pull-up 10K ohm to +3VS for ATI recommendation.
11. Page13: DNI R1320 and mount R1321 to change back light enable from DC level to PWM and meet VBIOS support.
12. Page13: Add R1343*0 ohm for reserving bead to ground.
13. Page15: Change L1504.2 to connect from +VGA_VCORE to +1.2VSP for ATI recommendation.
14. Page15: Change bead L1506 from 1200hm/100Mhz to 300hm/100Mhz type.
15. Page19: Add bead L1913 between TV_GND and GND.
16. Page23: Change High Definition damping resistors*R2312, R2314, R2316, R2318, R2320, R2322, R2324, R2325 from 22 ohm to 39 ohm for reducing reflection.
17. Page29: Add Line-in solution, please commt Black 2.
18. Page31, 32: Change LAN chip from Marvell 88E8053 to Realtek RTL8111B.
19. Page34: Add Q3401 and R3414 to replace U3402B.
20. Page34,35: Modify reset circuits to meet Intel specification, please commt Black 3.
21. Page35,43 : DNI R4312 and change R3509 from 4.7M ohm to 2.2 M ohm to short SWDJ_EN# detected to 2secends for BIOS requirement and add INIT# solution(please comment Block 7).
22. Page37: Change R3706 from 10K ohm to 100K ohm to enlarge R-C delay time.
23. Page39: Reserve R3905 to PLT_RSTNS# Wire-Or with PLT_RST#_BUF.
24. Page41: Short CON4101.1 and CON4101.2 and delete R4105, R4104, and C4103 because no timing issue between power and enable signal.
25. Page42: Delete D4201 and DNI R4202 because no power loss issue exist.
26. Page43: Modify S4 stretch circuits, please comment Block 4.
27. Page44: Add TPM connector.
28. Page45: Add C4508, C4509, R4506 and R4507 for EMI requirment.
29. Page42: Change CON4202.1 and CON4202.3 power from +3VSUS to +3V.
30. Page18: Change L1806.2 power from AC_BAT_SYS to AC_BAT_SYS_CPU for EMI requirement.
31. Page7: Change from VRM_PWRGD to ICH7_PWROK to enable MCH_PWROK for Intel requirement(Mount R721 and DNI R722).

32. Page23,34: Change thermal-trip solution.

- A. Mount R2315 and DNI R4507
- B. Remove the circuits.(please comment Block 5)
- C. Mount thermal protection circuits.(please comment Block 6)

33. Page5, 23, 37: Change capacitor values for TXC recommendations(C513,C514 from 33pF to 27pF, C2302, C2304 from 12pF to 22pF ,Change X3701 to 07G010S22450*30 ppm and C3725 and C3726 to 22pf).

34. Page15, 47: Add Back Bias circuits for ATI recommendations.

35. Page5, 23, 33: Add SATA circuits for OEM requirement.

36. Page12: Remove R1205 for ATI recommendations.

37. Page39: Reserve R-C to tune waveform quanlity.(R3906,R3907,C3911,C3912)

38. Page41: Reserve R4104, R4105, R4106 to modify enable blue tooth solution.

R1.1 -> R2.0

1. Page4, 34: Add power limit solution and change thermal protection solution.

- A. Add R421*0 ohm and connect to H_PROCHOT_S#
- B. DNI R417*0 ohm
- C. Add R422*0 ohm and connect to OVERTEMP# that is wire-or with FORCE_OFF#.
- D. DNI OTP solution.

2. Page15: Add BBIAS_CNTL pull-down resistor R1508*10K ohm to GND.

3. Page19: Modify parts (D1912 and F1901).

4. Page24: Add 3 pcs decoupling CAPS(C2410, C2411, C2412) to short return path because PCI Bus(IN1) reference +1.8VS(Vcc).

5. Page25, 44: Add BT_LED solution to co-layout with Scroll Lock for Epson requirement.

6. Page27: Change R2704 from 0 ohm to 150 ohm.

7. Page27: Change R2707 from 47K ohm to 332K ohm.

8. Page27, 28: Add MUTE_POP# solution for Epson requirements. Please comment PR BLOCK 1.

9. Page30: Add LID switch solution.

- A. Change BAT_SEL# push-pull resistor from +3V to GND.
- B. DNI Q3002*2N7002.

10. Page31: Change LAN chip reset signal from PLT_RSTNS# to PCI_RST#. (Mount R3107 and DNI R3106).

11. Page35: Change KBCRSM solution to connect to PM_PWRBTN# directly, please comment PR BLOCK 2.

12. Page36: Change CARDBUS chip reset signal from PLT_RST#_BUF to PLT_RST#. (Mount R3618 and DNI R3617).

13. Page39: Add WLAN_LED# pull-high resistor R3908*100K ohm to solve LED was lighted when miniCARD was un-plug in.

<Variant Name>

		Title : History (1)	
ASUSTek COMPUTER INC		Engineer: Marco Chen	
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14. Page40: Remove L4003, L4005, L4007, L4008 for EMI requirement.
15. Page43: Mount R4301*100K ohm to avoid PWR_SW# is floating.
16. Page43: Mount R4327*10K ohm to fix DJ_LED light soon issue when power on.

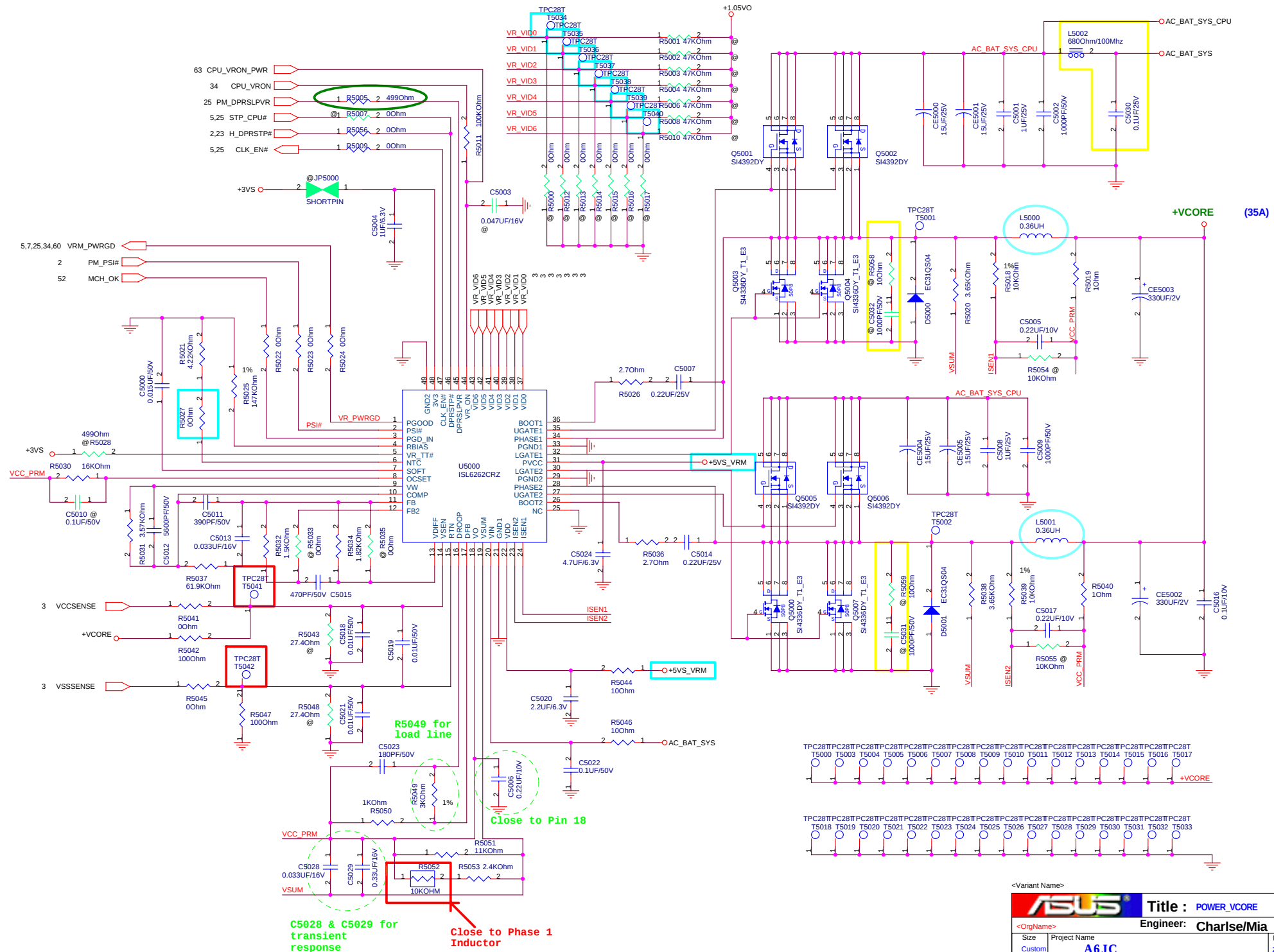
VGA NV G72M-V R1.0 -> R1.1

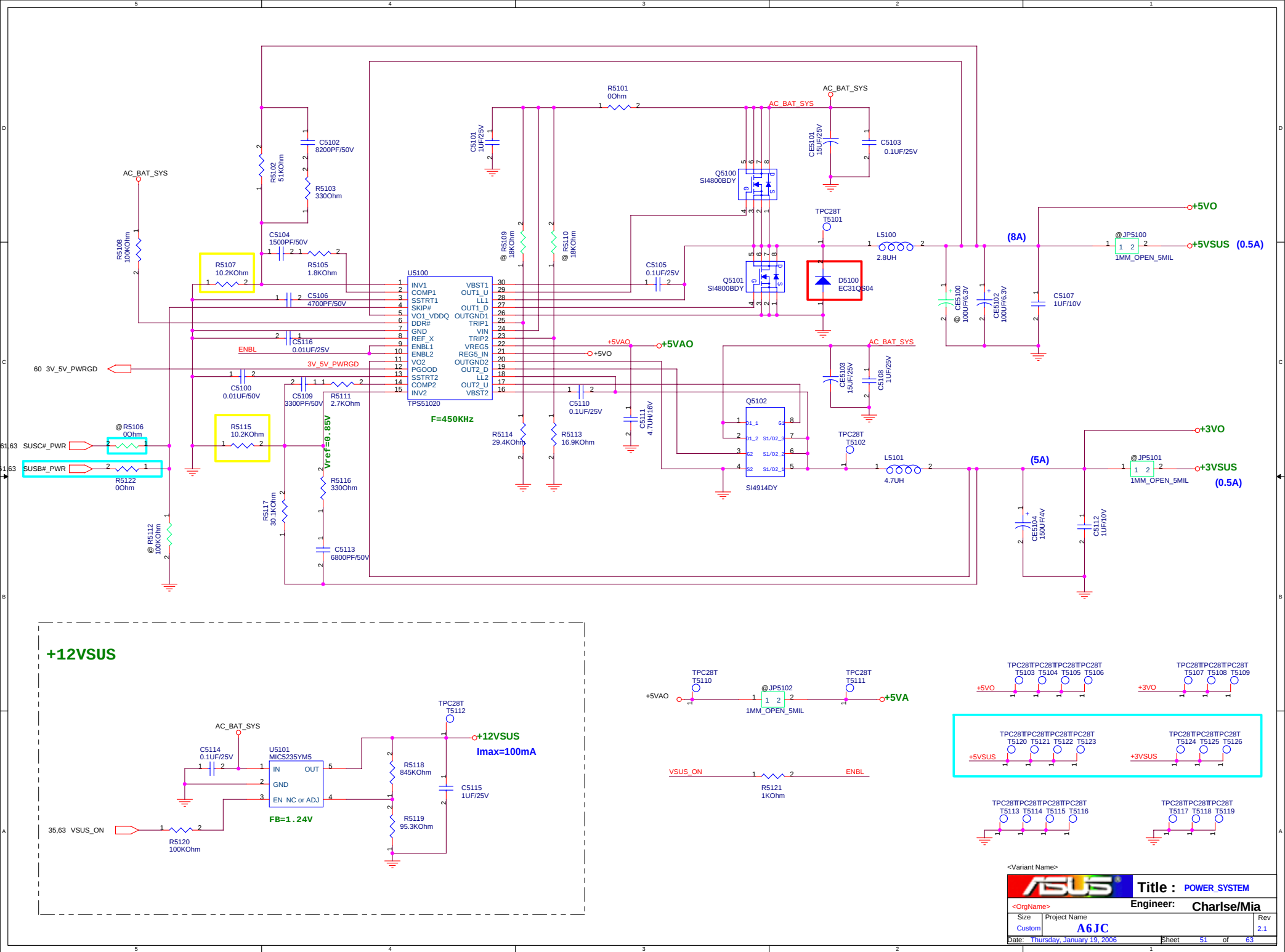
1. Page15: Change R1507 from 121 ohm to 0 ohm and Remove R1511 for SSC 3.3V requirment.
2. Page13: Change VRAM CLK Terminators R1303, R1304 from 120 ohm to 100 ohm for NV recommendation.
3. Page14: Change VRAM CLK Terminators R1402, R1403 from 120 ohm to 100 ohm for NV recommendation.
4. Page16: Change DACX_RSET R1605, R1607 to 124 ohm and remove R1604, R1606 for NV recommendation.
5. Page17: Mount 3GIO_PADCFG R1720 and DNI R1721 for NV recommendation.
6. Page17: Change RN1701 from 4R8P 0603 to 4R8P 0402 for BOM issue
7. Page19: Change D1913 from LM385M3 to BAV99.
8. Page19: Change L1901, L1905, L1906 to 180NH.
9. Page43: DJ_LED# Pull high to +3V via R4327 10Kohm.
10. Page35: Add D3509 (DNI) in parallel to R3532 for C3506 discharge path.
11. Page34: Change U3404 RN5VD to CMOS Topology and R3402(DNI).
12. Page04: Change R420 from 22K ohm to 10K ohm and change R419 from 33K ohm to 20K ohm for Volt divide.
13. Page43 :DNI C4306.
14. Page05: Change R519,R546 from 1 ohm to 2.7 ohm.
15. Page27: Change CE2701 from 47uF to 22uF and rename to C2727.
16. Page32: Change CE3301, CE3302 from 47uF to 22uF and rename to C3314, C3315.
17. Page17: Add U3003, Q3008(DNI) for 4S1P Battery detected.
18. Page23: Change X2301 to PN:07G010303270.
19. Page31: Change X3101 to PN:07G010S22500 for cost issue.
20. Page37: Change con3701 footprint to "nb_pcmcia_84p_6hold_a3n_lf2" for factory issue.
21. Page45: Change H4506, H4515, H4520, H4521 footprint to "nb_smt_nut_e40m20_lf2" for factory issue.
22. Page43: WLAN_LED# Pull-high to +3VS via R4328.
23. Page29: Change U2902 to PN 06G010147010.
24. Page14: Add R1415 and DNI L1403 for NV recommendation.
25. Page28: Change R2832 from 10K to 100K and R2806(DNI).
26. Page27: Change R2704 from 0 ohm to 100ohm.
27. Page35: Change R3509 from 2.2M ohm to 1Mohm and C3504 change from 1uF to 4.7uF.
28. Page31: Change R3106 DNI and R3107 stuff .
29. Page27: Change R2707 from 47k ohm to 332K ohm.
30. Page43:Mount R4301
31. Page35: Modify KBCRSM Circuit.
32. Page30:Add D3003 and C3007.

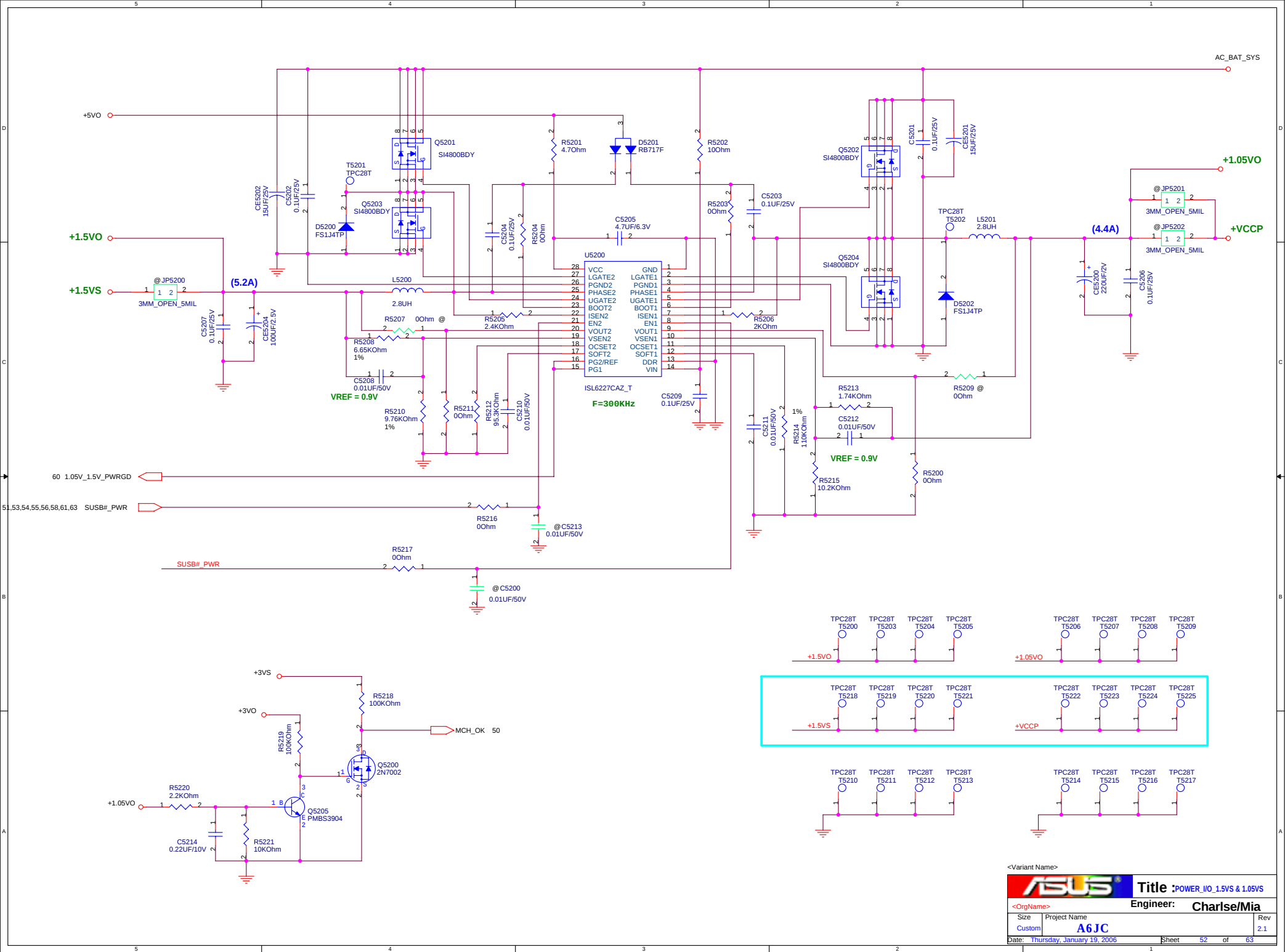
VGA NV G72M-V R1.1 -> R2.0

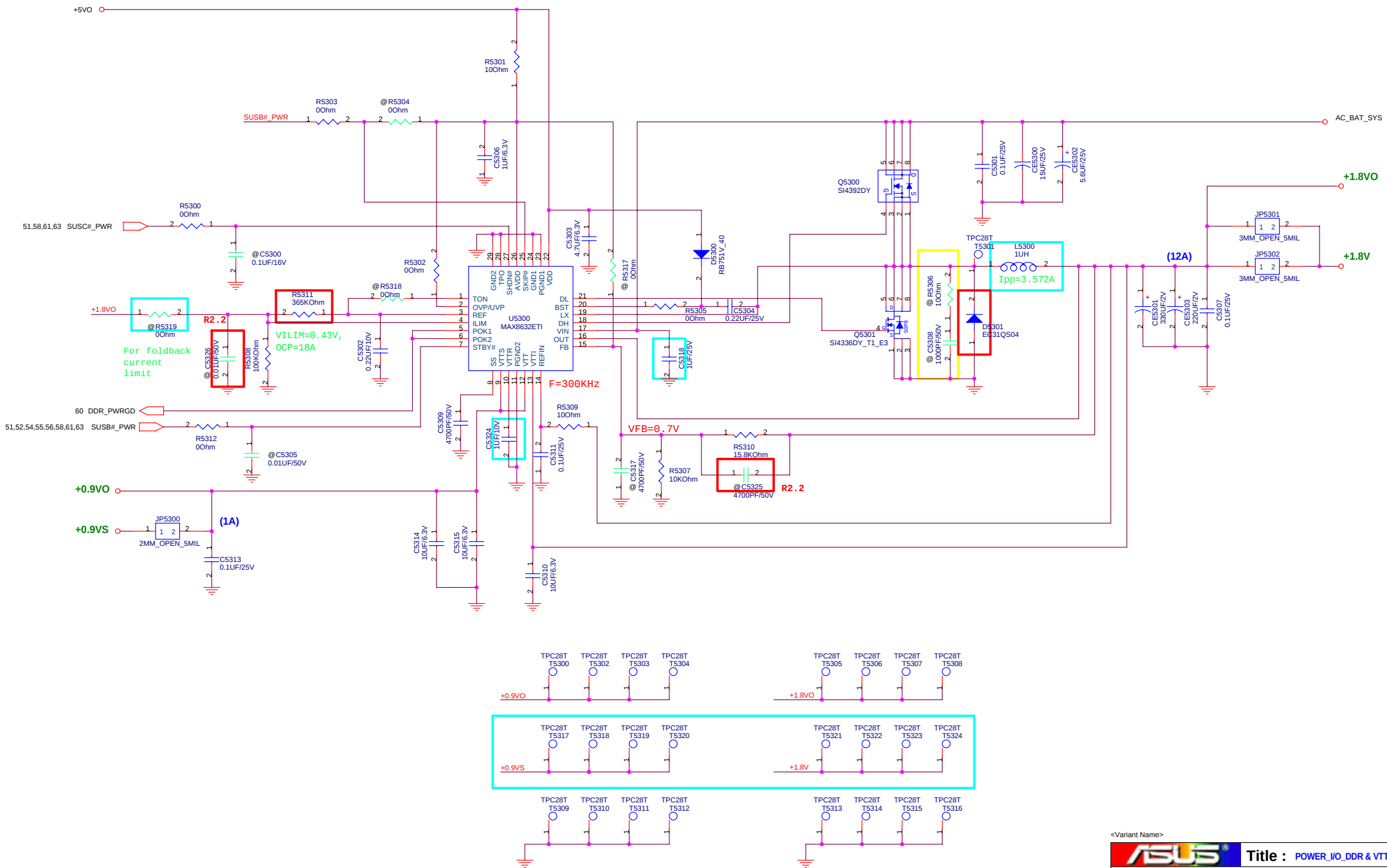
1. Page19: Change L1901, L1905, L1906 to 09G013120409 120ohm/100MHZ.
2. Page31: Change C3133,C3134 from 22PF to 27PF.
3. Page46: Change ChipResistor RN4607~RN4612 to Single Resistor R4607 ~ R4630.
4. Page45: Change C4509 from 10uF to 2.2uf.
5. Page19: Change R1910 from 33Kohm to 47Kohm for BOM reduction.
6. Page15: Change R1501 from 71.5ohm to 81.6ohm for BOM reduction.
7. Page25: Add R2550 ,R 2553, R2555 for BT_ON.
8. Page14: Mount R1414 for NV recommendation.

C2827	MLCC 2.2UF/10V(0603)Y5V+80-20%	-->	MLCC 2.2UF/6.3V(0603)X5R 10%
C3007	CAP 2.2UF/6.3V(0603) Y5V (225)	-->	MLCC 2.2UF/6.3V(0603)X5R 10%
C3503	MLCC 2.2UF/6.3V(0603)Y5V+80-20	-->	MLCC 2.2UF/6.3V(0603)X5R 10%
C3506	MLCC 2.2UF/6.3V(0603)Y5V+80-20	-->	MLCC 2.2UF/6.3V(0603)X5R 10%
C3502	MLCC 4.7UF/6.3V(0805) X5R 20%	-->	MLCC 4.7U/6.3V(0805) X7R 10%
C3405	MLCC 2.2UF/6.3V(0603)X5R 10%	不變	
C3411	MLCC 0.22UF/10V(0603)X7R 10%	不變	
C3504	MLCC 4.7UF/6.3V(0603)X5R 10%	不變	

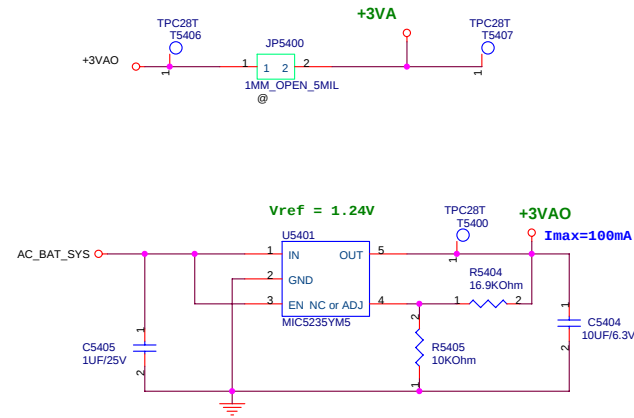




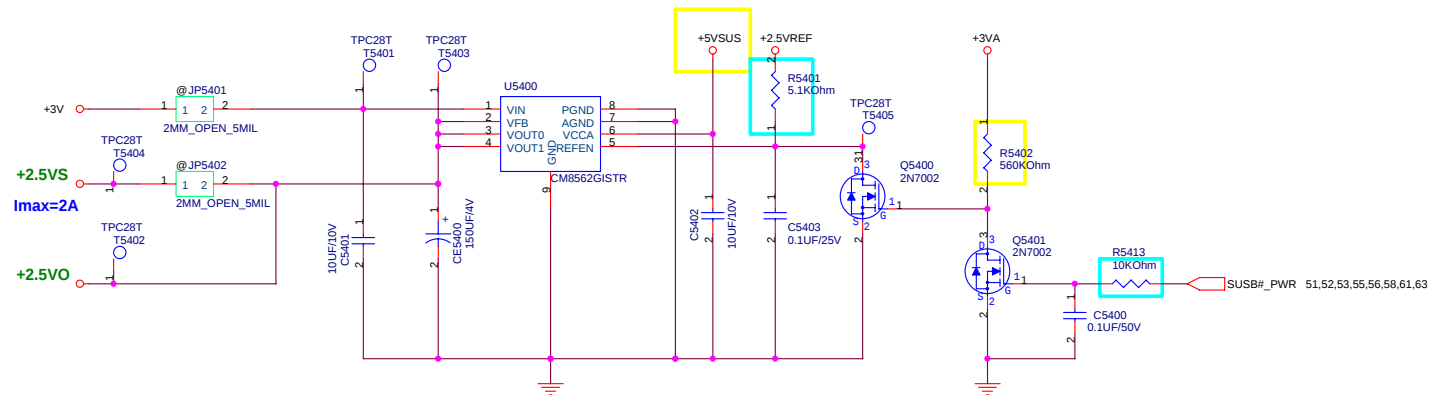




+3VAO

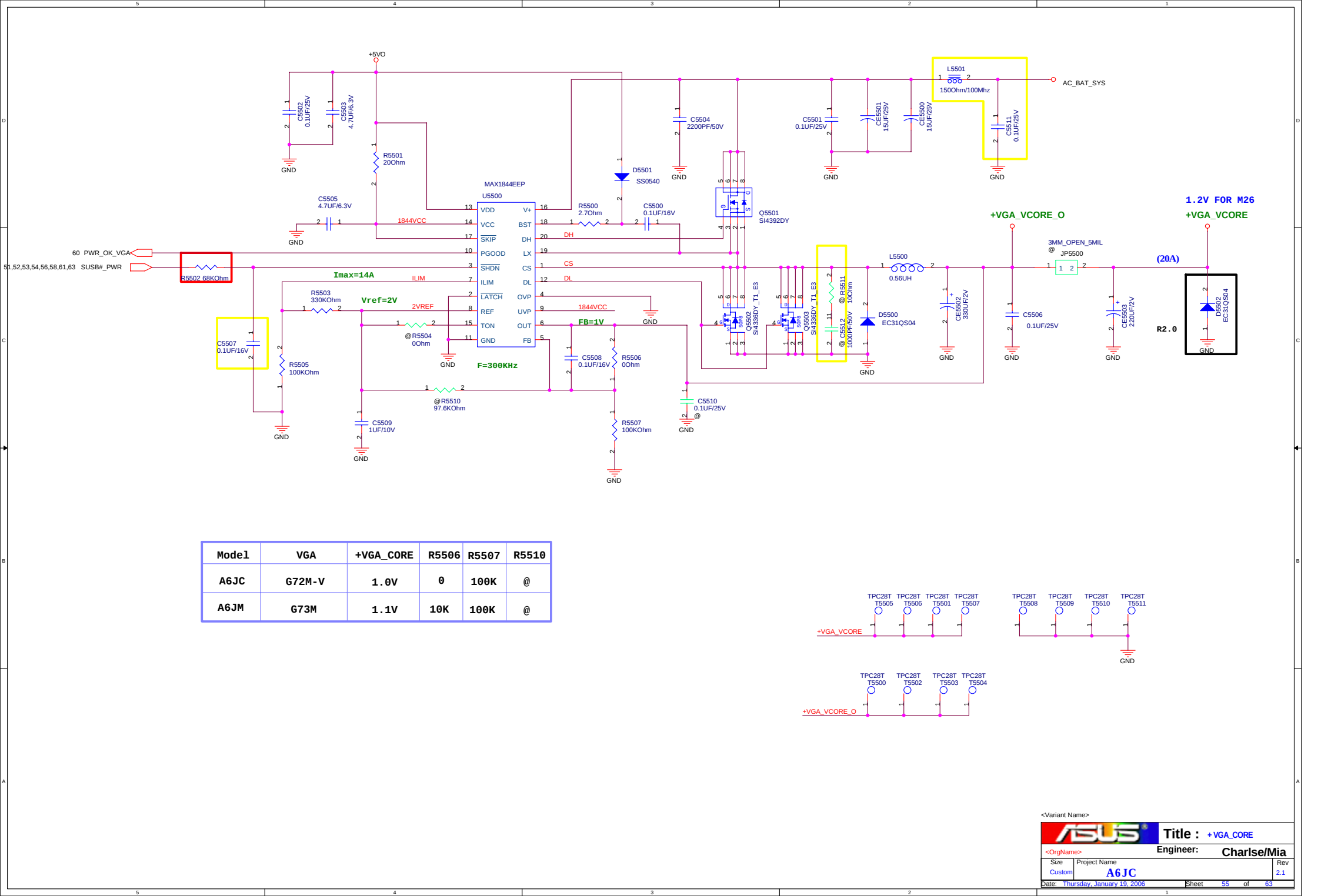


+2.5VS



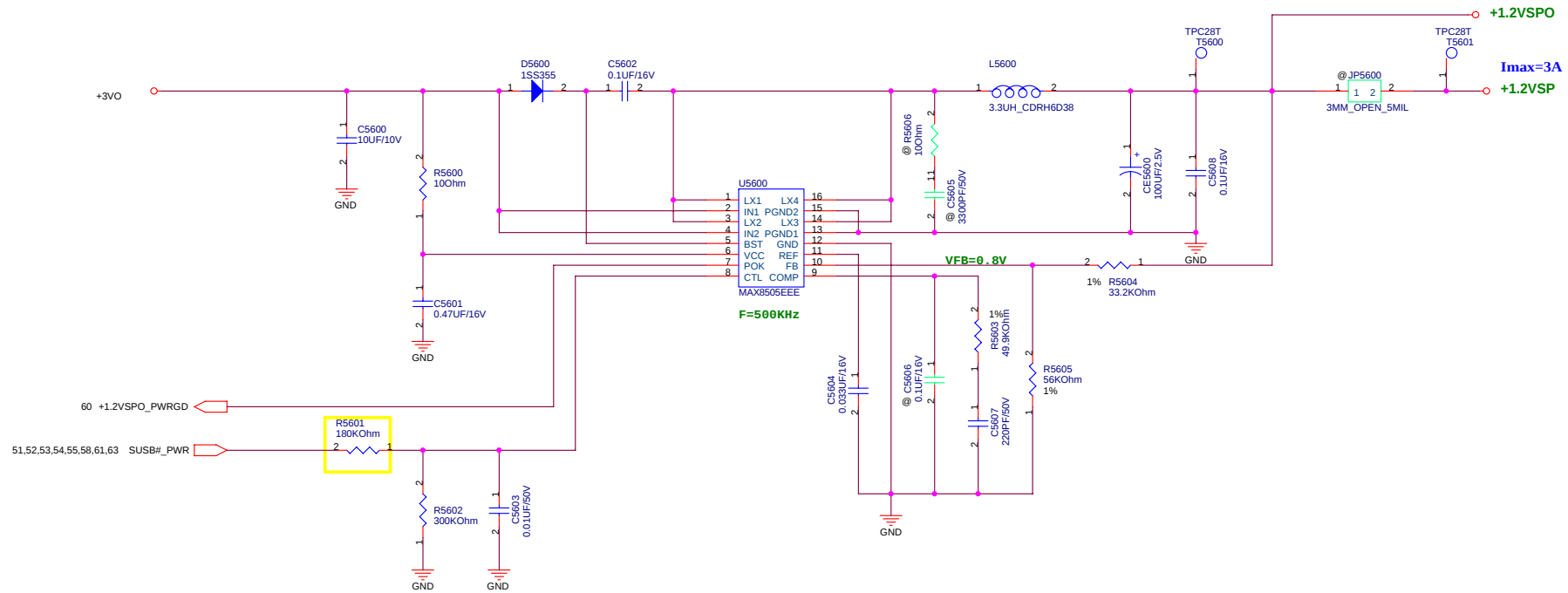
<Variant Name>

		Title : POWER_I/O_+3VA & +2.5V	
<OrgName>		Engineer: Charlse/Mia	
Size	Project Name	Rev	
Custom	A6JC	2.1	
Date: Thursday, January 19, 2006		Sheet	54 of 63



Model	VGA	+VGA_CORE	R5506	R5507	R5510
A6JC	G72M-V	1.0V	0	100K	@
A6JM	G73M	1.1V	10K	100K	@

+1.2VSP



<Variant Name>



Title : POWER_VGA_+1.2VSP

<OrgName>

Engineer: Charlse/Mia

Size
Custom

Project Name
A6JC

Rev
2.1

Date: Thursday, January 19, 2006

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- ->3.42A

45,59,60 A/D_DOCK_IN

BATSEL_2P# = "H" (1P)			
BAT capacity	R5712	VICTL(V)	ICH6(A)
2000MAH	41.2K	1.8976	1.39
2200MAH	52.3K	2.0989	1.537
2400MAH	66.5K	2.2918	1.679
2600MAH	86.6K	2.4871	1.822

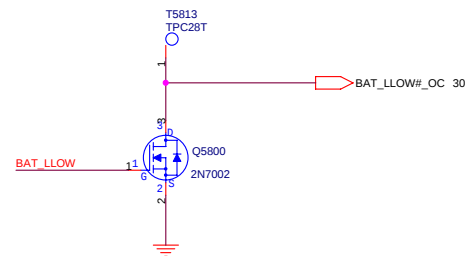
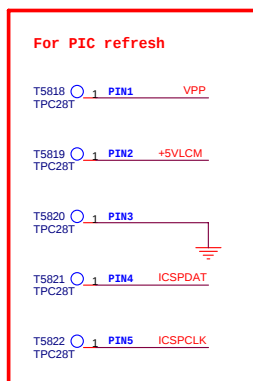
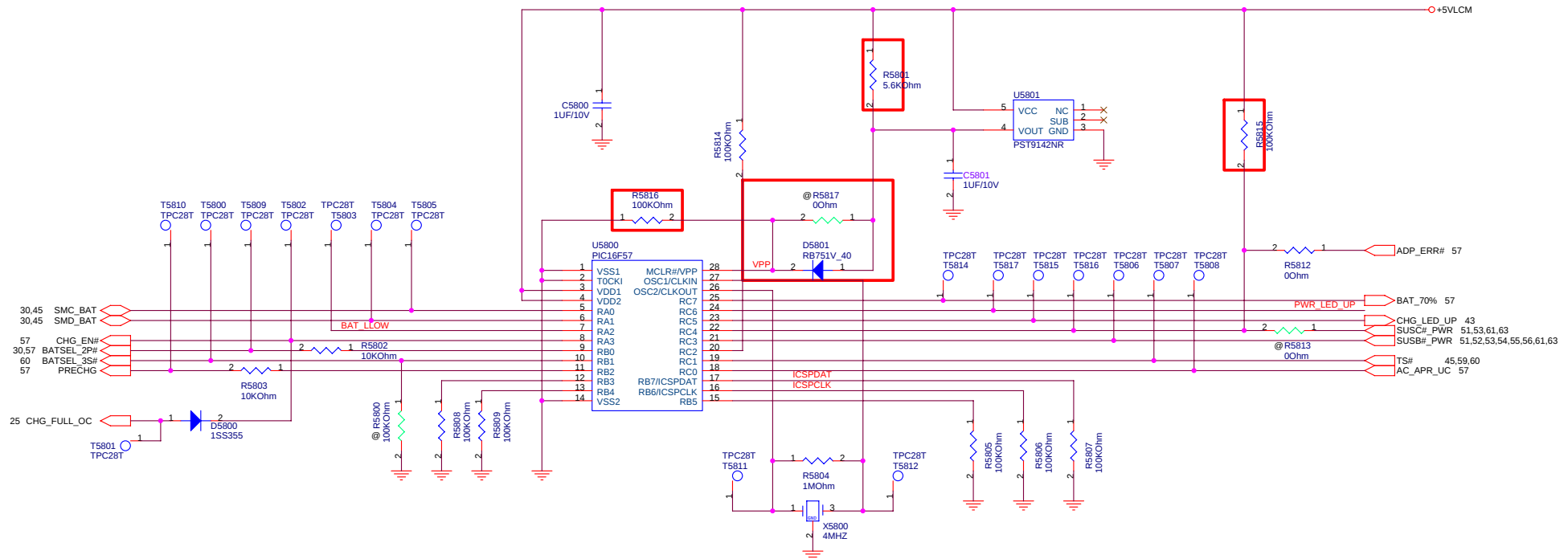
Charge Current I_{chg} =
 $[0.075V/R_{sense}(CHG)] \cdot [V_{CLS}/4.096V]$
 $R_{sense}(CHG) = 0.025 \text{ ohm}$
 $V_{ICTL} = 3.4632V \Rightarrow I_{chg} = 2.53A$

$V_{th} = 17.5V$ (MAX. 17.8V & MIN. 17.2V)

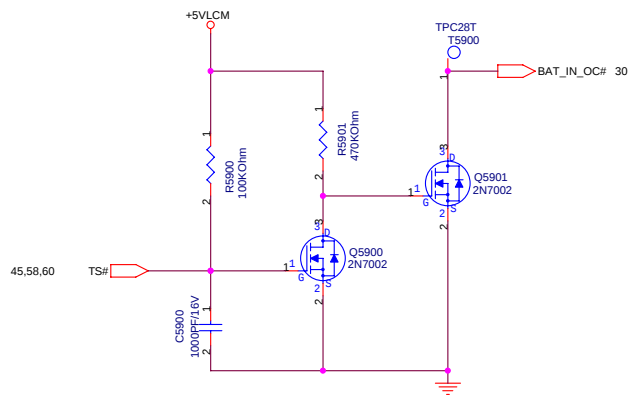
Power Limit Circuit

PRE_CHARGE CIRCUIT
Pre-charge voltage 12.6V

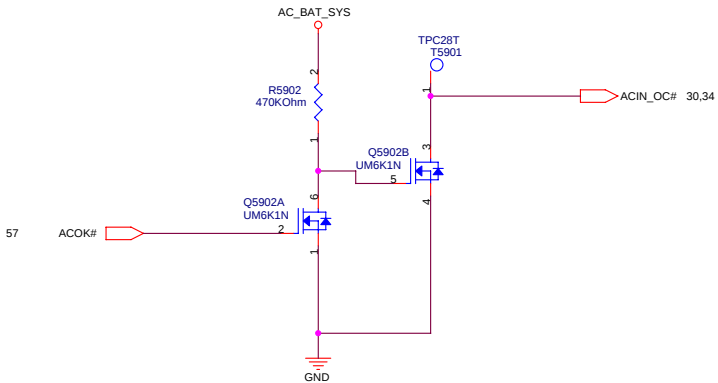
PIC16F57



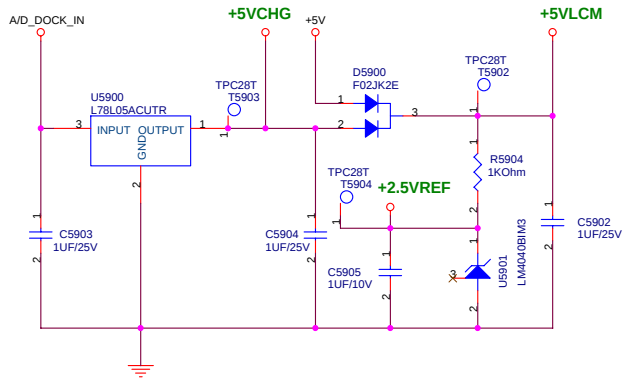
BATTERY IN DETECT



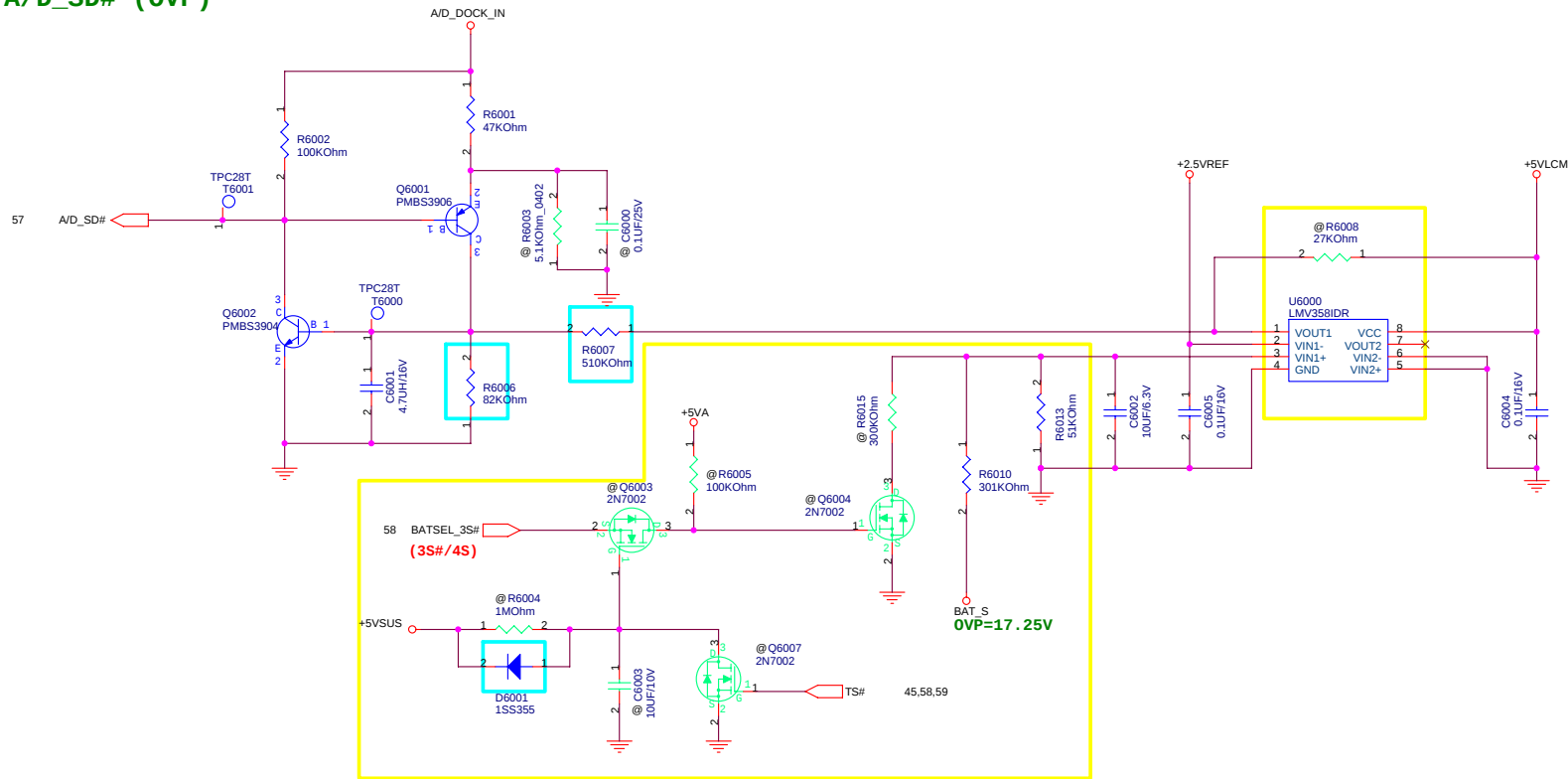
ADAPTER IN DETECT



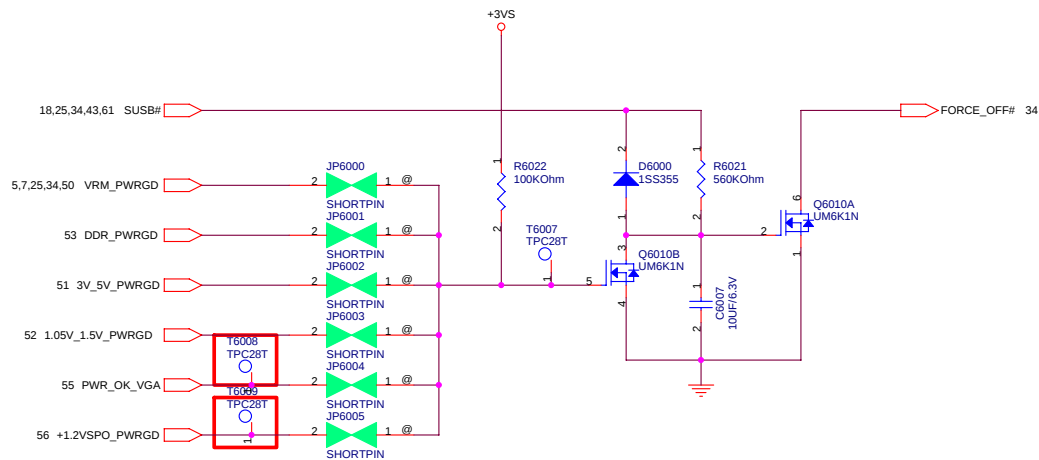
+5VLCM, +5VCHG & +2.5VREF



BATTERY A/D_SD# (OVP)

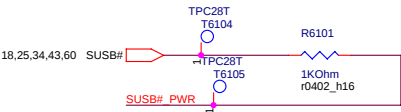
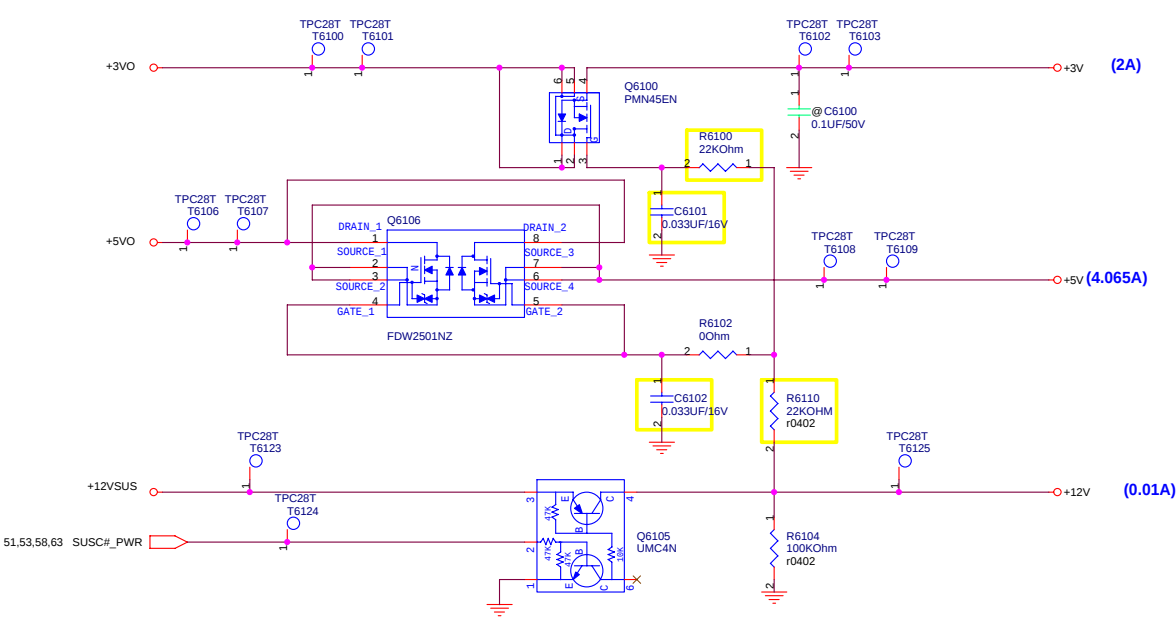


POWER GOOD DETECTOR

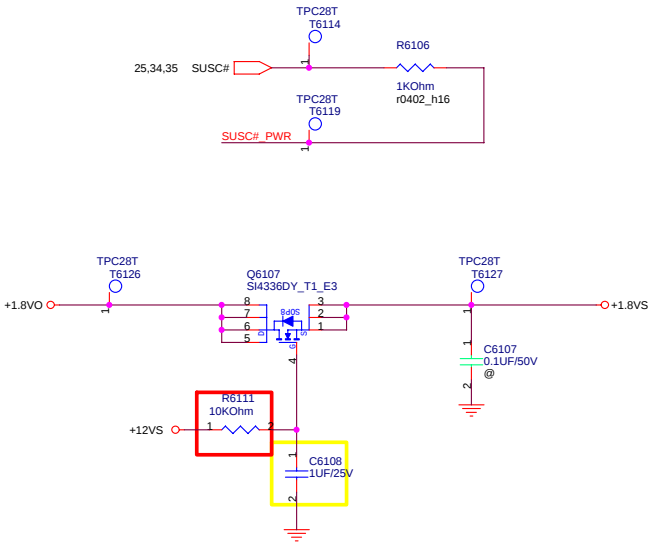
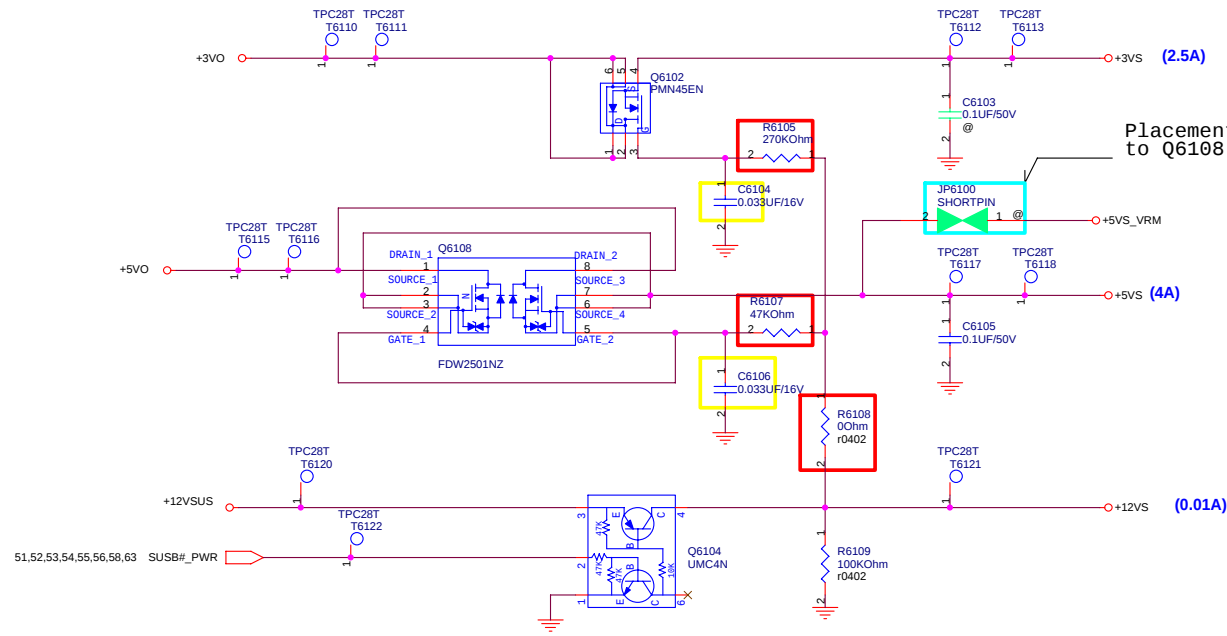


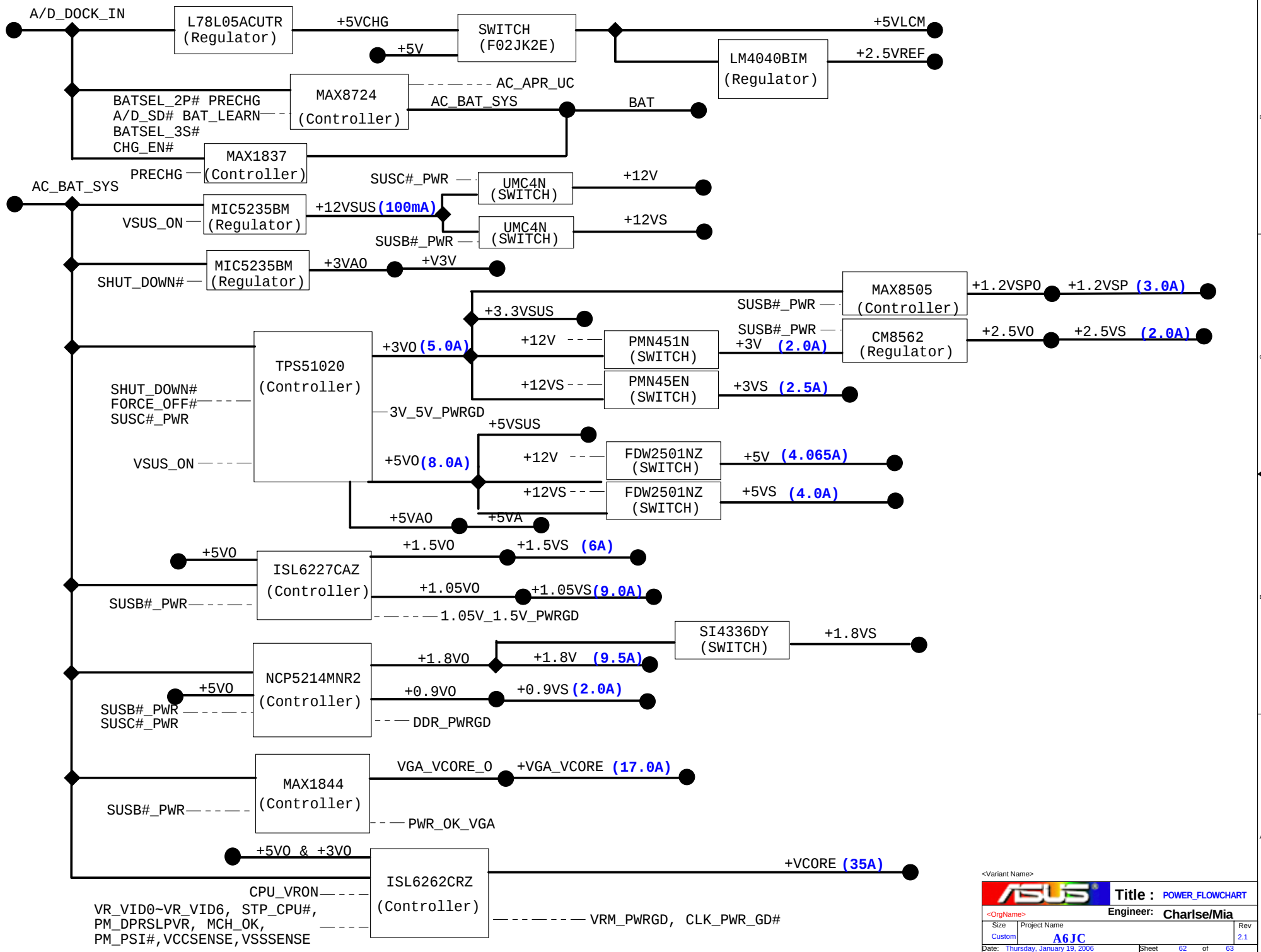
TPC28T	T6002		1	VRM_PWRGD
TPC28T	T6003		1	DDR_PWRGD
TPC28T	T6004		1	3V_5V_PWRGD
TPC28T	T6005		1	1.05V_1.5V_PWRGD

SUSC#_PWR POWER



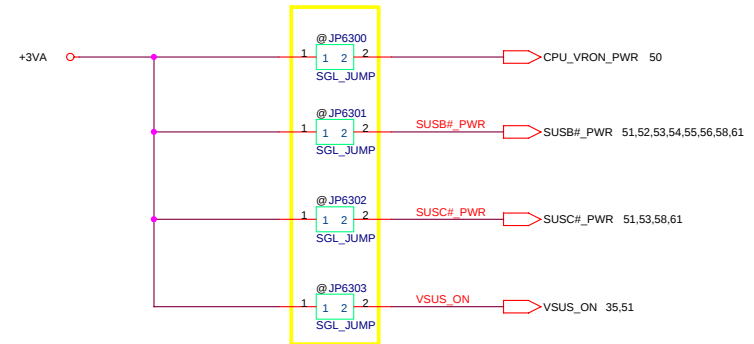
SUSB#_PWR POWER







FOR POWER TEST



<Variant Name>

		Title : POWER_SIGNAL	
<OrgName>		Engineer: Charlse/Mia	
Size	Project Name	Rev	
Custom	A6JC	2.1	
Date: Thursday, January 19, 2006	Sheet	63	of 63